

TV Service Manual



Note: (Product rendering pictures are only for reference, please subject to actual product)

Product Model: 100MLED800/78(100I1U-FISDB)

Main Board: RTD2885-T11E1&MP651TT-6MX1

File Version: V202506.01.Q0

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1. Safety Precautions

In order to ensure the normal use of this product and prevent accidents such as electric shock or fire, please read and understand all use requirements and operating procedures before using or repairing this product. Strictly comply with the following requirements (including but not limited to):

- Do not expose this product to rain, humidity and direct sunlight, and pay attention to avoid excessive humidity and dust, so as to avoid circuit corrosion and failure;
- Do not place this product near heat sources, such as heaters and radiation sources, to keep good ventilation and heat dissipation;
- Do not use corrosive liquid to wipe this product to prevent any liquid from entering the machine;
- Do not forcibly plug and unplug each connecting port, and ensure that the wire and the corresponding port are correctly and firmly connected;
- Please unplug the power supply when it is not used for a long time;
- Do not disassemble this product without permission. If the product fails and needs to be repaired, the professional maintenance personnel must carry out the maintenance operation on the premise of fully understanding the product information and relevant maintenance guidance documents;
- Maintenance and assembly need to be carried out under the condition of power failure;
- Pay attention to electrostatic protection during maintenance and assembly to avoid ESD electrostatic damage to products;
- During maintenance and assembly, ensure convection and heat dissipation of surrounding air, and prevent short circuit caused by live conductors contacting components.

2. Product information

1.Panel spec	
Size	100" diagonal
Backlight	DLED direct Type
Maximum resolution	3840×2160
LCM Center Luminance of White	Min:500nit ;Typ :600nit APL20%: Min:900nit ;Typ :1000nit
Contrast ratio (Typ)	100000 :1
Response time(Typ)	8ms
Display scale	16:9
Viewing angle(CR>10)	Typ (H :178 °,V :178 °)
Display Colors	1.07G
Color Gamut(NTSC)	≥85%
Local dimming	800zones default, 1600zones optional
Uniformity of Luminance	≥75%
2.Hardware Information	
ATV	PAL M/N; NTSC M
DTV	ISDB
CPU Frame	ARM Cortex-A75x2+ A55x2/1.2GHz/Quad core
GPU	IMG BXE-4-32
RAM(DDR)	2GB
ROM(Flash)	16GB
Audio power(Output)	SPK1 (8W+8W) ;SPK2(8W+8W) ;SPK3(20W)
WIFI(Type)	2T2R
Tuner type	screw-thread
USB 2.0	2
USB 3.0	1
VGA	-
AV In	-

YPbPr In	-
CI	-
PC Audio	-
RJ-45	1
Earphone	-
Audio In	-
Audio Out	1
Video Out	-
SPDIF Out	1 (optical)
Bluetooth(Version)	5.0
HDMI	2
Others	-
3.Software Function	
Channel list	YES
Channel edit	YES
Picture freezing	NO
MTS/NICAM	YES
Sleep time setting	YES
Teletext	YES
PVR	YES
V_CHIP/Parental Guidance	YES
CC(Closed caption)	NO
AD(Audio description)	YES
CI+	NO
DOLBY	YES
HDMI-ARC	HDMI-3
HDMI-CEC	YES
HDMI-MHL	NO
Operation system	Android 11
OTA	YES

Hotel mode	NO
EPG	YES
TTS(Text to Speech)	NO
4.Structure Information	
Base model name	BCH4-100 Triangle Fixed Base
Size (without stand) L×W × H	2232*69*1274mm
Size (with stand) L×W × H	TBD
Size (carton) L×W × H	2385*243*1482mm
Net Weight (without stand)	70.2kg
Net Weight (with stand)	72kg
Gross Weight (without stand)	88.2kg
Gross Weight (with stand)	90kg
Size (Wall hanging)	800×500mm
5.Power Management&Safety&Certificate	
Power input	100-240VAc
Fire rating	UL94-HB/HB75
Standby power	≤0.5W
Rated power	De
Working condition	Temperature: 5°C~40°C humidity: 20%~80% atmosphere: 86KPa~106KPa
Storage condition	Temperature: -20°C~55°C humidity: 20%~80% atmosphere: 86kPa~106kPa
6.Accessory	
Stand(Optional)	1PCS
Remote control	1PCS
Instruction	1PCS
Warranty card(Optional)	1PCS
Battery(Optional)	2PCS

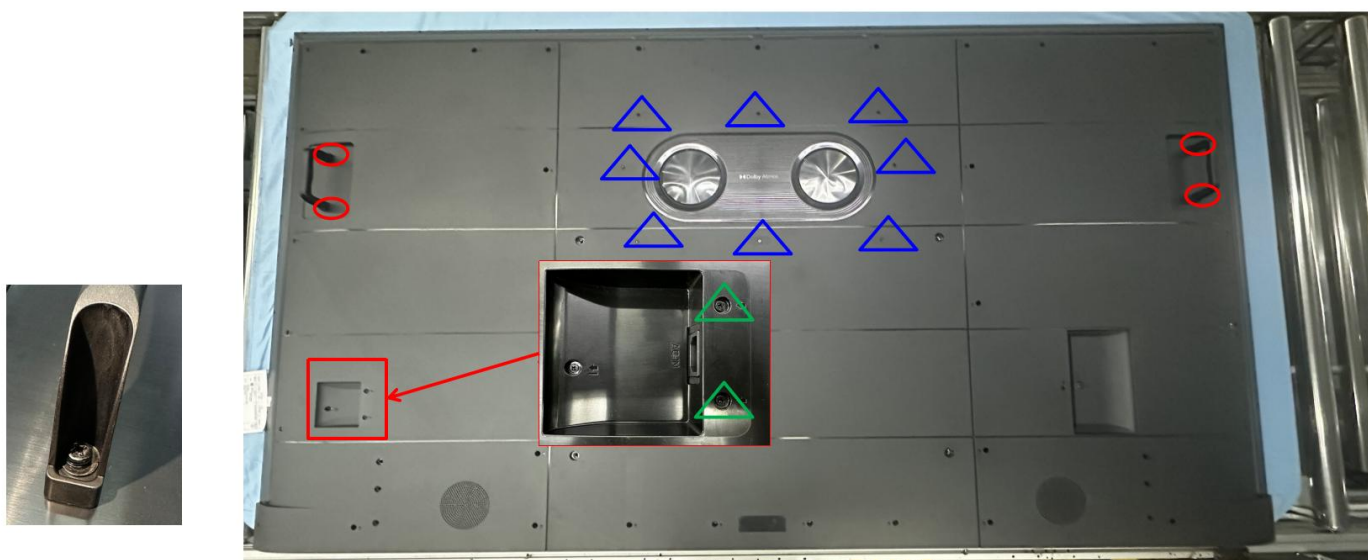
3. Whole machine disassembly

3.1 Remove screws from back cover-1

1. Use electric screwdriver to remove 2pcs ST3×13mm tapping screws; (Figure : )
2. Use electric screwdriver to remove 8pcs M3×7mm screws; (Figure : )
3. Use electric screwdriver to unscrew 4pcs M5×20mm screws, then remove 2pcs handles; (Figure : )

Notes: 1. Please wear ESD wrist strap during operation;

2. Please read carefully and fully understand the content of SOP before operation;

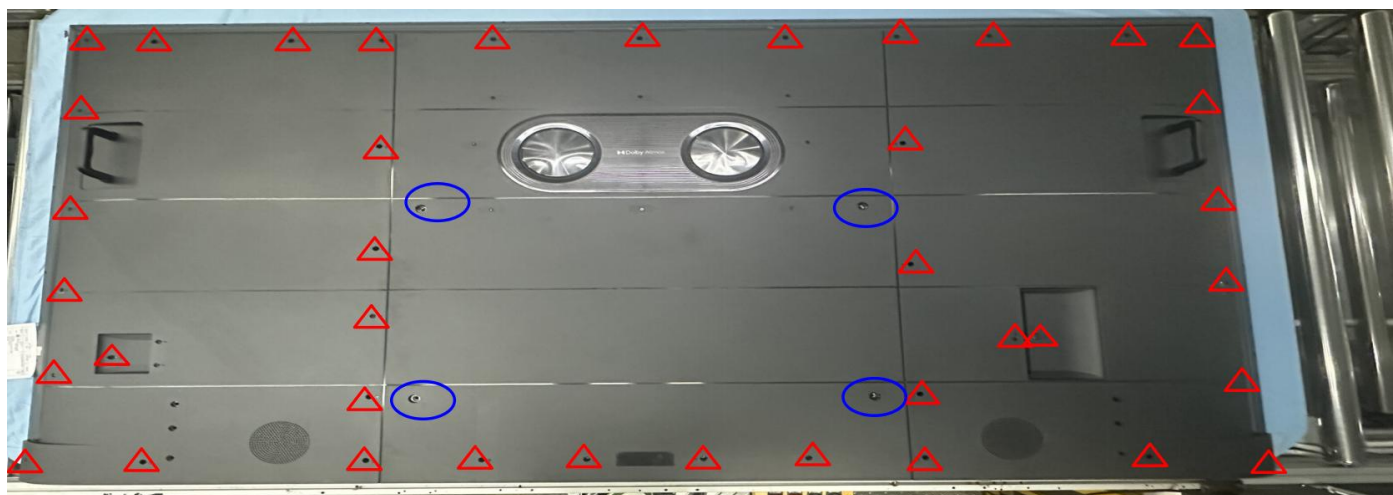


3.2 Remove screws from back cover-2

- 1.Remove 39pcsM3×7mm screws from back cover-L/M/R in turn;(Figure : )
- 2.Unfasten back cover-L/R from upper side, make them separate from tabs, then remove back cover-L/R in turn;
- 3.Unfasten from the upper side, lift the plastic back cover-M, then pull it out;(Figure : )

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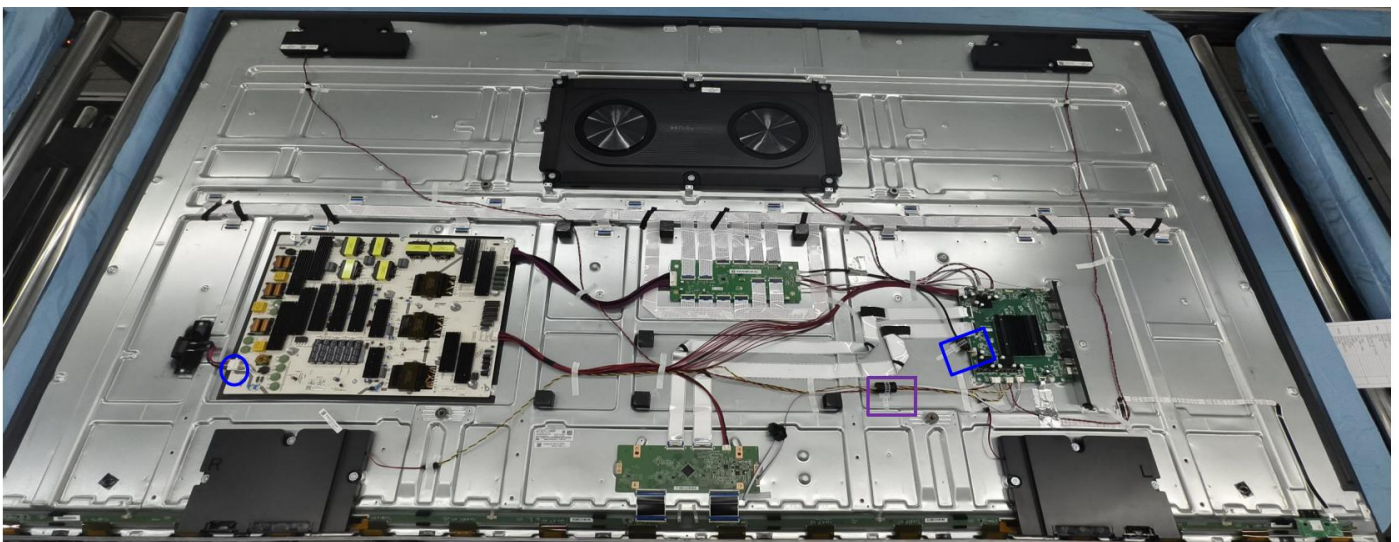


3.3 Remove EMI cores

1.As the blue/purple boxes shown in the figure, unfasten line buckles first, then open the EMI cores and remove them;

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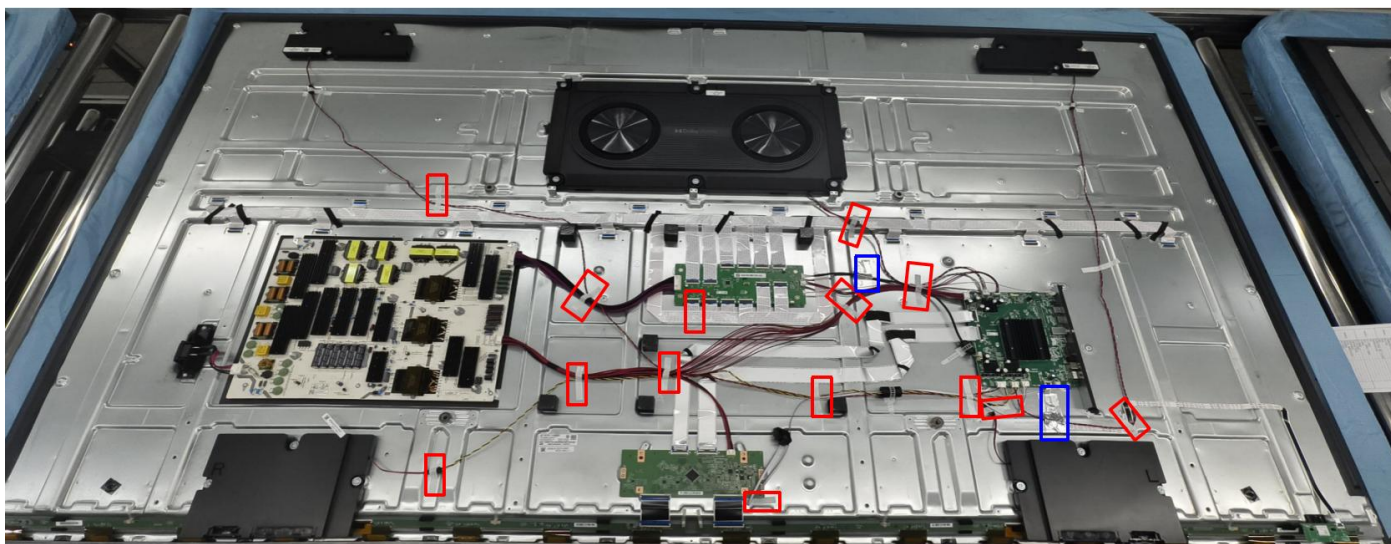


3.4 Arrange wires

- 1.As shown in the figure, remove all tapes which are pasted on wires, then put them in designated position
- 2.Unplug the wires of power board, main board, drive board, wifi board, speakers and remote control receiving window from corresponding connectors, then classify them and put them neatly

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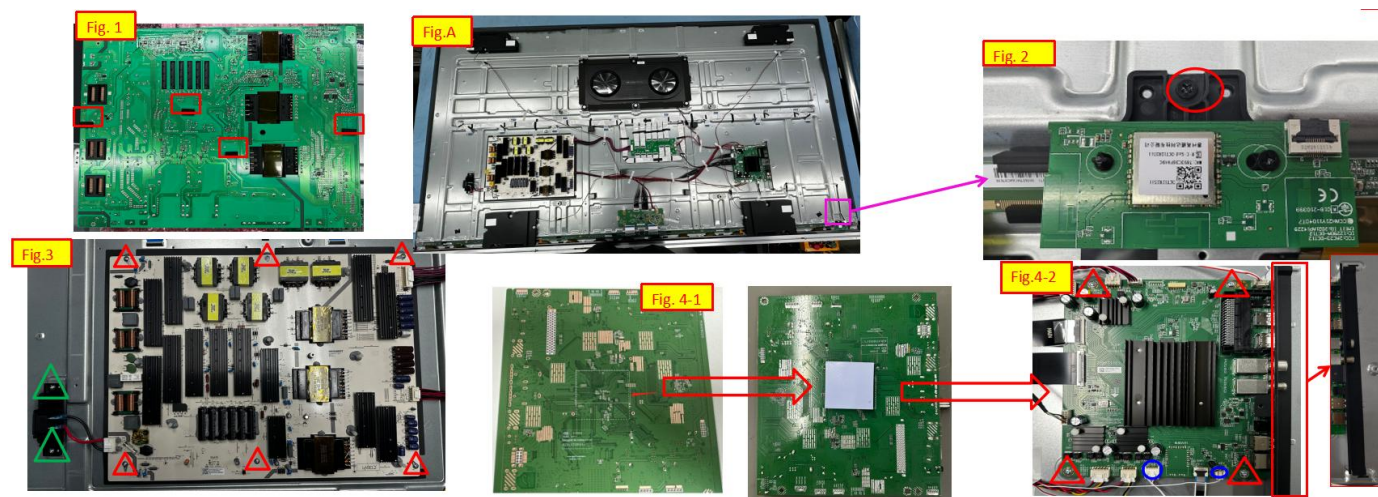


3.5 Remove power board, AC switch, main board/WiFi assembly

1. Use electric screwdriver to unscrew 1pcs $M3 \times 7.0\text{mm}$ screw, then remove the WIFI assembly; (Fig.2)
2. Remove 1pcs IO baffle-R; (Fig.4-2)
3. Use electric screwdriver to unscrew 6pcs $M3 \times L5.5\text{mm}$ screws, then remove the power board; (Fig.A, 3: )
4. Use electric screwdriver to unscrew 4pcs $M3 \times L5.5\text{mm}$ screws, then remove the AC switch assembly; (Fig.A, 3: )
5. Use electric screwdriver to unscrew 4pcs $M3 \times L5.5\text{mm}$ screws, then remove main board; (Fig.A, 4-2: )
6. Remove 1pcs $45 \times 45 \times 6.5\text{mmT}$ heat dissipation silicone pad from the dotted line box of main board; (Fig.4-1)
7. Remove 4pcs $20 \times 10 \times 4\text{mmT}$ black silicone pads from the blank area on the back of power board; (Fig.A/1)

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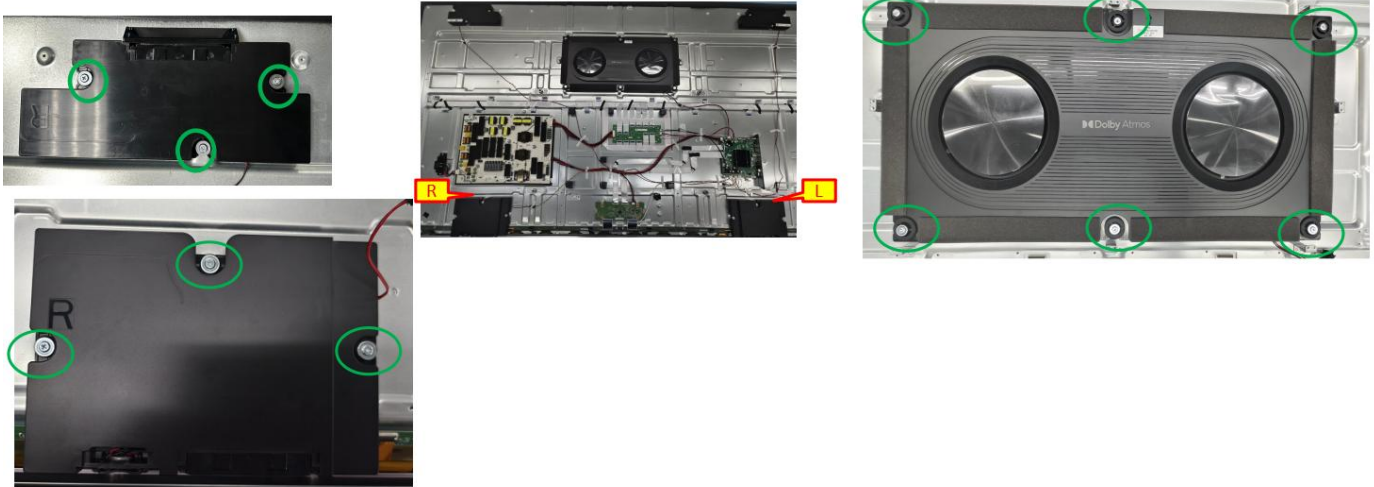


3.6 Remove speakers

1. Use electric screwdriver to unscrew 6pcs M3×6.5mm screws, then remove the subwoofer;
2. Use electric screwdriver to unscrew 12pcs M3×6.5mm screws, then remove 4 speakers;

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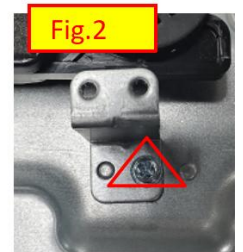


3.7 Remove back cover fixing brackets

1. Use electric screwdriver to unscrew 8pcs M3×6mm screws, then remove back cover fixing brackets;

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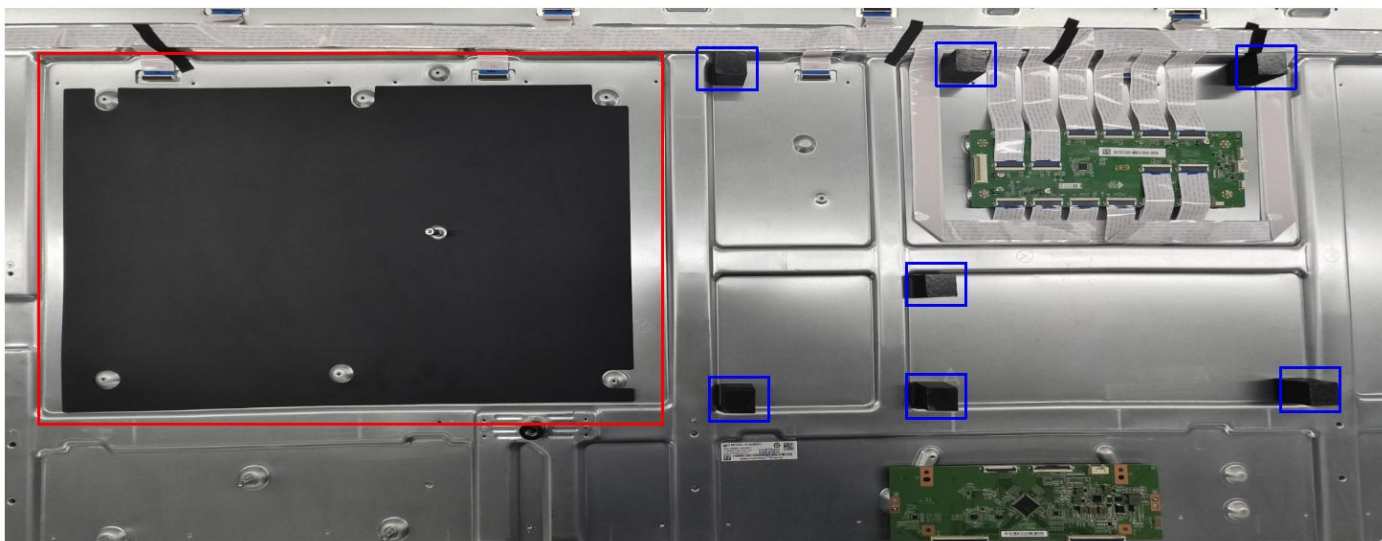


3.8 Remove EVA pads/mylar

- 1.Remove 7pcs $25 \times 25 \times 29\text{mmT}$ black EVA pads from back plate;(Fig: )
- 2.Remove 1pcs $460 \times 355 \times 0.43\text{mmT}$ black fireproof mylar from the corresponding position of power board;
(Fig: )

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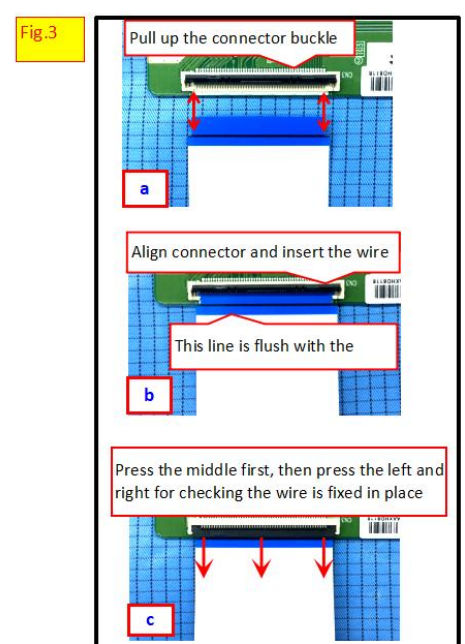
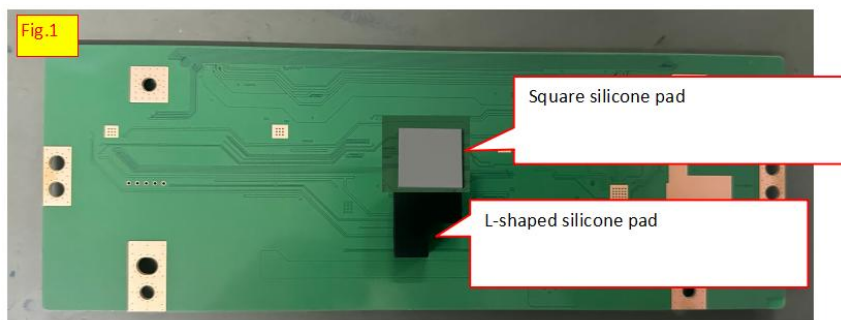
4. LCM disassembly

4.1 Remove T-CON board

1. Unplug the FFC wire which connects OC PCB and T-CON board. (Fig.2, 3)
2. Use electric screwdriver to unscrew 2PCS M3×3mm screws, then remove the T-CON board;
(Fig.2: )
3. Remove 1pcs 20×20×8mm square silicone pad from T-CON board; (Fig.1)
4. Remove 1pcs 20×20×7mm black L-shaped silicone pad from T-CON board; (Fig.1)

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2. Please read carefully and fully understand the content of SOP before operation;

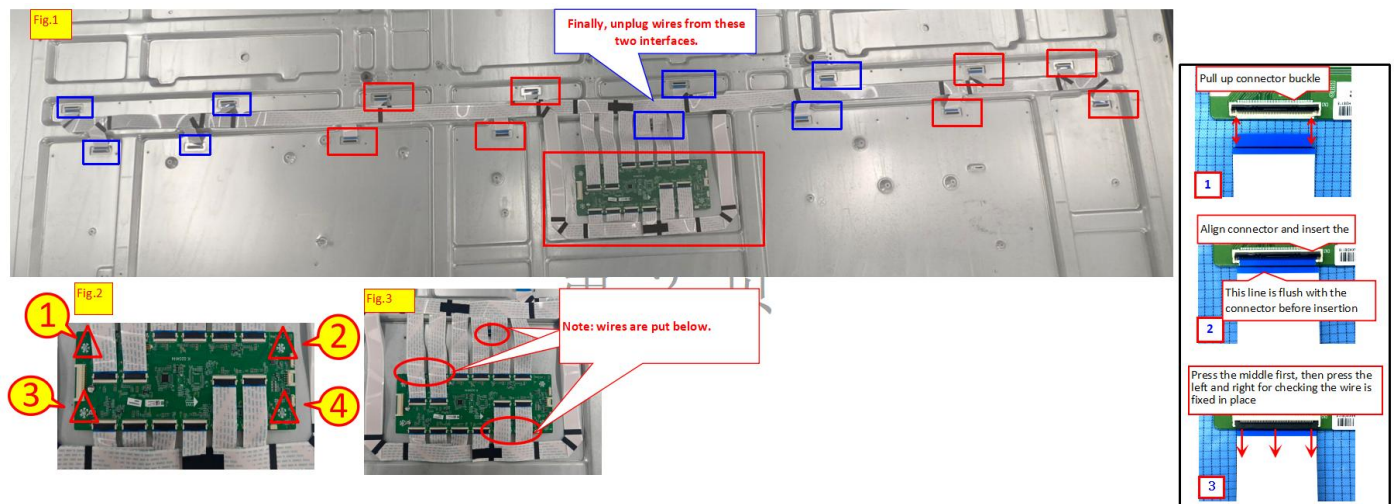


4.2 Remove T-CON board

- 1.Remove all wire terminals that connect drive board and T-CON board, then unplug the wires;
- 2.Use electric screwdriver to unscrew 4pcs M3×3mm screws, then remove the drive board;

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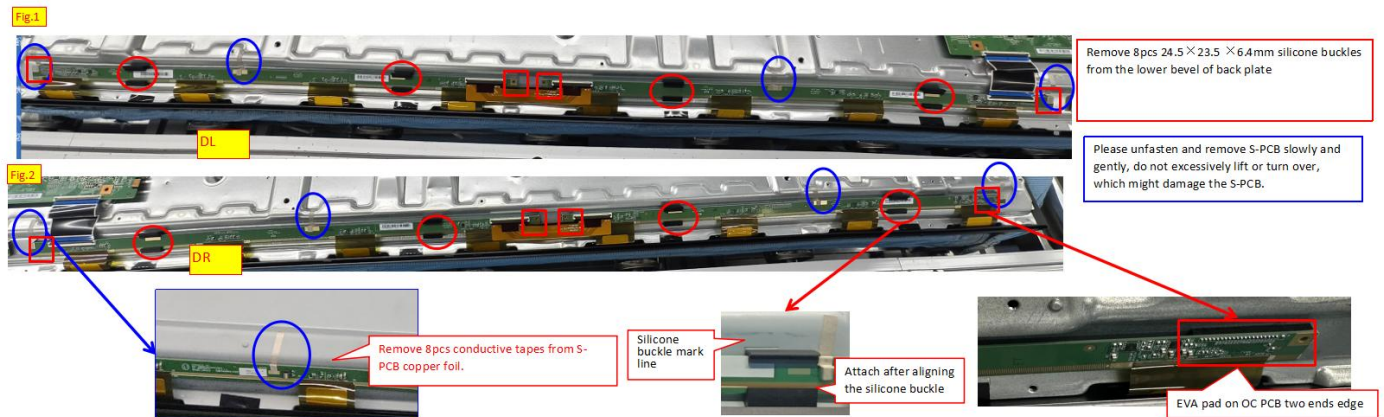


4.3 Remove conductive tapes+silicone buckles

- 1.Remove 8pcs conductive tapes from S-PCB copper foil.
- 2.Slowly remove the pcb from silicone buckles, please pay special attention not to damage COF during operation.
- 3.Remove 8pcs $20 \times 8 \times 3\text{mm}$ black EVA pads from two ends of each PCB of OC;
- 4.Remove 8pcs $24.5 \times 23.5 \times 6.4\text{mm}$ silicone buckles from the lower bevel of back plate

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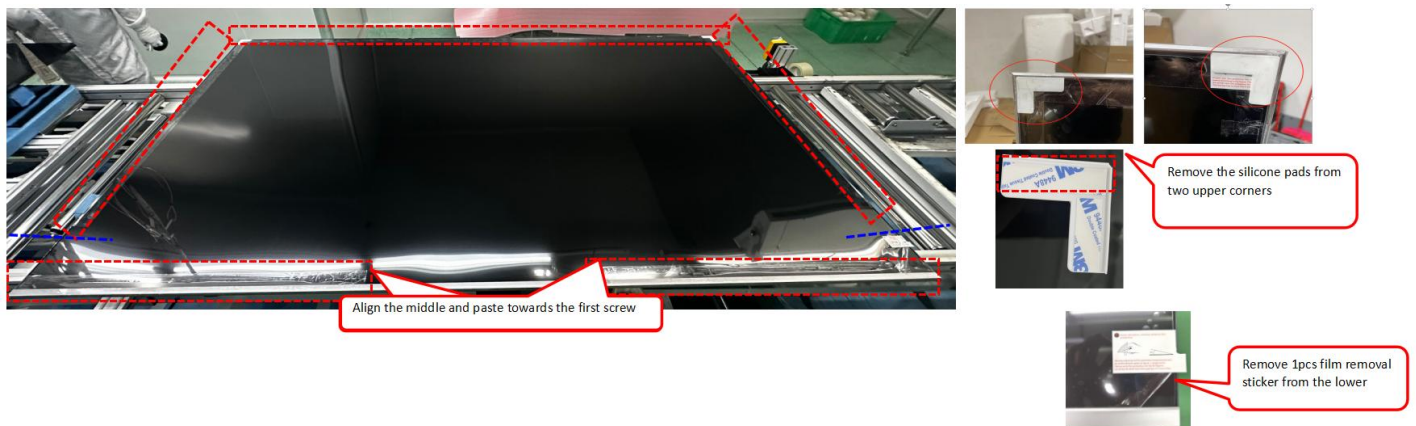


4.4 Remove film removal sticker + protective tapes

1. Two or four operators work together, both hands respectively grasp the middle of bezel-L/R (do not pinch the screen), then turn over the LCM (OC faces upward), put the LCM on tooling plate with tooling rods; note: respectively put 1pcs tooling rod on L/R and middle U side under the back plate; when turning over, do not twist the machine, lest OC is damaged;
2. Tear off the protective tapes from four edges of OC;
3. Remove 2pcs $50 \times 50 \times 3.4\text{mmT}$ white silicone pads which are pasted at the upper left/right corner of OC;
4. Remove 1pcs film removal sticker from the lower right corner;

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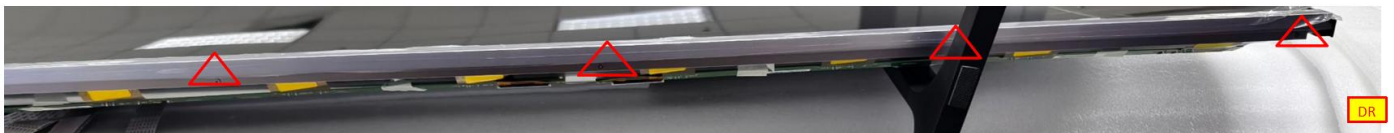


4.5 Remove decoration strip

1. Use electric screwdriver to unscrew 9pcs $M2.5 \times 4\text{mm}$ screws, then remove the decoration strip;
2. Remove the decoration strip.

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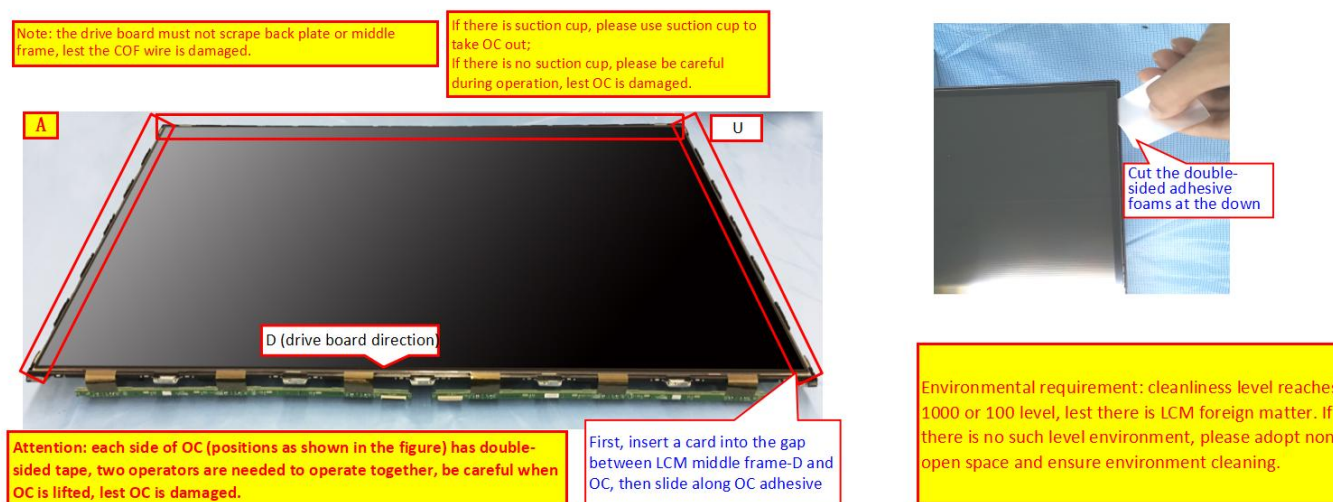


4.6 Remove OC

1. Bend S-PCB towards OC lest drive board is hung on middle frame when OC is lifted, and the COF wire is damaged.
2. Use suction cup to attach OC, note: double-sided tapes are used to fix OC, as shown in the figure; ensure double-sided tapes are separated from OC before OC is lifted; (one operator removes double-sided tapes from OC -L/R while the other operator lifts OC, these two operators work together)
3. Use suction cup to lift OC and put it on a clean workbench (note: the workbench where OC is put shall be free of any object or dust);

Notes: 1. Please wear ESD wrist strap during operation;

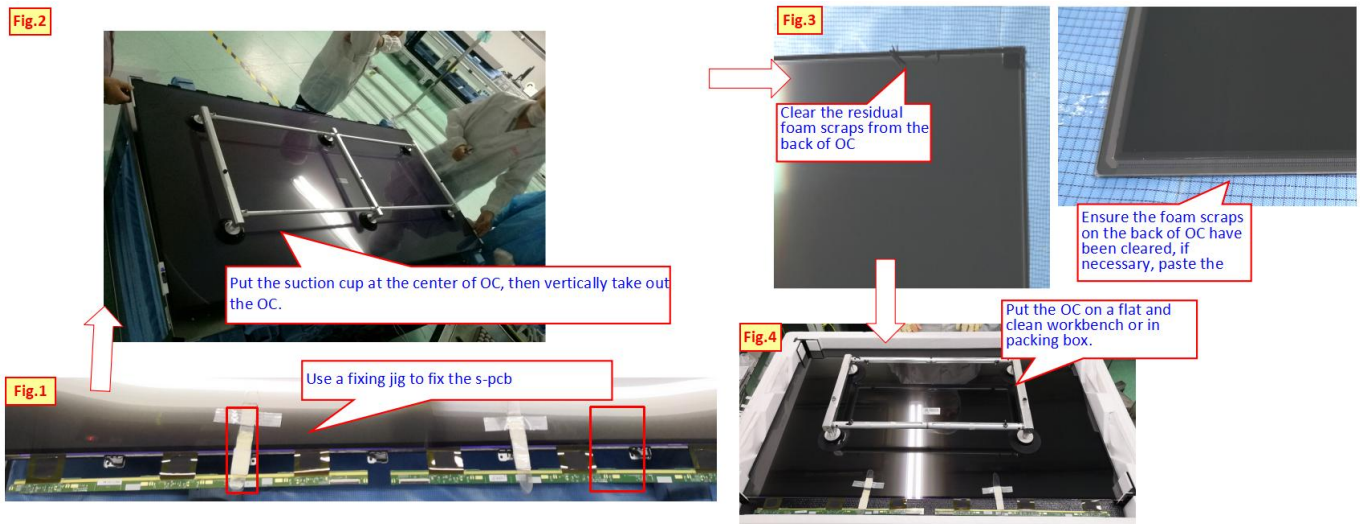
2. Please read carefully and fully understand the content of SOP before operation;



4.7 Remove OC-B

1. Inspect the foams of OC -D have been all separated at previous station;
2. Ensure OC is no longer attached to middle frame;
3. Inspect S-PCB is fixed in horizontal position by an S-PCB fixing tool;
4. Attach OC firmly, then vertically move OC out from the LCM; (Note: clear the residual foams from the back of OC;)
5. Put the cleared OC in a packing box, then remove the S-PCB fixing tool and suction cup.

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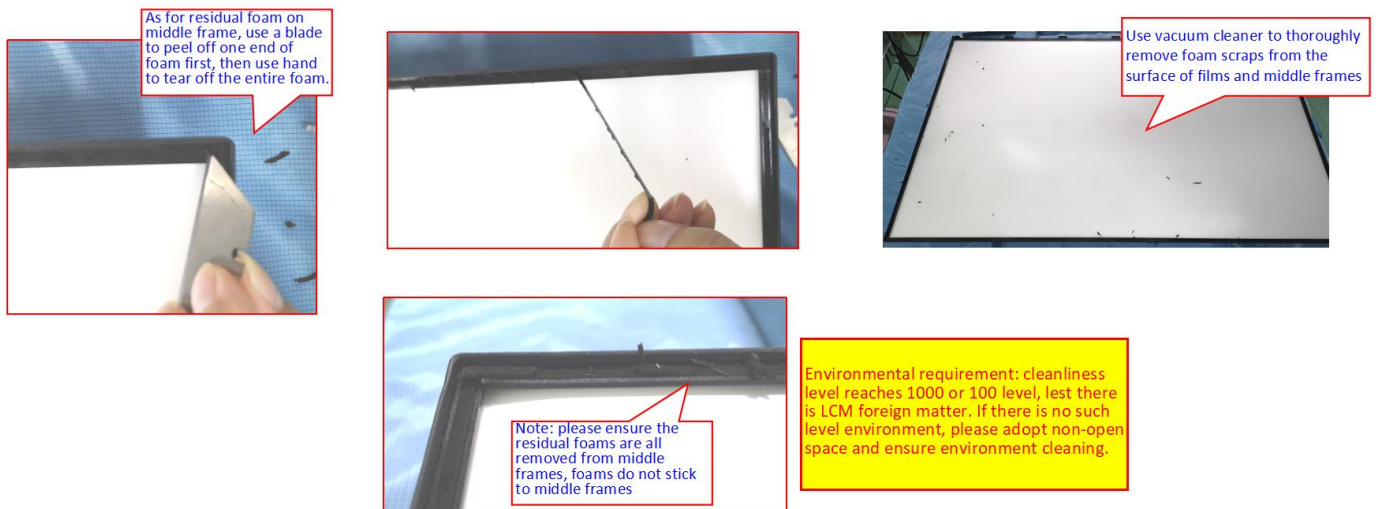


4.8 Remove metal middle frames

1. Use electric screwdriver to unscrew 21pcs M2.5×4mm screws from the back (U: 9+ L:6+ R:6), then remove the metal middle frame;
2. Remove metal middle frames in sequence: middle frame-U, middle frame-L, middle frame-R;

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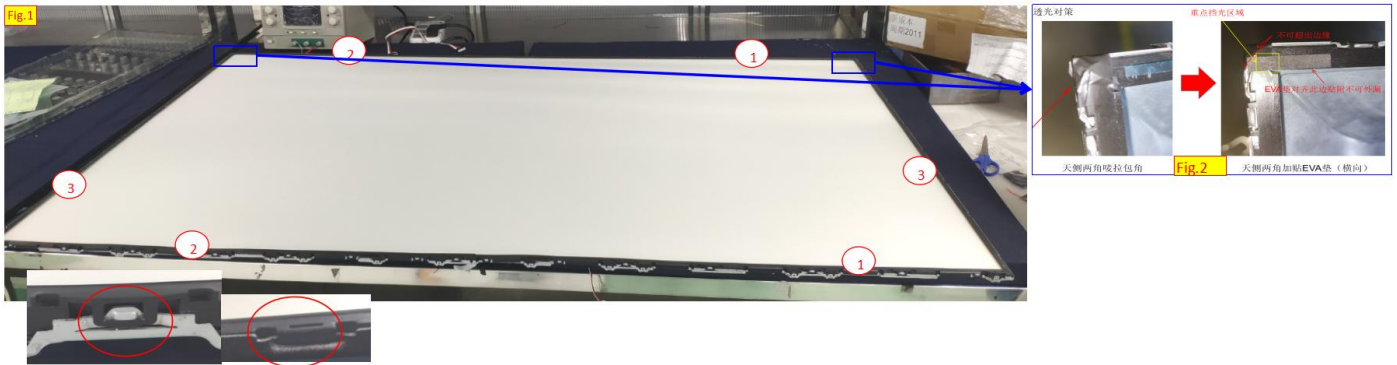


4.9 Remove plastic middle frames

- 1.Remove 2pcs $30 \times 6 \times 0.5\text{mmT}$ black EVA pads from joints between middle frame-U and middle frame-L/R;
- 2.Remove 2pcs $20 \times 12 \times 0.05\text{mmT}$ black mylars from joints between middle frame-U and middle frame-L/R;
- 3.The sequence to remove middle frames is as shown in the figure, please remove middle frame-L/R first, then middle frame-UL/DL, finally middle frame-UR/DR

Notes: 1.Please wear ESD wrist strap during operation;

2.Please read carefully and fully understand the content of SOP before operation;

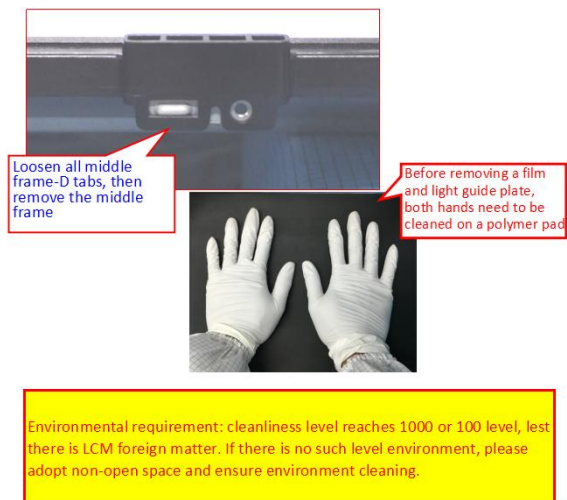
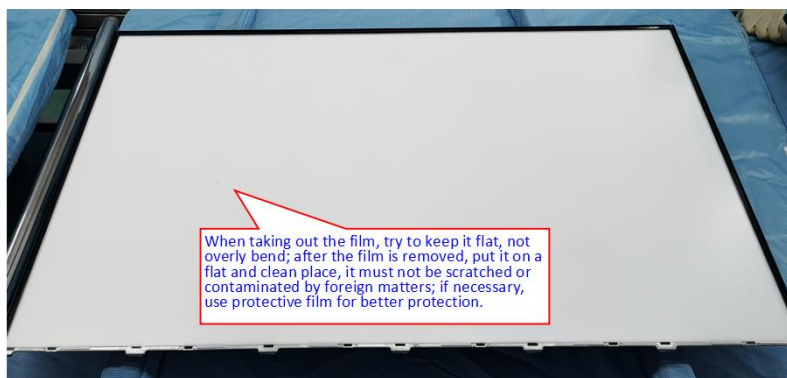


4.10 Remove films and diffusion plate

1. After middle frames are removed, two operators work together to take out the films; note: grasp the middle of film -L/R, it is forbidden to fold the film or the film shall not scrape the back plate, lest there is damage; put the films on clean workbench.
2. After films are removed, two operators lift the diffusion plate and put it on the anti-static PE bag (clean and without foreign matters) on the workbench;
3. Inspect there is no omission;

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2. Please read carefully and fully understand the content of SOP before operation;

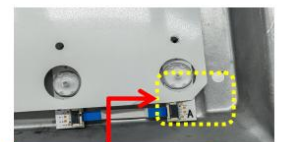
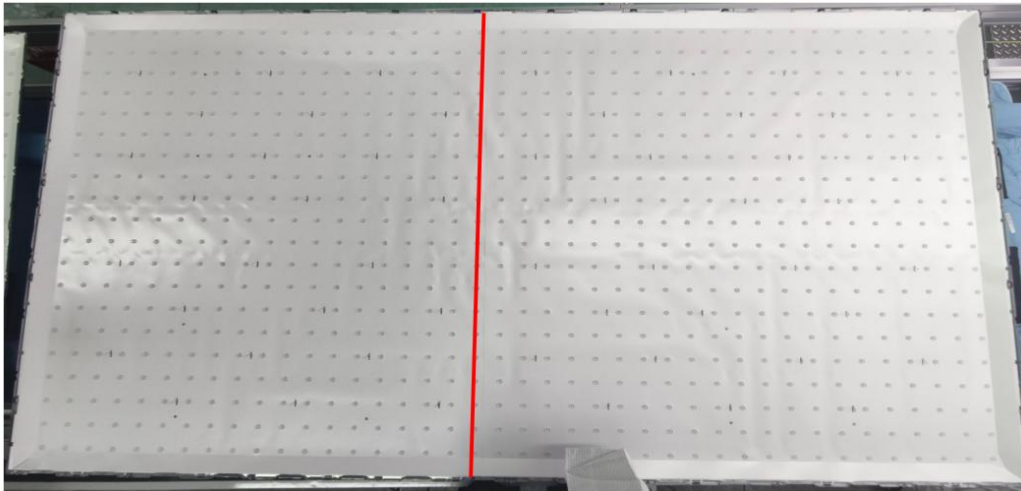


4.11 Remove reflective film

1.Pull the reflective film from four edges, then slowly pull up the reflective film

Notes:1.Please wear ESD wrist strap during operation;

2.Please read carefully and fully understand the content of SOP before operation;



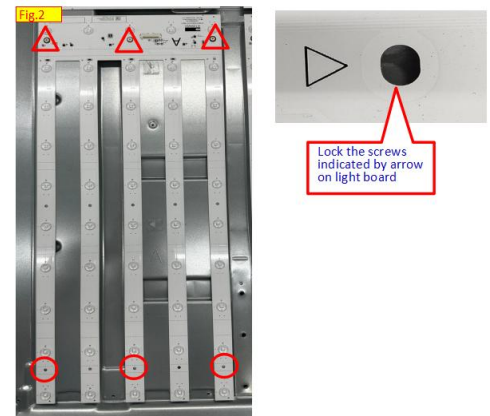
Note! The chamfer of reflective film is at the

4.12 Remove light board

1. Use electric screwdriver to unscrew 48pcs M3×2mm screws, then remove 16pcs light boards;

Notes: 1. Please wear ESD wrist strap during operation;

2. Please read carefully and fully understand the content of SOP before operation;

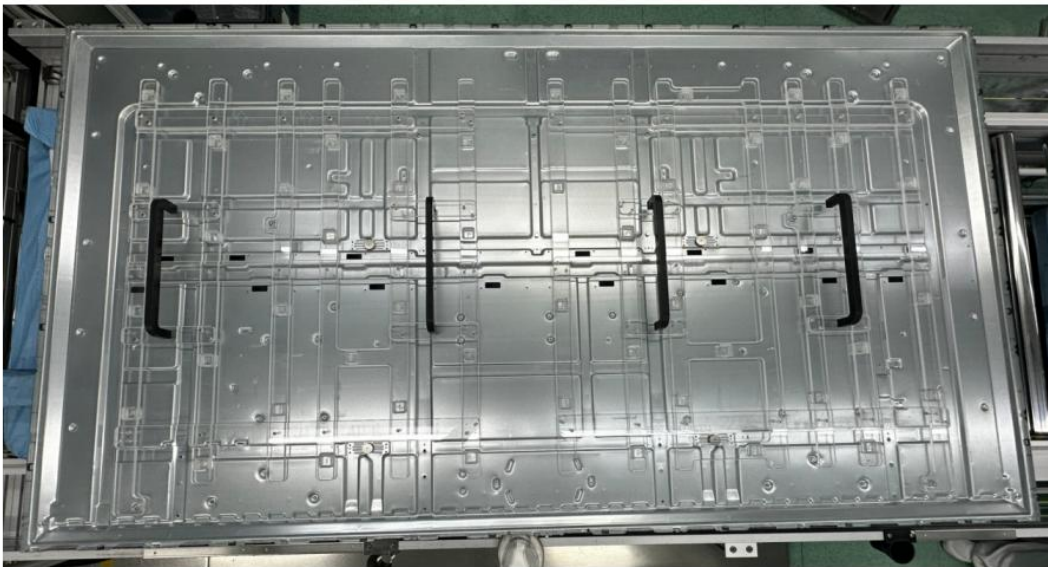


4.13 Remove diffusion plate brackets

1.Remove 52pcs diffusion plate brackets; can also use a knife to slowly pry

Notes: 1.Please wear ESD wrist strap during operation;

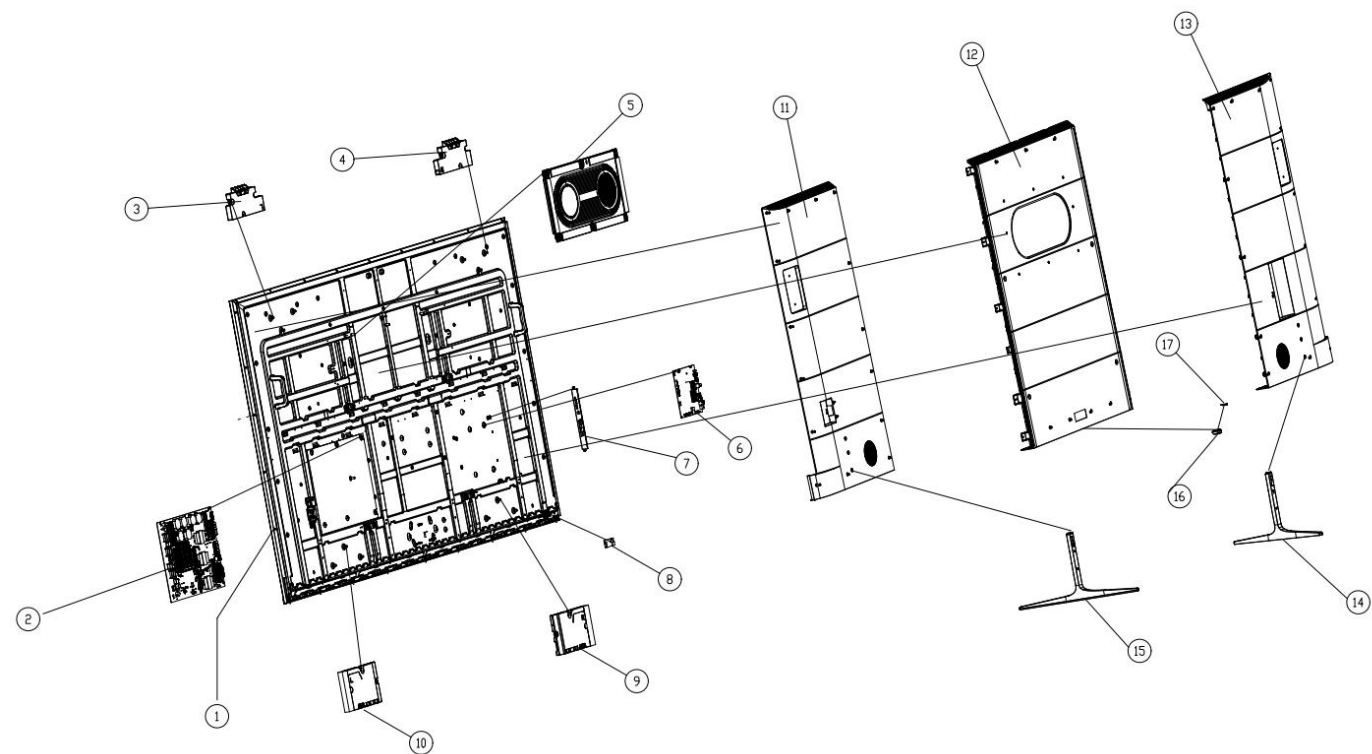
2.Please read carefully and fully understand the content of SOP before operation;



Bracket direction: U/D
Bending direction: towards left

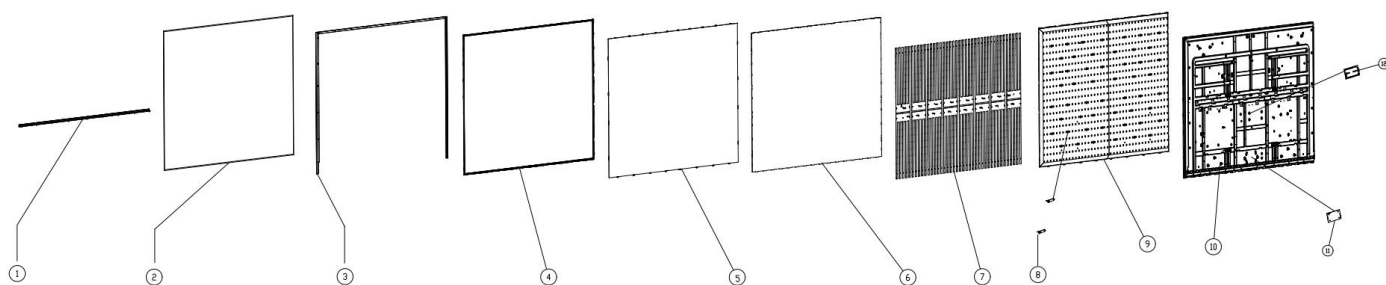
5. Explosion diagram

5.1 Whole machine diagram



17	1066	Remote control receiving board	1
16	45	Remote control receive	1
15	50R	Base-R	1
14	50L	Base-L	1
13	40L	Backcover - L	1
12	40M	Backcover - M	1
11	40R	Backcover - R	1
10	1185	Speaker-R	1
9	1187	Speaker-L	1
8	WiFi02	WIFI	1
7	1053ST	Side baffle	1
6	1053	Mainboard	1
5	1186	Speaker	1
4	1187	Speaker-L	1
3	1185	Speaker-R	1
2	1054	Power board	1
1	1050	Module	1
Detail for whole structure			
NO	Tag number	NAME	QTY

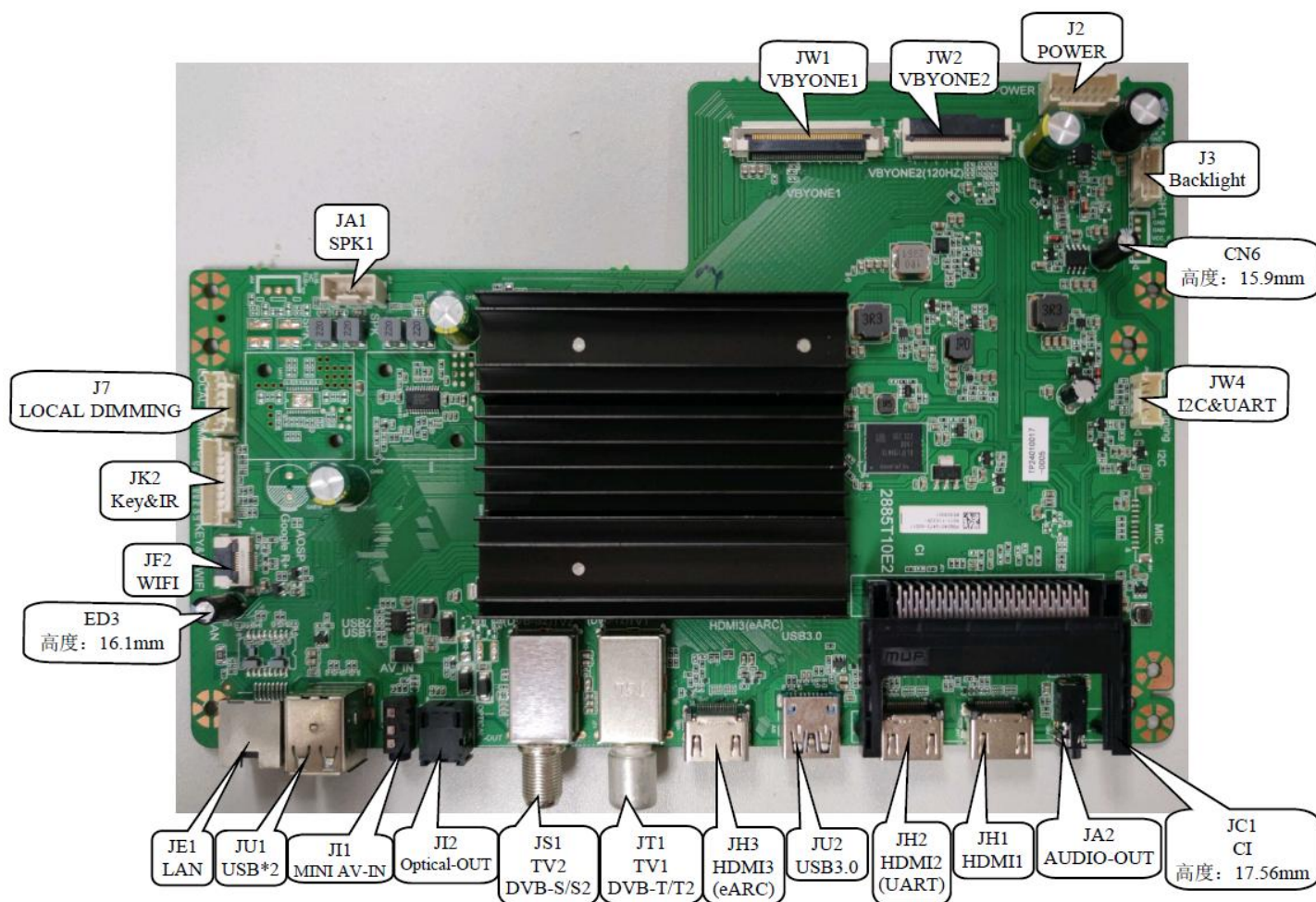
5.2 LCM diagram



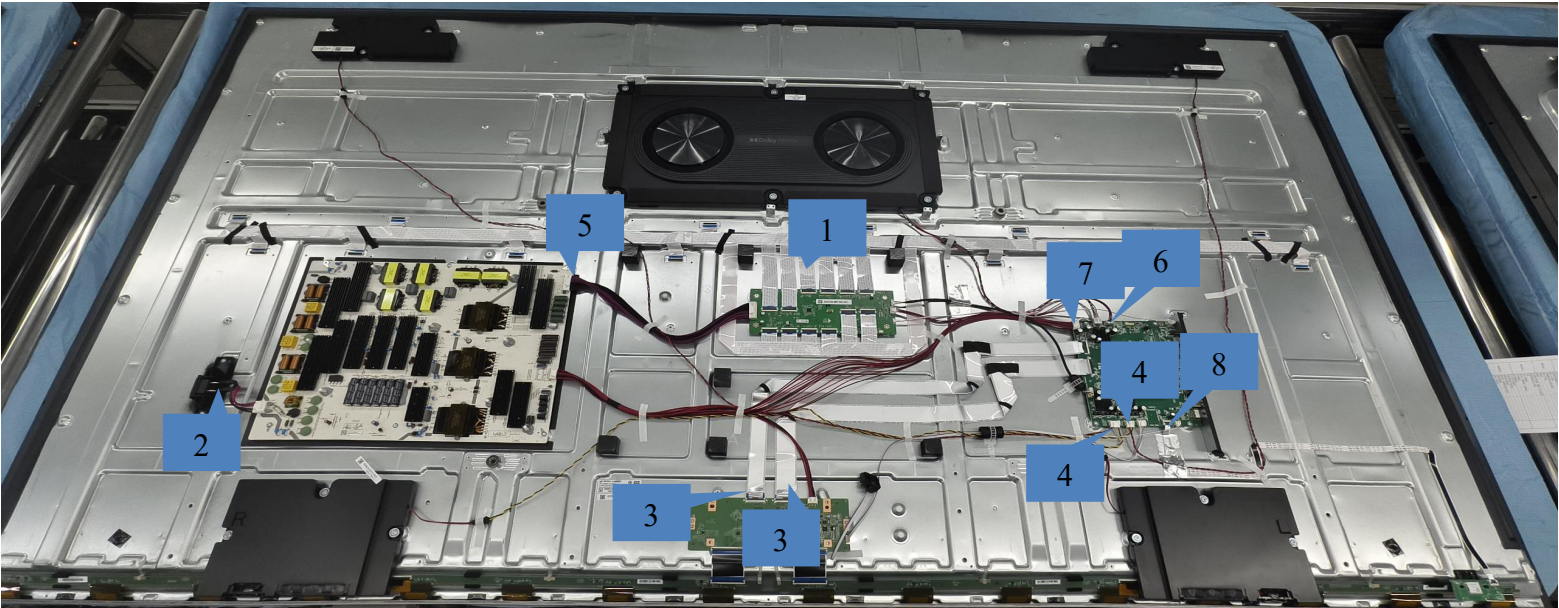
12	1055	Driver board	1
11	1050TCON	T-con	1
10	1050BC	Back plate	1
9	1050RF	Reflector plate	1
8	others	Supporting bracket	52
7	1050BAR	Light Bar	1
6	1050DP	Diffuser	1
5	10501F	Film	1
4	30M	Pastic cement module middle frame- UL/UR/DL/DR/L/R	1
3	30M	Metal module middle frame -U/L/R	1
2	1050OC	Glassborad	1
1	30D	Surface frame decoration	1
Detail for Module			
NO	Tag number	NAME	QTY

6. Connections Overview

6.1 Main board interface



6.2 Cable dressing



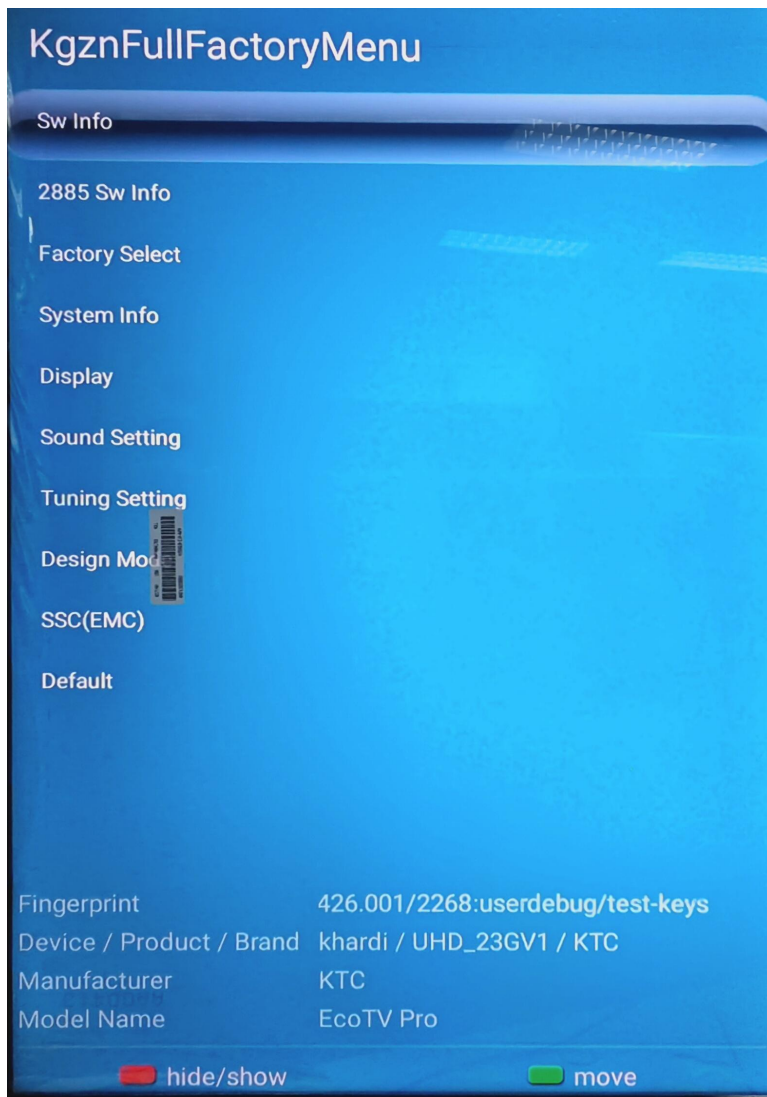
NO	Location	part description
1	1050BARC	Backlight line
2	E-POW	power line
3	KW19	FFC line
4	KW14	Speaker line
5	KW21	Power board to Diver cable
6	KW21	Motherboard to Diver cable
7	KW21	Motherboard to Power board cable
8	KW20	Motherboard to key board cable

7. Software upgrade

7.1 Factory Mode

Press "Source" key + arrow keys "Left/right/left/left" on remote control to enter factory menu, press ← to exit factory menu

Main menu	Value, notes
Sw Info	Software Information
2885 Sw Info	2885 Software Information
Factory Select	Factory Selection
Systm Info	System Information
Display	Display Information
Sound Setting	Sound Setting
Tuning Setting	Tuning Setting
Design Mode	Design Mode
SSC(EMC)	Data Debugging
Default	Default Option
Fingerprint	
Device/Product/Brand	Device/Product/Brand
Manufacturer	Manufacturer
Model Name	Model Name



7.2 Software upgrade

Operation content and steps:

1. Formatting U disk into FAT32 format .
2. Decompress the software package compressed,After checked, copy it in the formatted U disk.

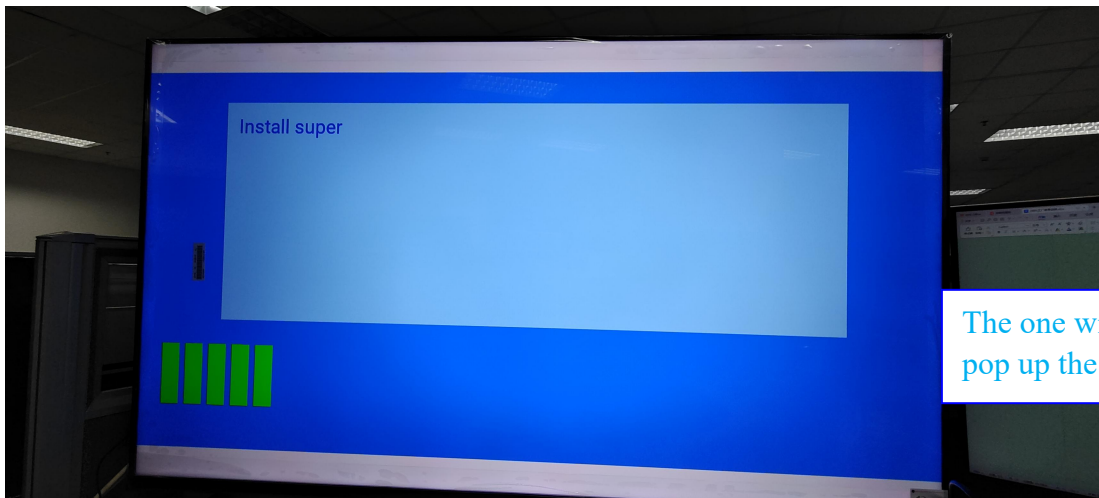
(Software Naming: install.img)

- 3.Insert the U disk into the USB 1 interface of Motherboard.
4. Software upgrade: press the power switch or plug in the power cord to energize the machine, and the LED light of the machine will start flashing for (the upgrade progress bar will appear if there is a display screen). After the upgrade is completed, the LED will Go out (if there is a display screen, the screen will be black).

Notes: 1.File name and capitalized can t be wrong, otherwise unable to upgrade;

2.In the process of upgrading,it is forbidden to operate or cut off power,otherwise,main chip would be damaged

3.This program takes a long time to upgrade and it takes about



8. Circuit Description

8.1 Introduction

- The solution supports DVB-T/T2/C/S/S2 digital TV system, can support CI module, applicable to the digital TV with CI module in Europe or the digital TV without CI module in Europe and Southeast Asia.
- Support Google TV 3.0, support 4K*2K@120Hz display.
- Equipped with a quad-core 1.2GHz CPU+GPU processor; Android 11 version system. Standard built-in 2GB RAM, standard 16GB FLASH.
- Single main board design is adopted, match T10 large board, can match models for use.
- This solution supports network wake-up function and it is set to off by default. When the network wake-up function is enabled, the standby power consumption of the machine does not exceed 1W.
- The machine is tested 10 minutes after the standby action is conducted, the data at this moment is the standard standby power consumption.
- Main board supports Dolby VISION and ATMOS.
- If the main board with MINI AV-IN function is used, one piece of AV adapter cable needs to be added to machine configuration
- The solution supports 120Hz, if it is for 120Hz module, prepare 2pcs panel wires (matching JW1 and JW2 connectors)

8.2 Major Accessories

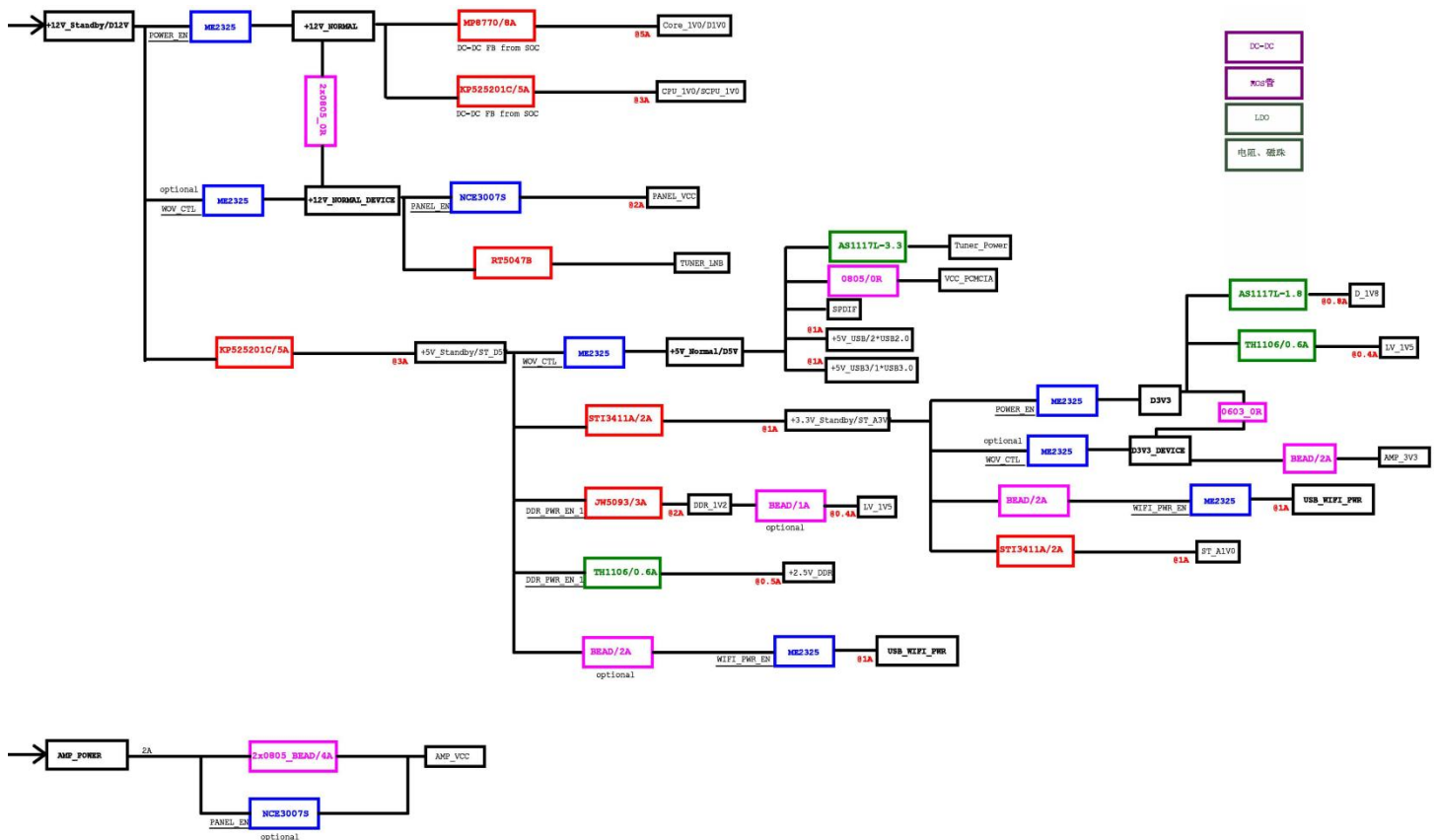
Key components of the main board:

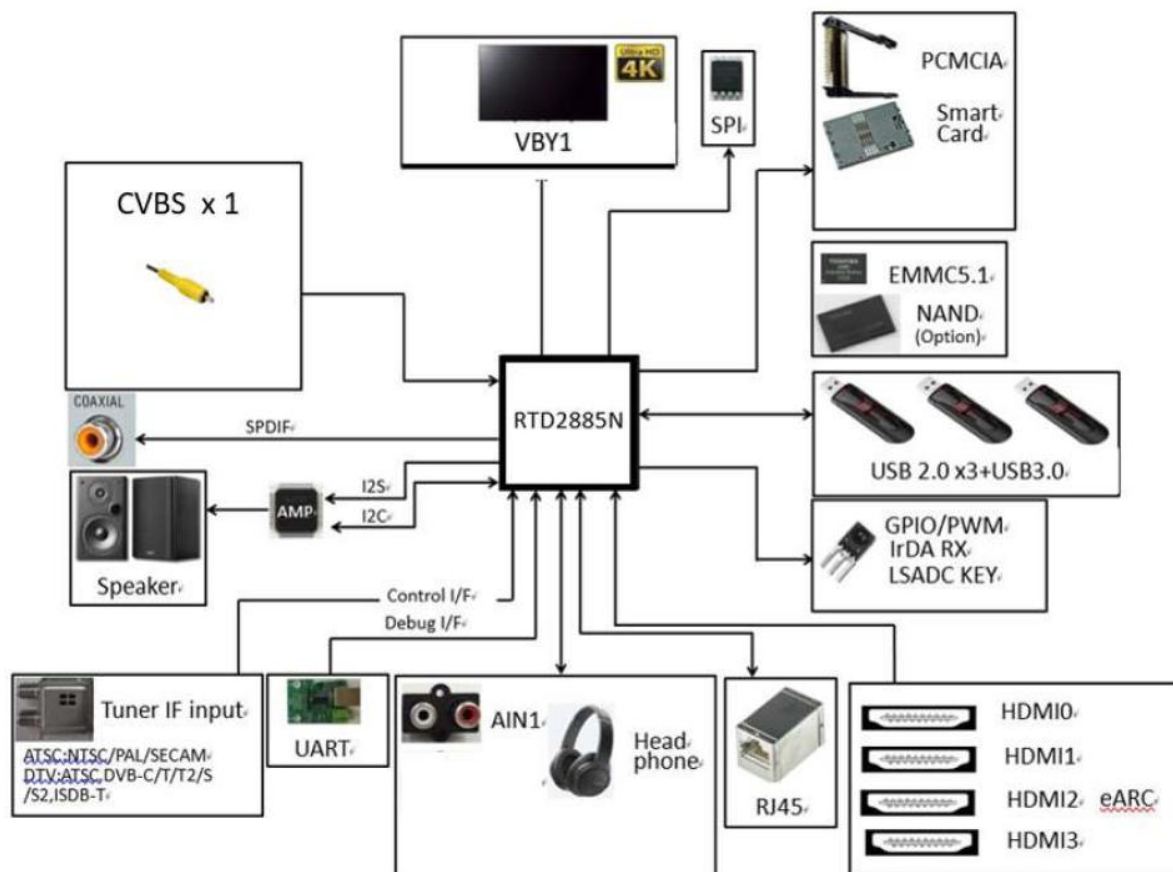
- Main board IC RTD2885NSP-GR HBBTV2.0 2GB (RefDes: U51) ;
- KLMBG2JETD-B041 SAMSUNG FLASH IC eMMC SMT 32GB (RefDes: U8) ;
- Audio amplifier circuit (audio amplifier IC) : audio amplifier IC AD82088-QG24NRR3 (RefDes: UA10);
- DC-DC converter circuit (DC-DC voltage converter IC) :
KP525201CQDGA DC-DC IC (RefDes: UD1 UD5) ; JW5093SOTI DC-DC IC (RefDes: UD2) ;
MP8770GQ DC-DC IC (RefDes: UD4) ; STI3411A DC-DC IC (RefDes: UD7 UD8) ;

- LDO voltage regulator circuit (LDO voltage regulator IC) : AS1117L LDO voltage regulator IC (RefDes: U9 UD10) ;

TH1106-ADJB LDO voltage regulator IC (RefDes: UD12 UW8) ;

8.3 Block Diagram





8.4 Power Supply Device

Important variables of main board:

- New LED backlight power supply architecture
- Backlight adjustment signal adjusts the output of backlight through a PWM signal

Turn-on control signal:

- PS_ON

Backlight control signal:

- BL_ON/OFF

Backlight adjustment signal:

- PWM

In this manual, detailed information is not provided due to design protection.

8.5 Key Voltage Input

- +12V_Standby: 12V DC power supply

1. DC/DC Converter

The DC/DC converter on main board provides voltage below (depends on the settings):

- 5V_Standby: 5V standby supply system constant voltage;
- D1V0、 Core_1V0: CPU peripheral power supply
- CPU_1V0、 SCPU_1V0: CPU peripheral power supply
- 3.3V_Standby: 3.3V standby supply system constant voltage
- 1.0V_Standby: chipset, HDMI power supply

2. LDO Converter

- Tuner_Power: supply power to tuner;
- D1V8: supply power to EMMC;
- LV_1V5: supply power to chipset;
- +2.5V_DDR: supply power to DDR;

3. MOSFET

- +12V_Normal: 12V turn-on voltage;
- +PANEL_VCC: supply power to LCD;
- +5V_Normal: supply power to USB, optical fiber interface, CI;
- AMP_3V3、 AMP_VCC: supply power to amplifier IC;

8.6 Signal Interfaces

1. HDMI interface

Available HDMI connection: maximum resolution: 2160P@120Hz, version: HDMI2.0*2, HDMI2.1*1

- HDMI 1: HDMI input, HDMI2.0 interface
- HDMI 2: HDMI input (support UART) , HDMI2.0 interface
- HDMI 3: HDMI input, HDMI2.1 interface, support FRL protocol and eARC, ALLM, VRR functions (need panel to support)

2. USB interface

- The supply power is not less than 5V, not exceed 500mA if with load, USB3.0 with load does not exceed 900mA
- USB2.0*2 (JU1) , USB3.0*1 (JU2) input
- Support picture, music and video file playing, can use USB to upgrade

3. Support ATV+DTV video source input:

- ATV (video system: PAL, SECAM, sound system: I, D/K, B/G, receiving frequency 46.25-863.25MHz)
- DTV (video system: MPEG-2, sound system: MPEG1 layer 1/2)

4. Tuner

- IEC interface: DVB-T/T2/C
- Thread connector: DVB-S/S2

8.7 Others

1. Speaker/amplifier

Audio input: 0.5Vms, THD+N<10%@1KHz;

Supply voltage: 12V support maximum output 2X8W(8Ω); 18V support maximum output 2X15W(8Ω);
24V support maximum output 2X18W(8Ω);

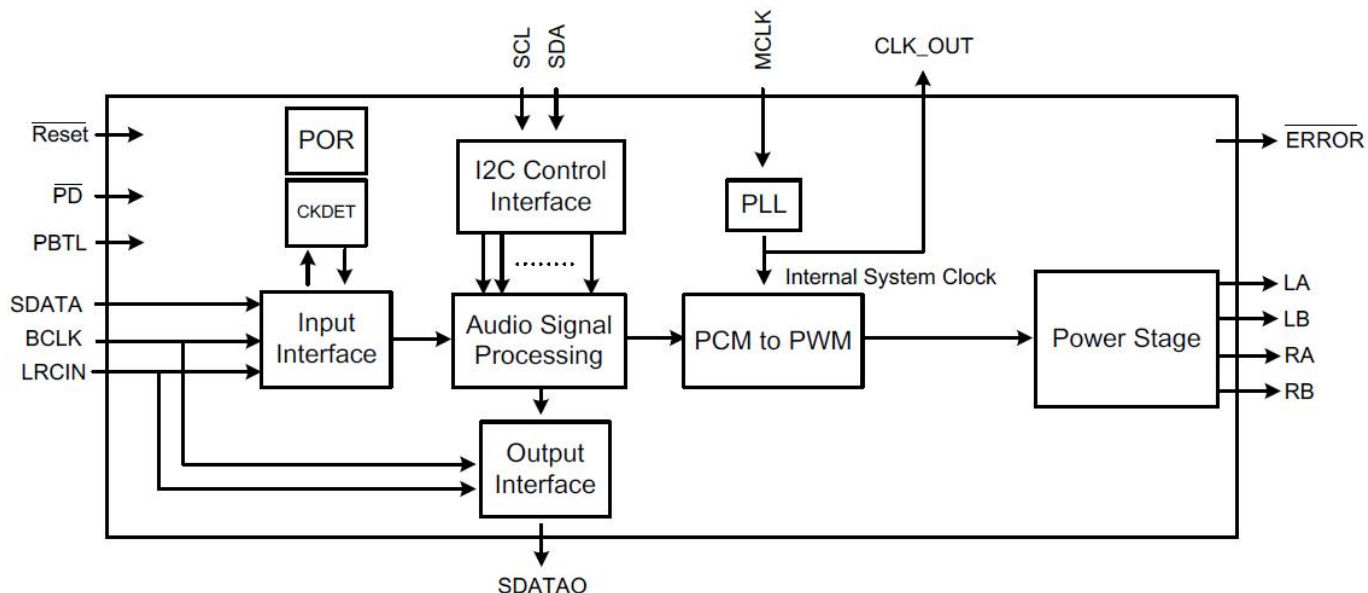
2. Button control: single Power button

3. LED control: LED light is off during normal working, LED light is on in standby state

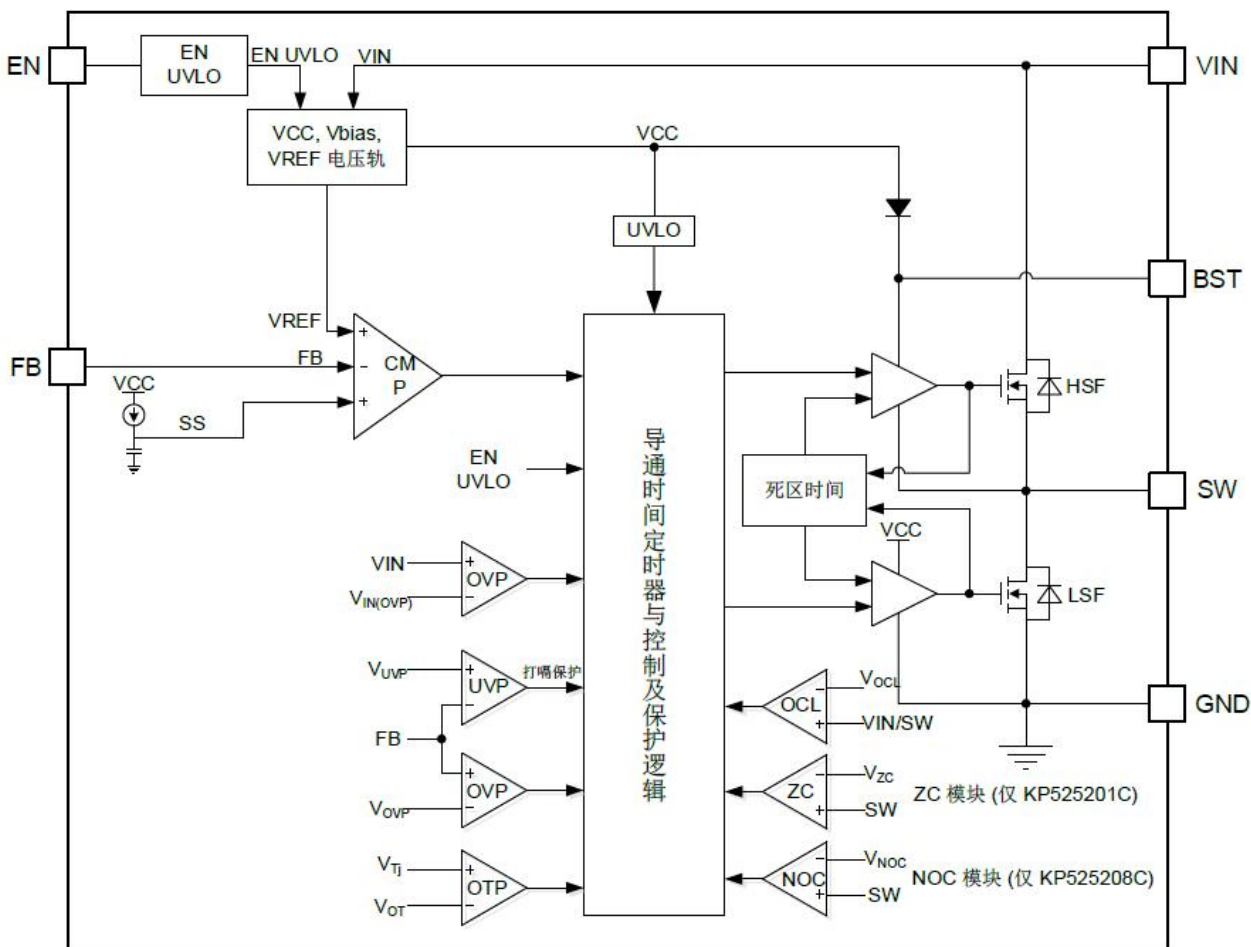
4. HDR: support HDR10

9. IC Data Sheet

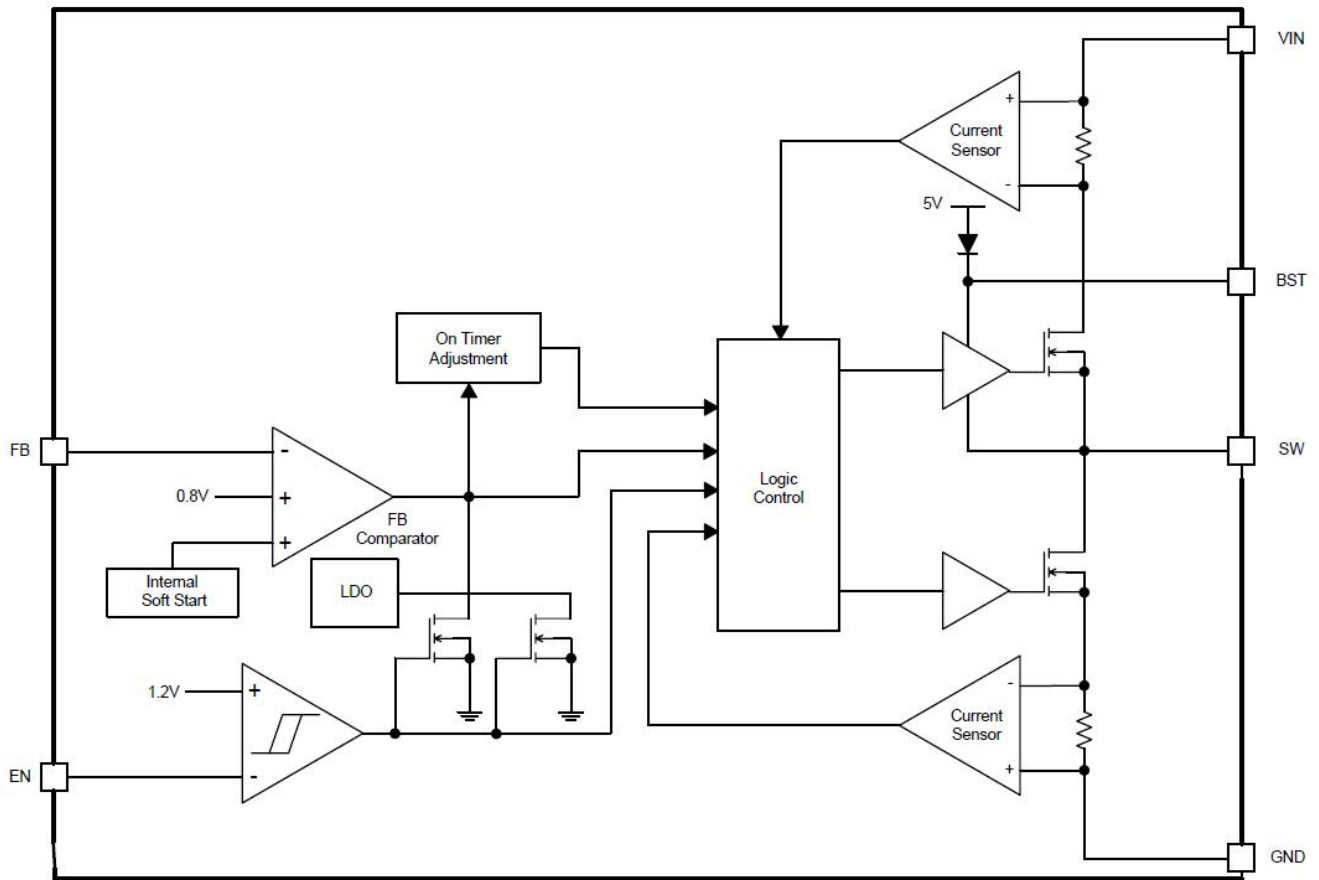
9.1 AD82088 Audio Amplifier IC



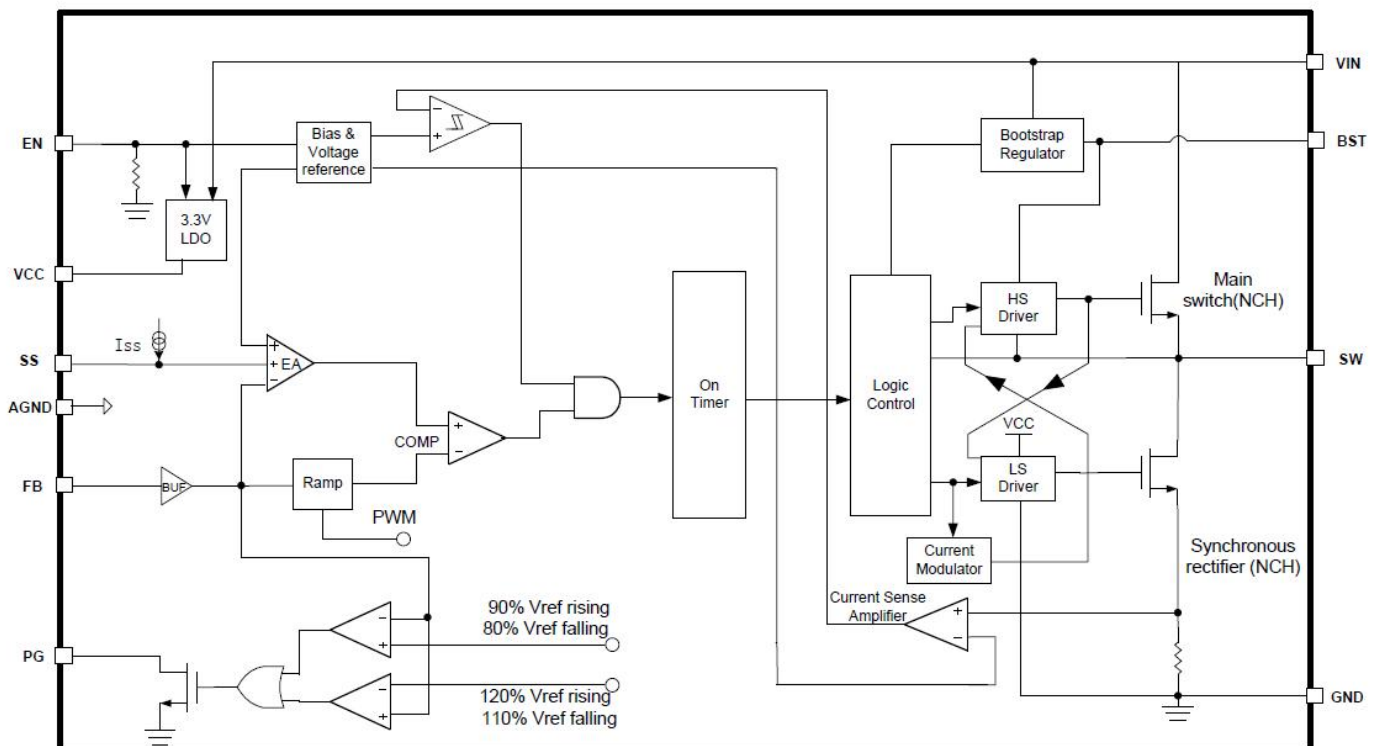
9.2 KP525201CQDGA DC-DC Voltage Converter IC



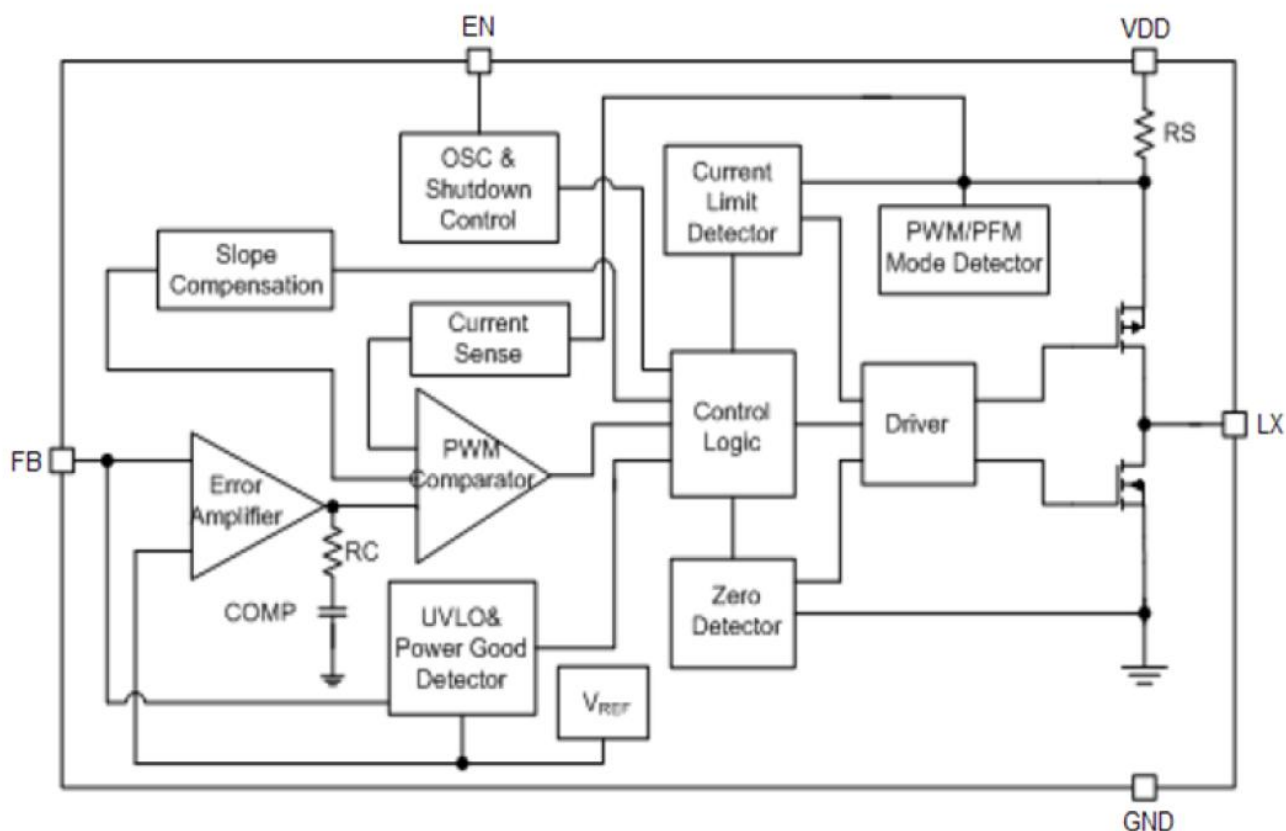
9.3 JW5093SOTI DC-DC Voltage Converter IC



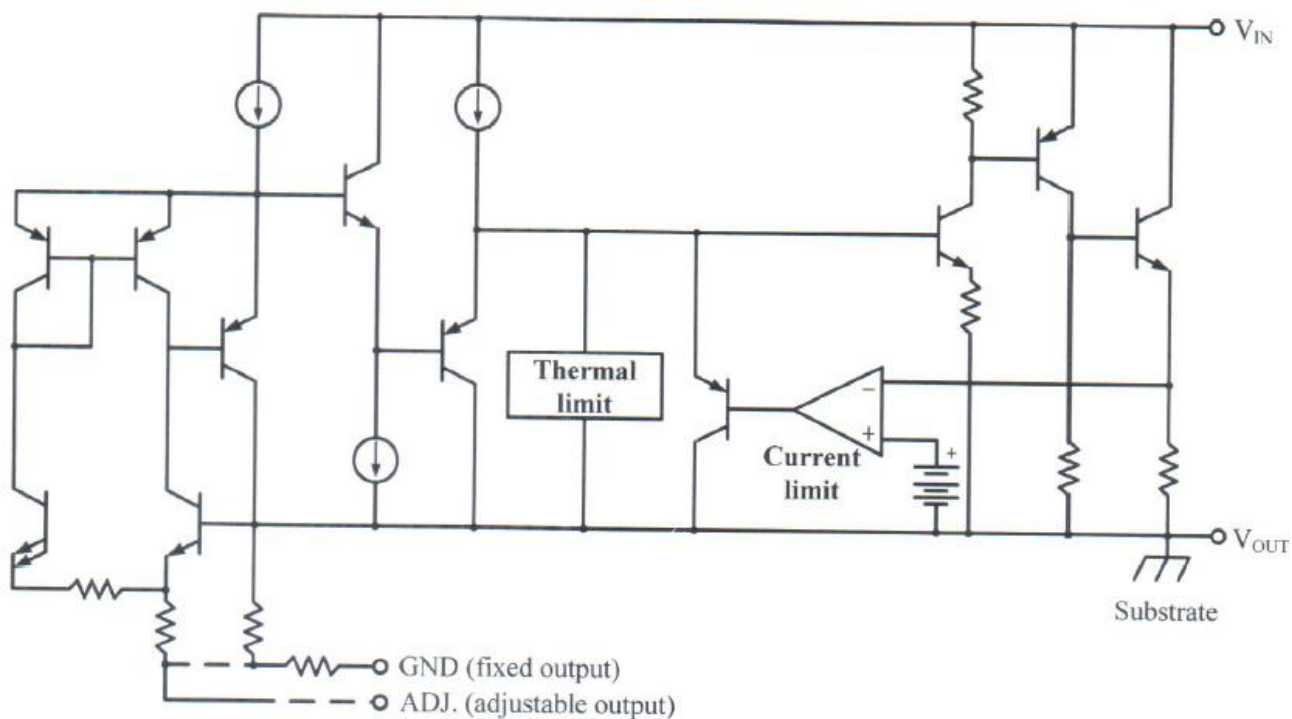
9.4 MP8770GQ DC-DC Voltage Converter IC



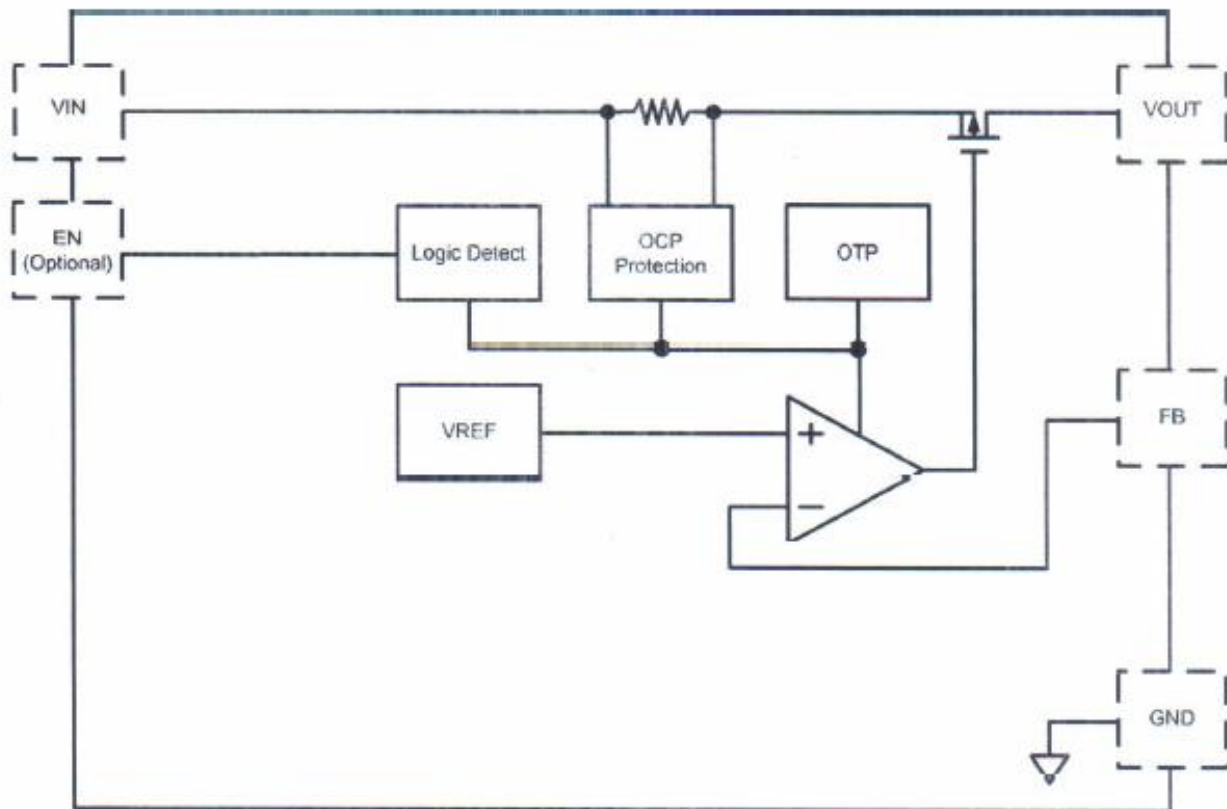
9.5 MP1655GG-Z DC-DC Voltage Converter IC



9.6 THL1117 LDO Voltage Regulator IC

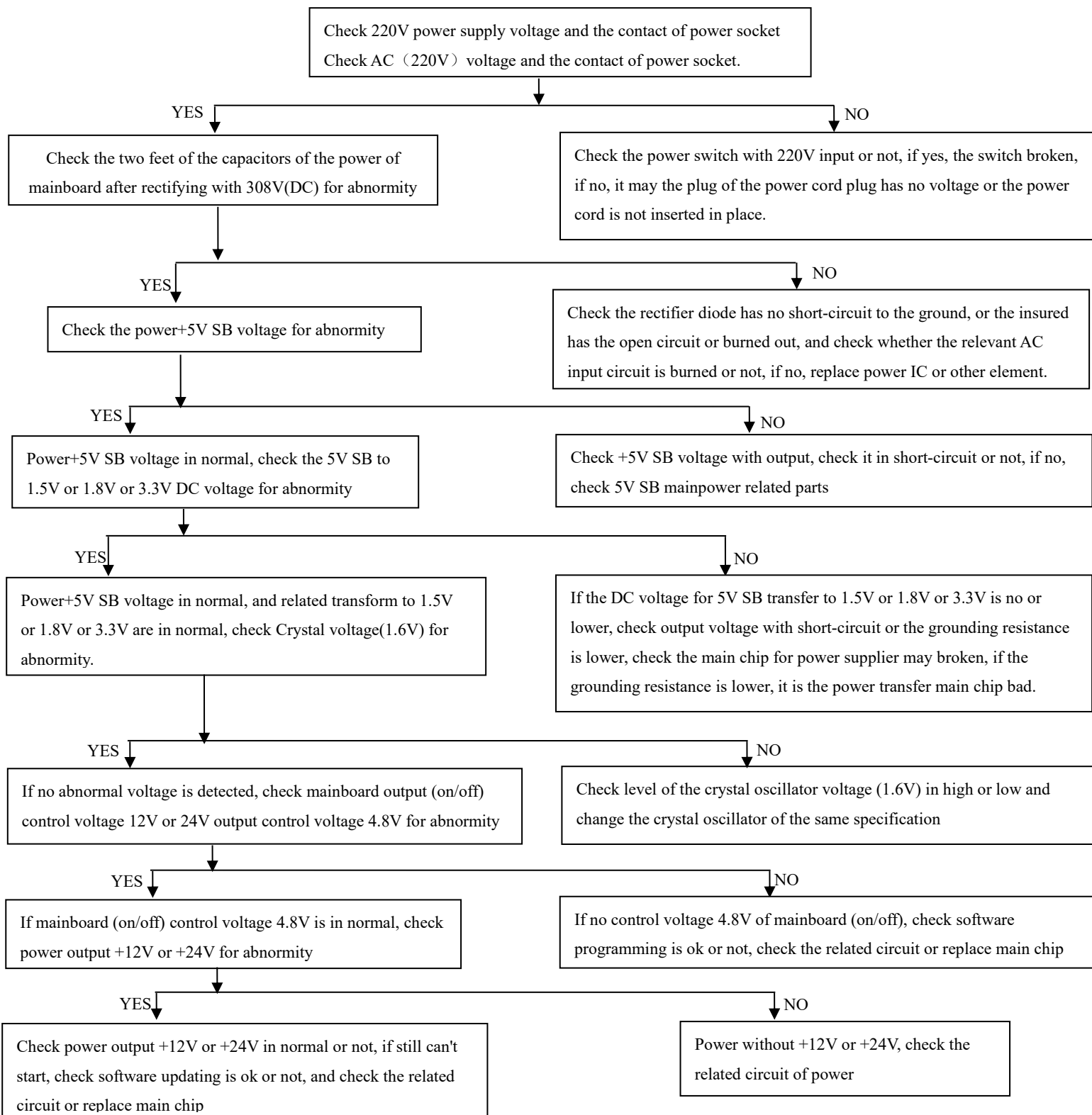


9.7 TH1106-ADJB LDO Voltage Regulator IC

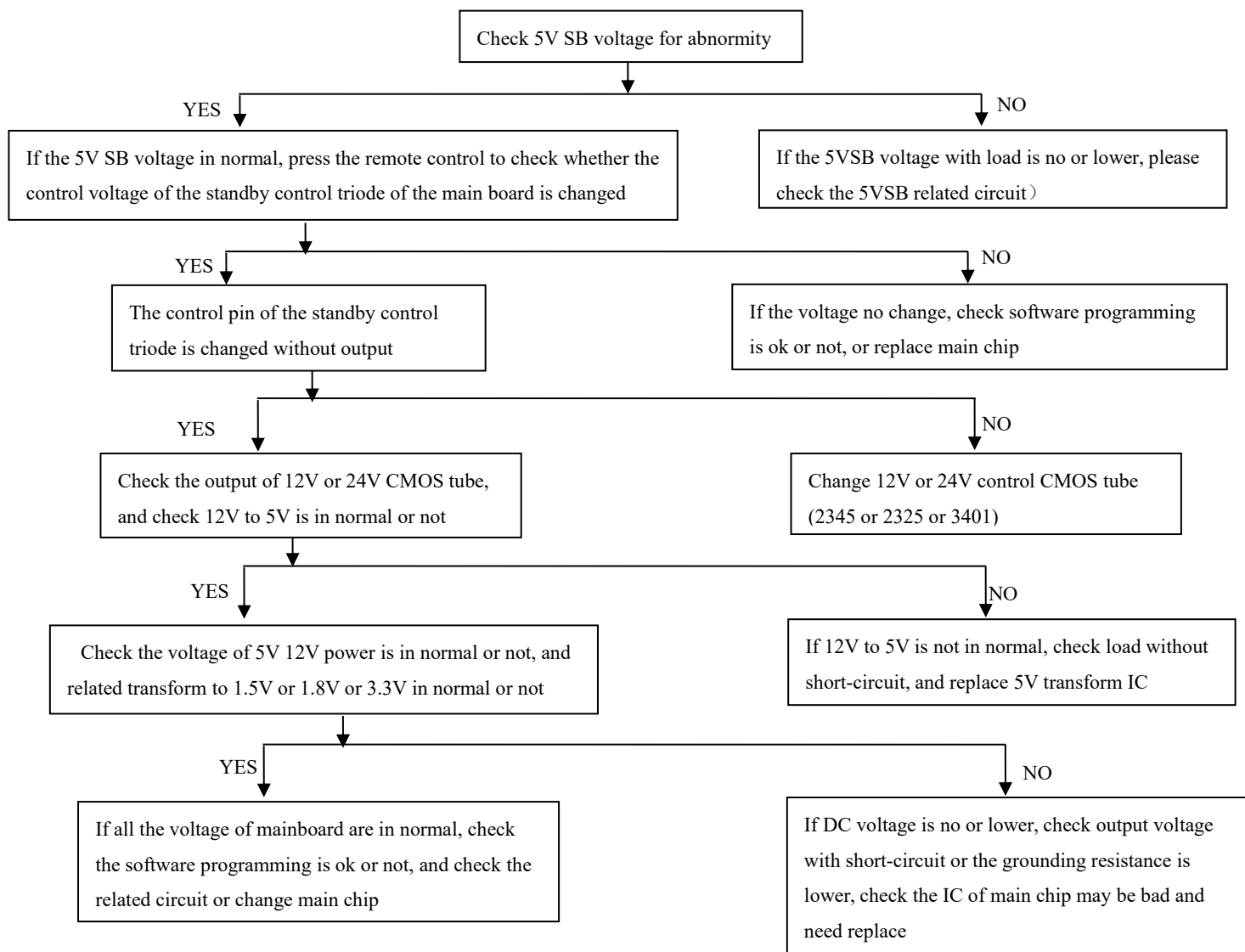


10. Troubleshooting

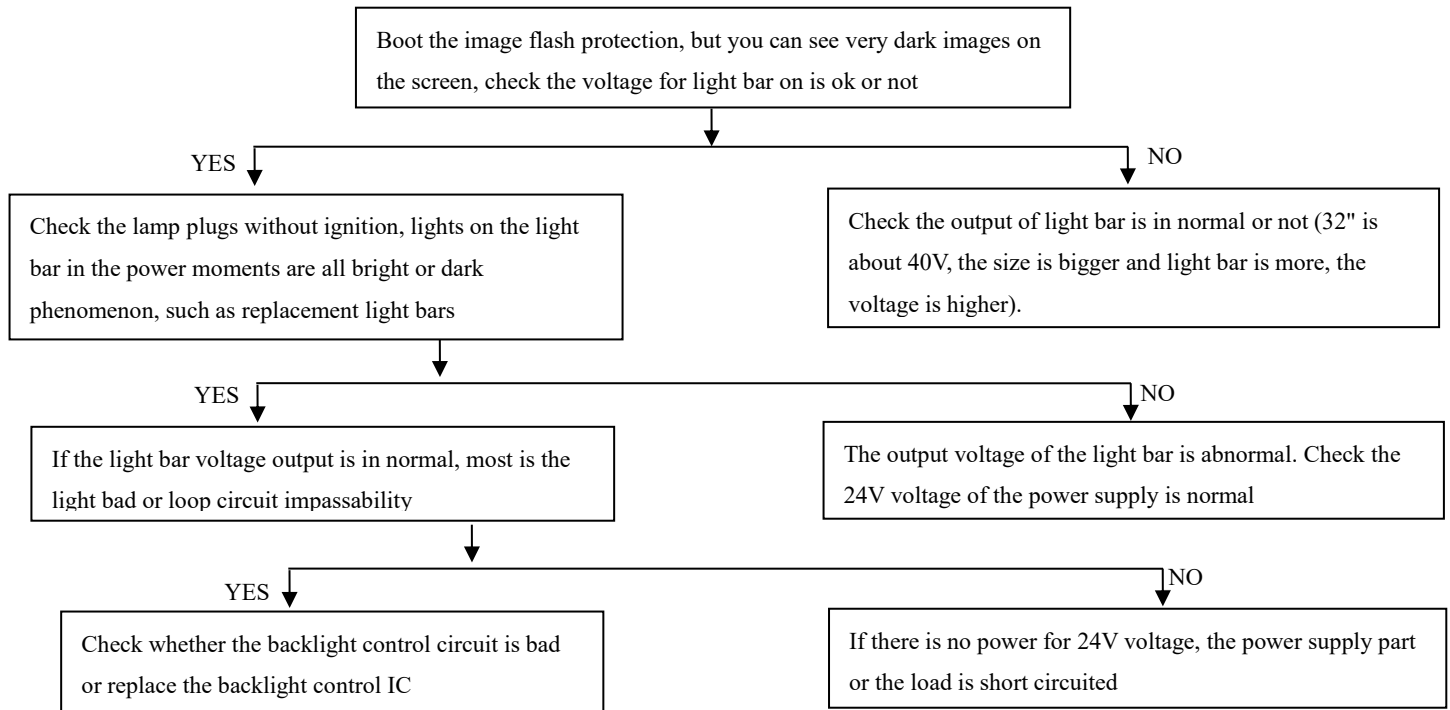
10.1.No power (Connect to power, but all the indicator lights don't work)



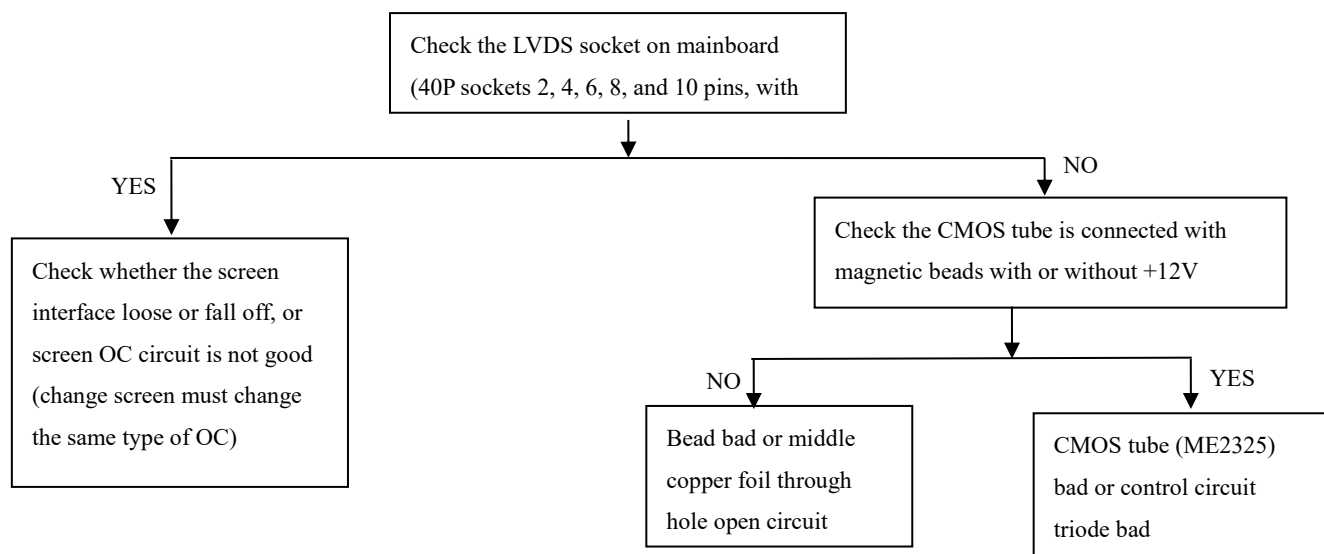
10.2. Red light can't start (Red light, remote control no reflect, no picture display)



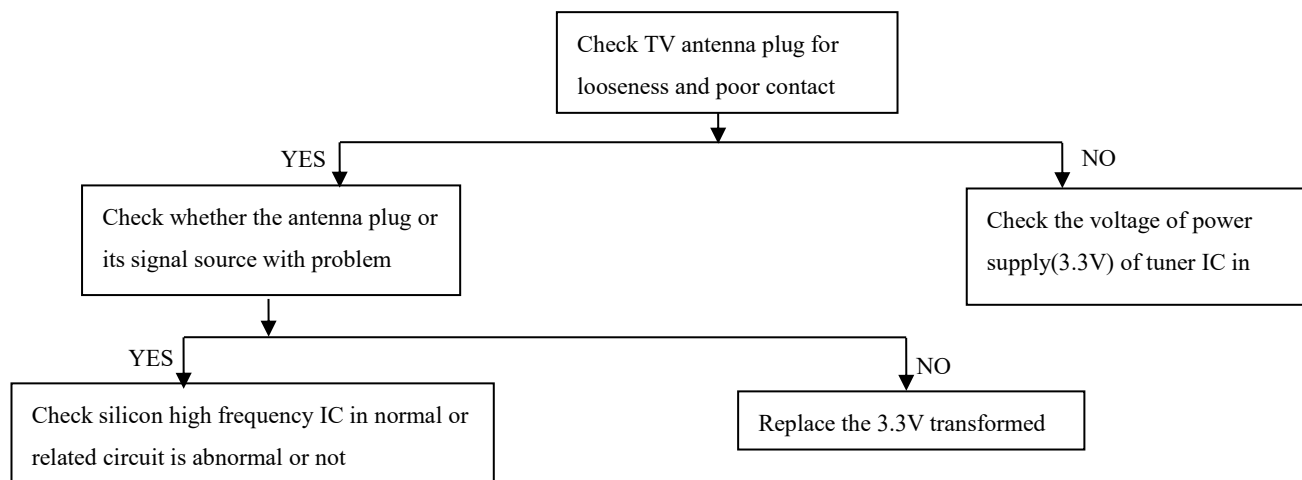
10.3. No light (Boot the image flash protection, but you can see very dark images on the screen)



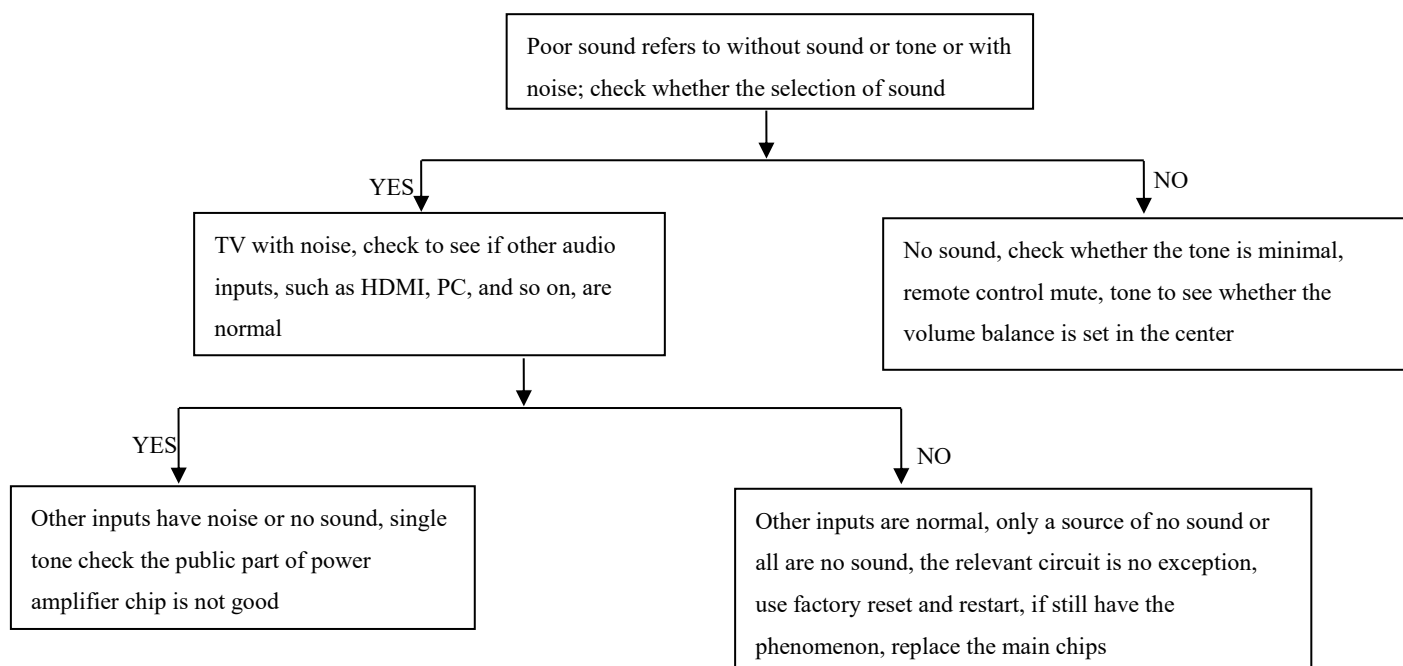
10.4. No picture (the screen light shadow, backlight is bright, but no picture display)



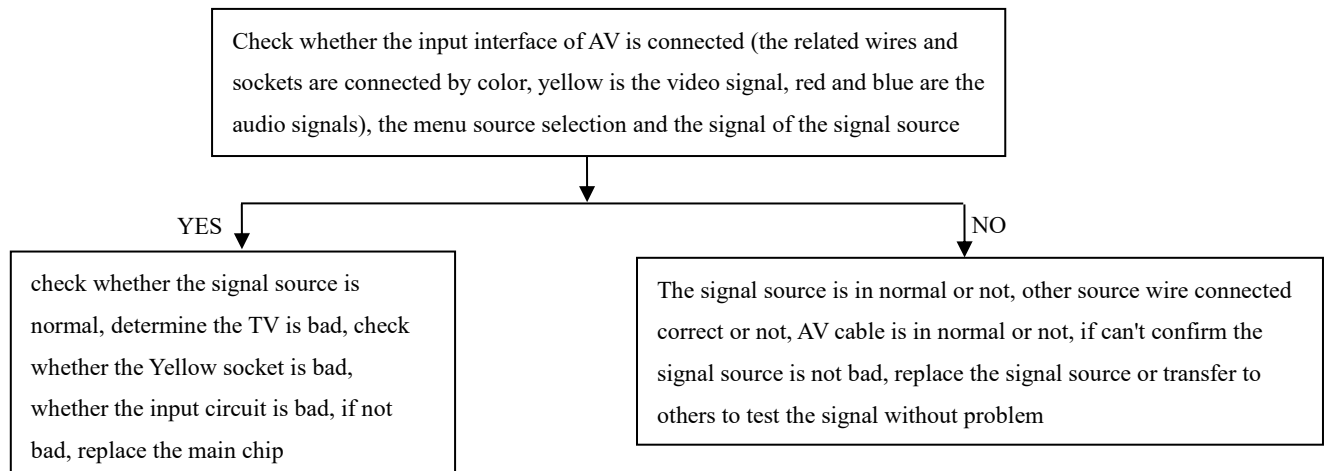
10.5. TV without channel or less channel or interfered



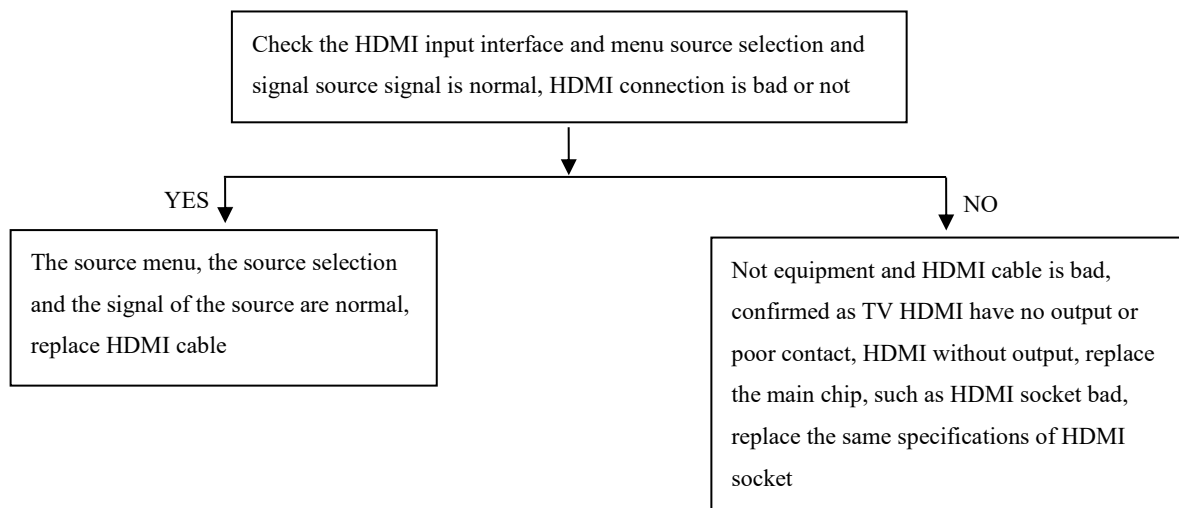
10.6. Poor sound



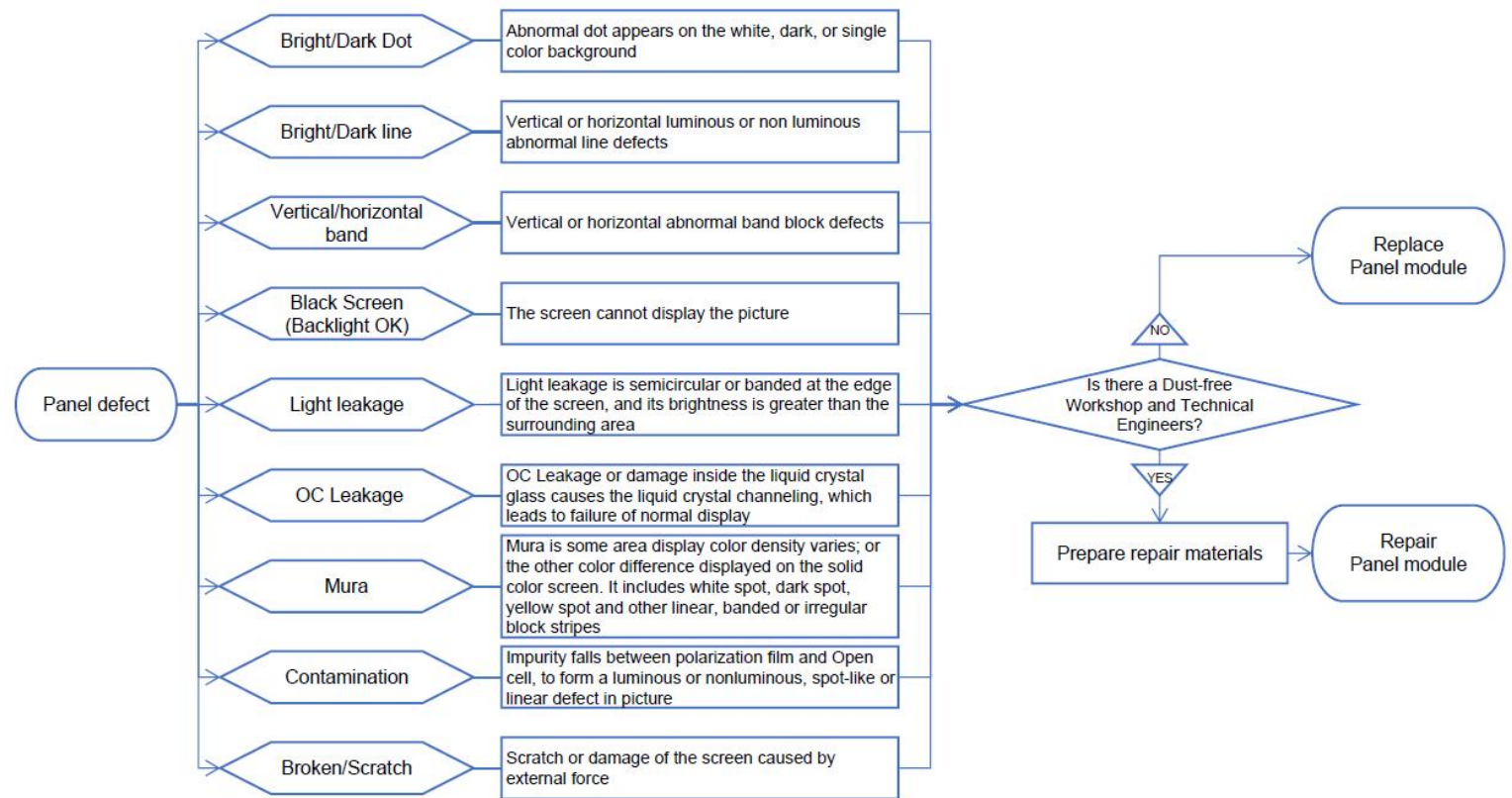
10.7. AV (video) without picture



10.8. HDMI without picture

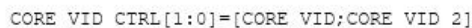


10.9 Panel defect

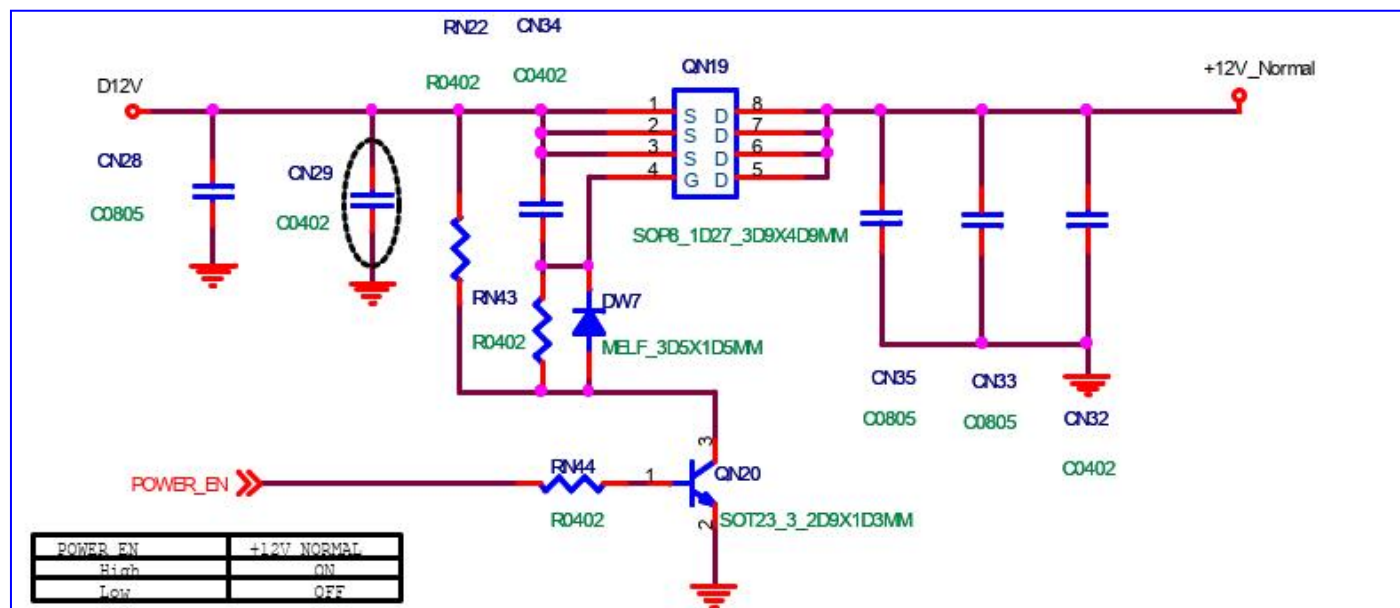


10.10 Panel defect sample photo

Panel defect	Sample photo	Panel defect	Sample photo
Bright/Dark Dot		OC Leakage	
Bright/Dark line		Mura	
Vertical/horizontal band		Contamination	
Black Screen (Backlight OK)		Broken/Scratch	
Light leakage			



CORE_VID	CORE_VID_2	DC Side	Ball Side Voltage
L (OD Off)	L	0.985V	0.95V [TBD]
	H	1.015V	0.98V [TBD]
H (OD ON)	L	1.178V	1.14V [TBD]
	H	1.208V	1.17V [TBD]

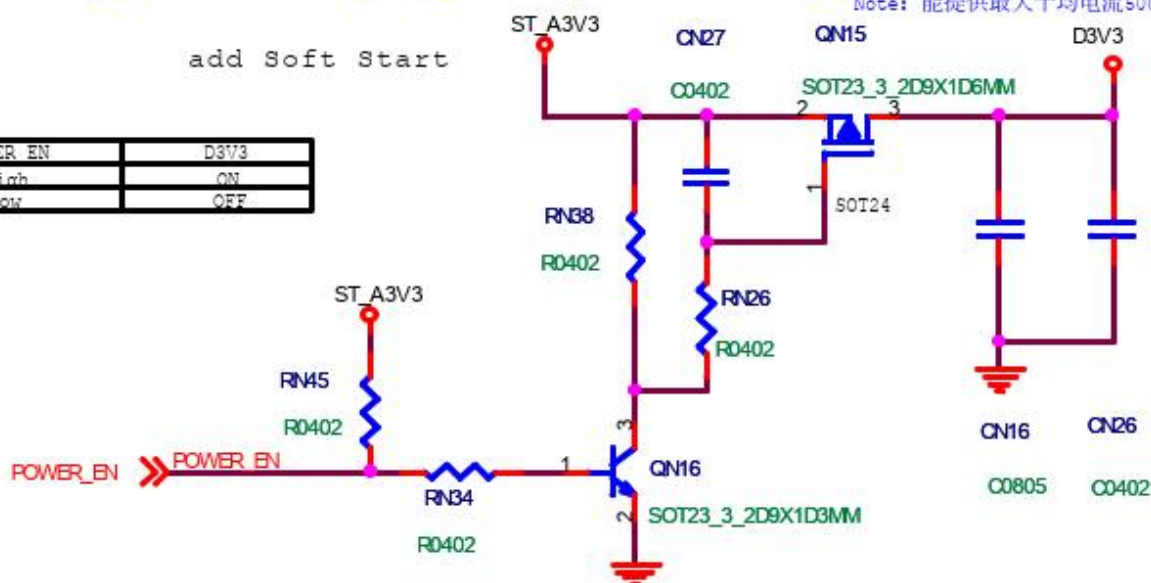


+3.3V_STANDBY(ST_A3V3) ==> +3.3V_NORMAL(D3V3)

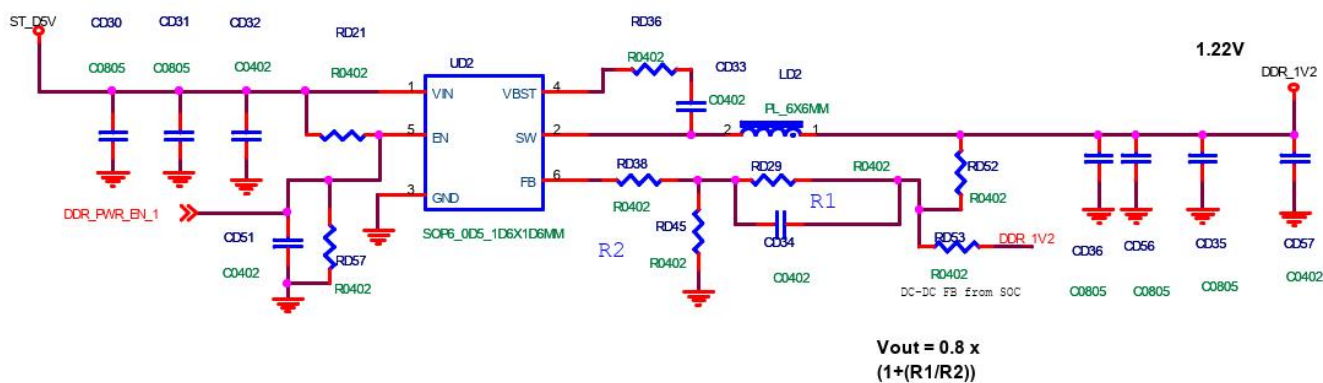
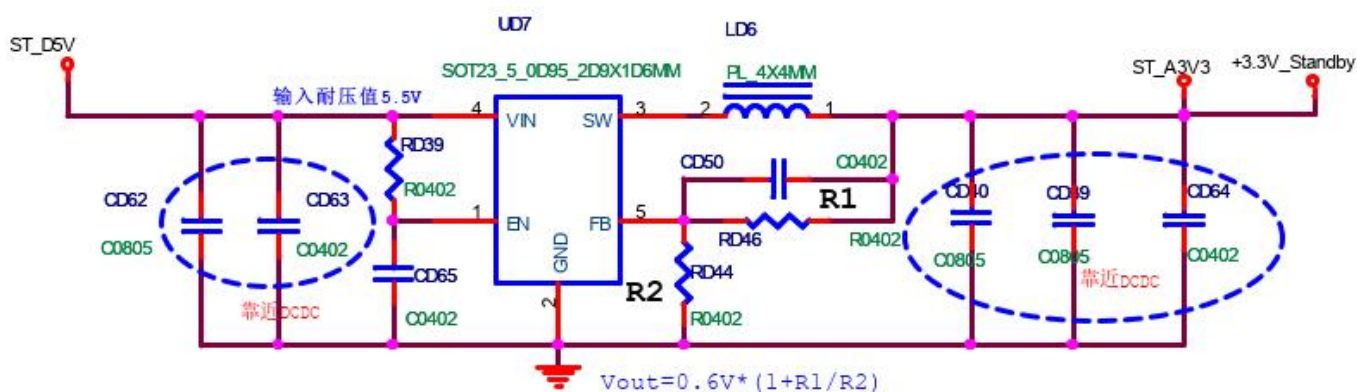
Note: 能提供最大平均电流500MA, 25MILS.

add Soft Start

POWER_EN	D3V3
High	ON
Low	OFF



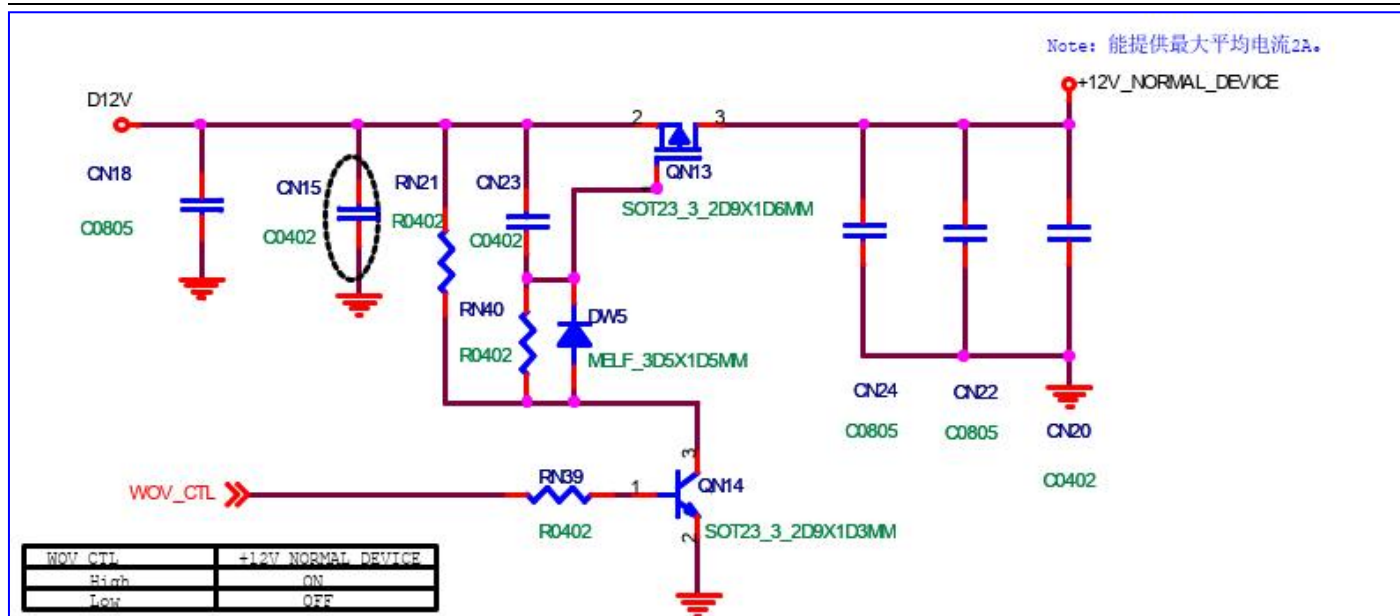
+5V_STANDBY (ST_D5V) ==> +3.3V_STANDBY (ST_A3V3)



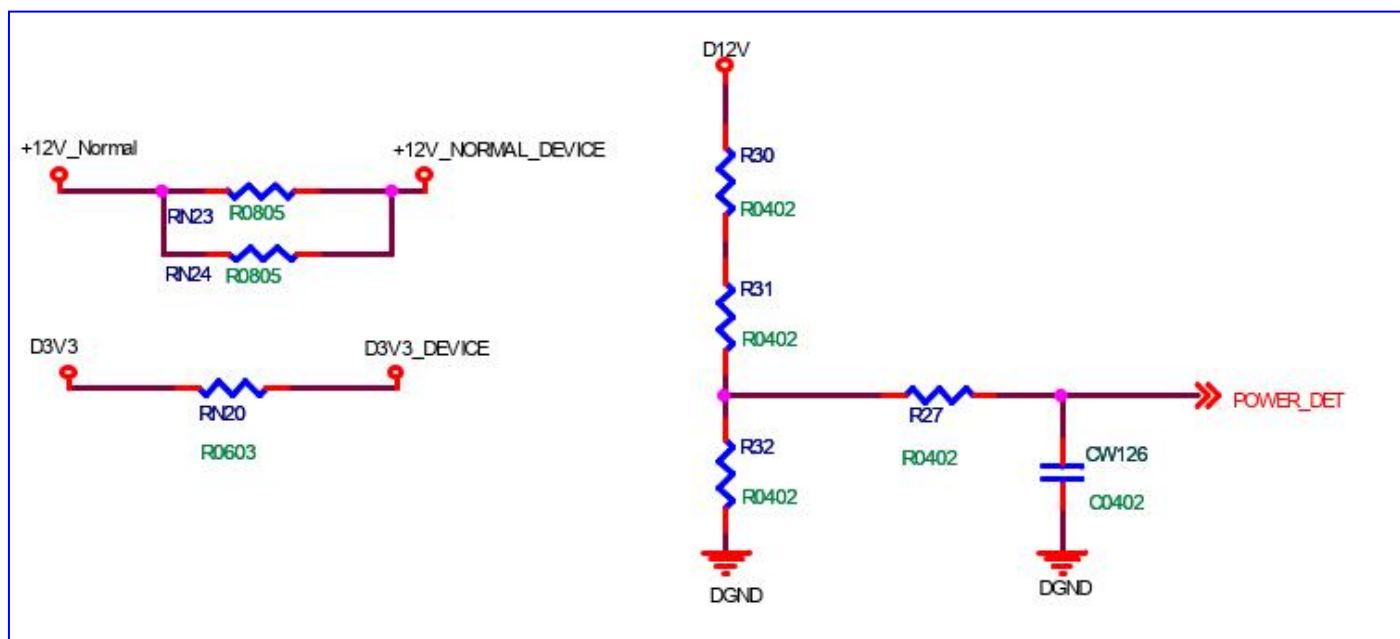
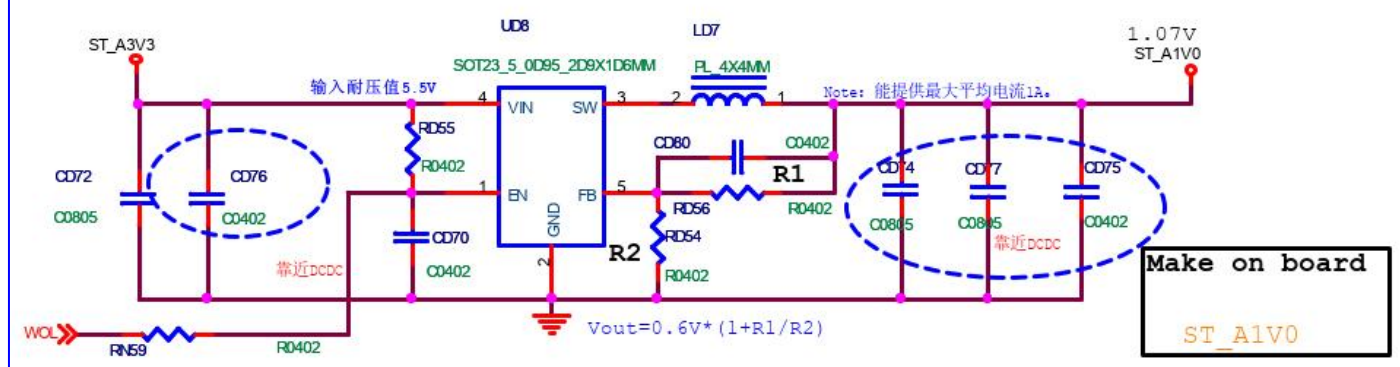


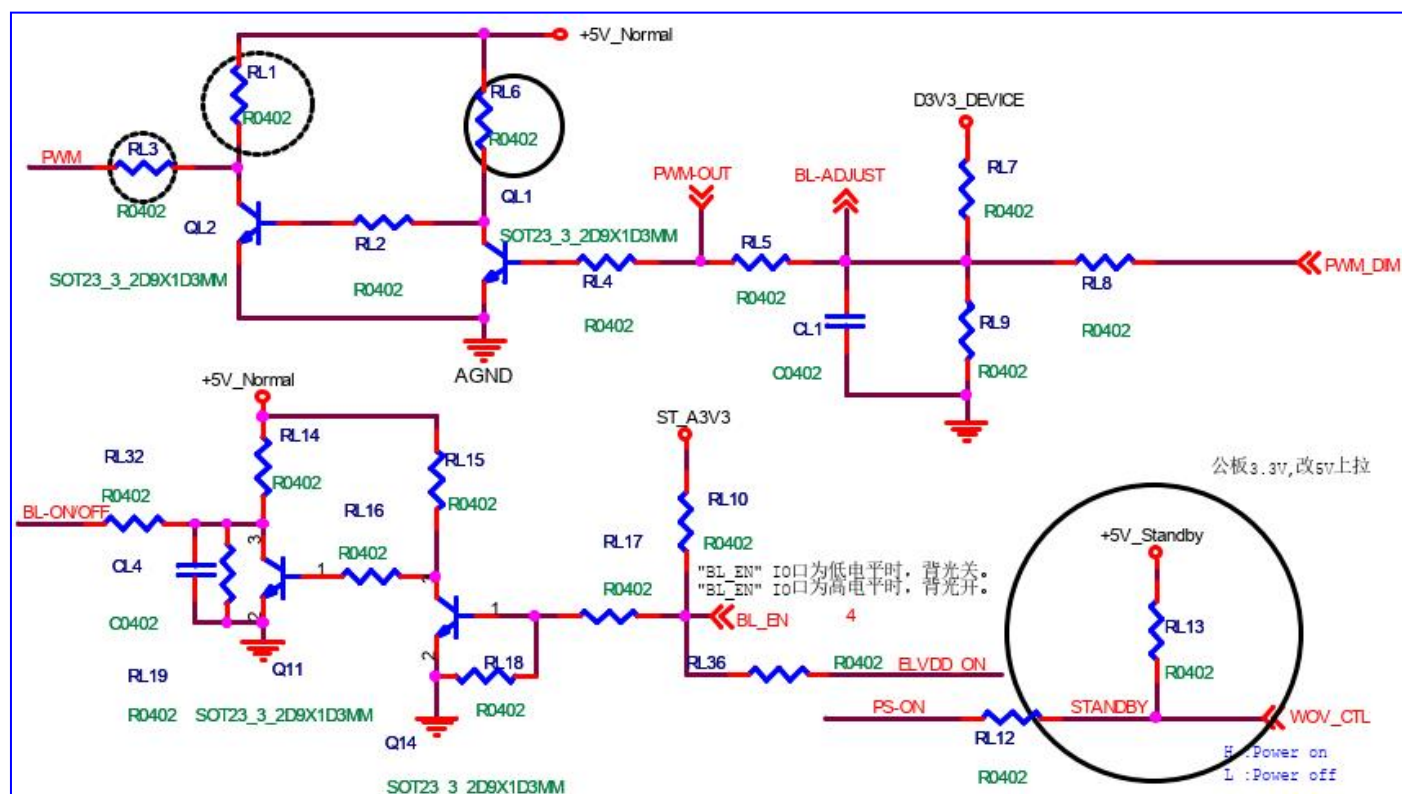
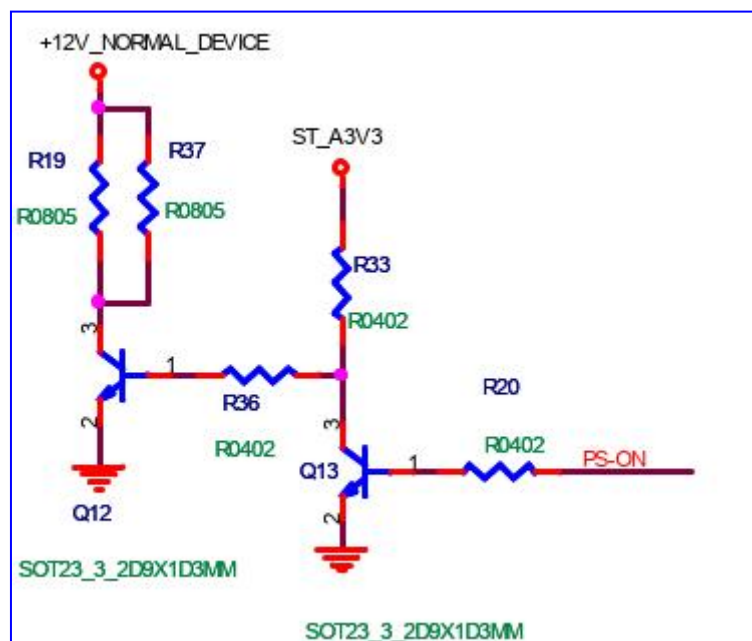
Make on board

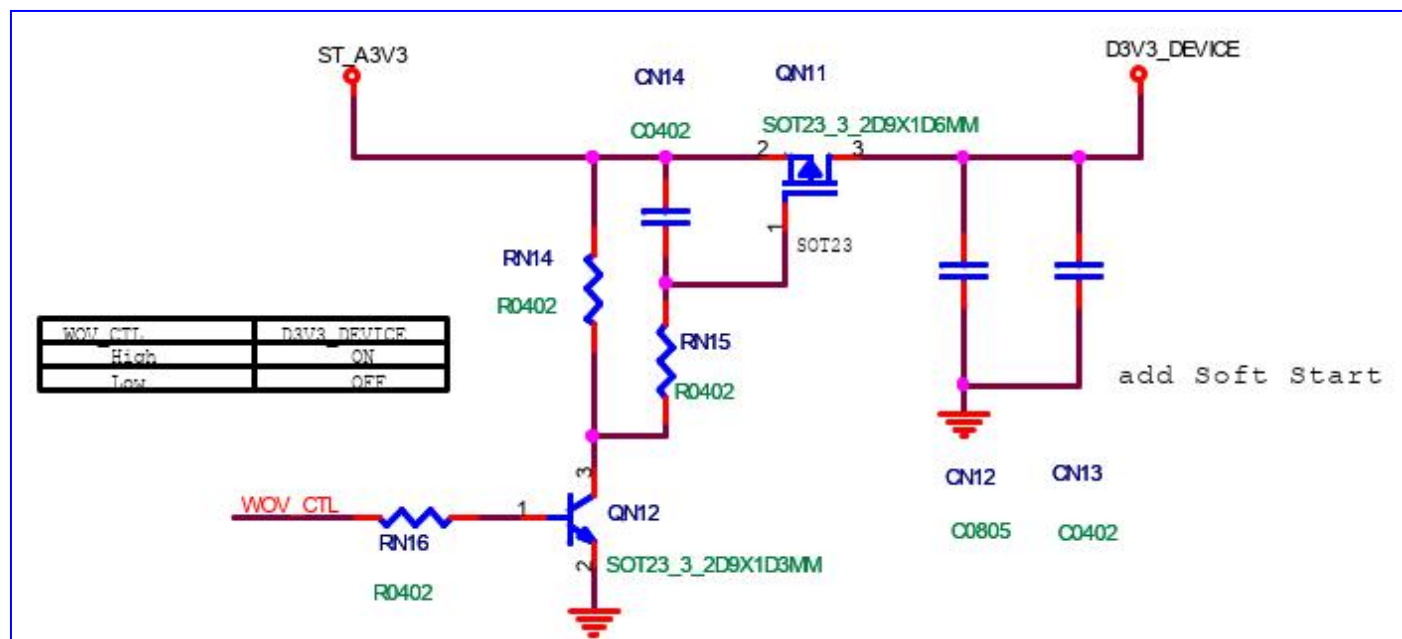
ST A1V0



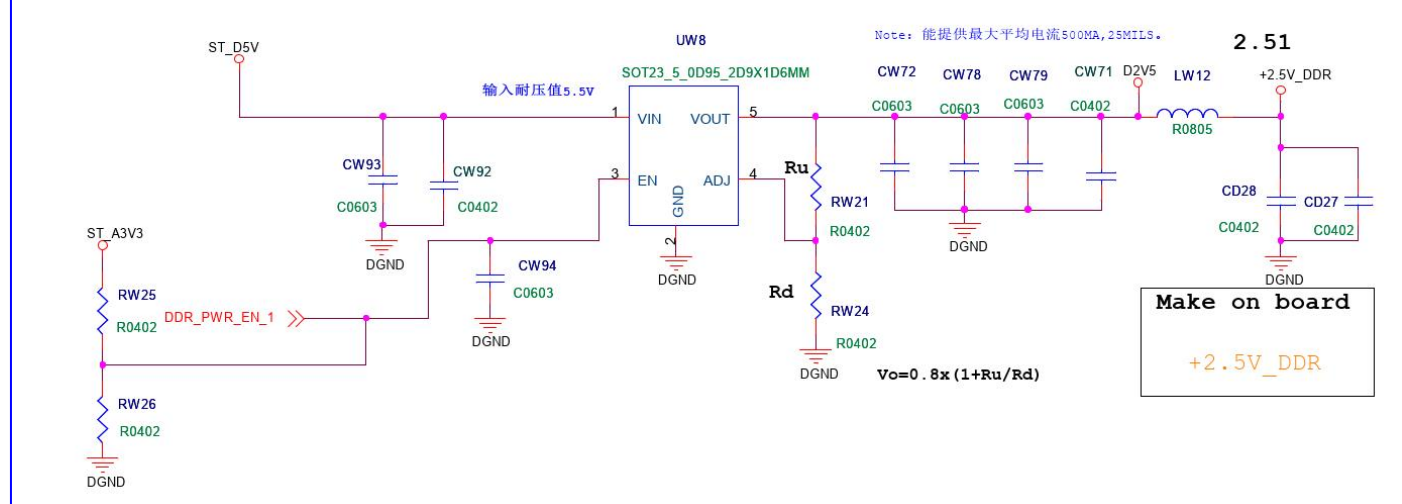
+3.3V_STANDBY(ST_A3V3) ==> +1.0V_STANDBY(ST_A1V0)



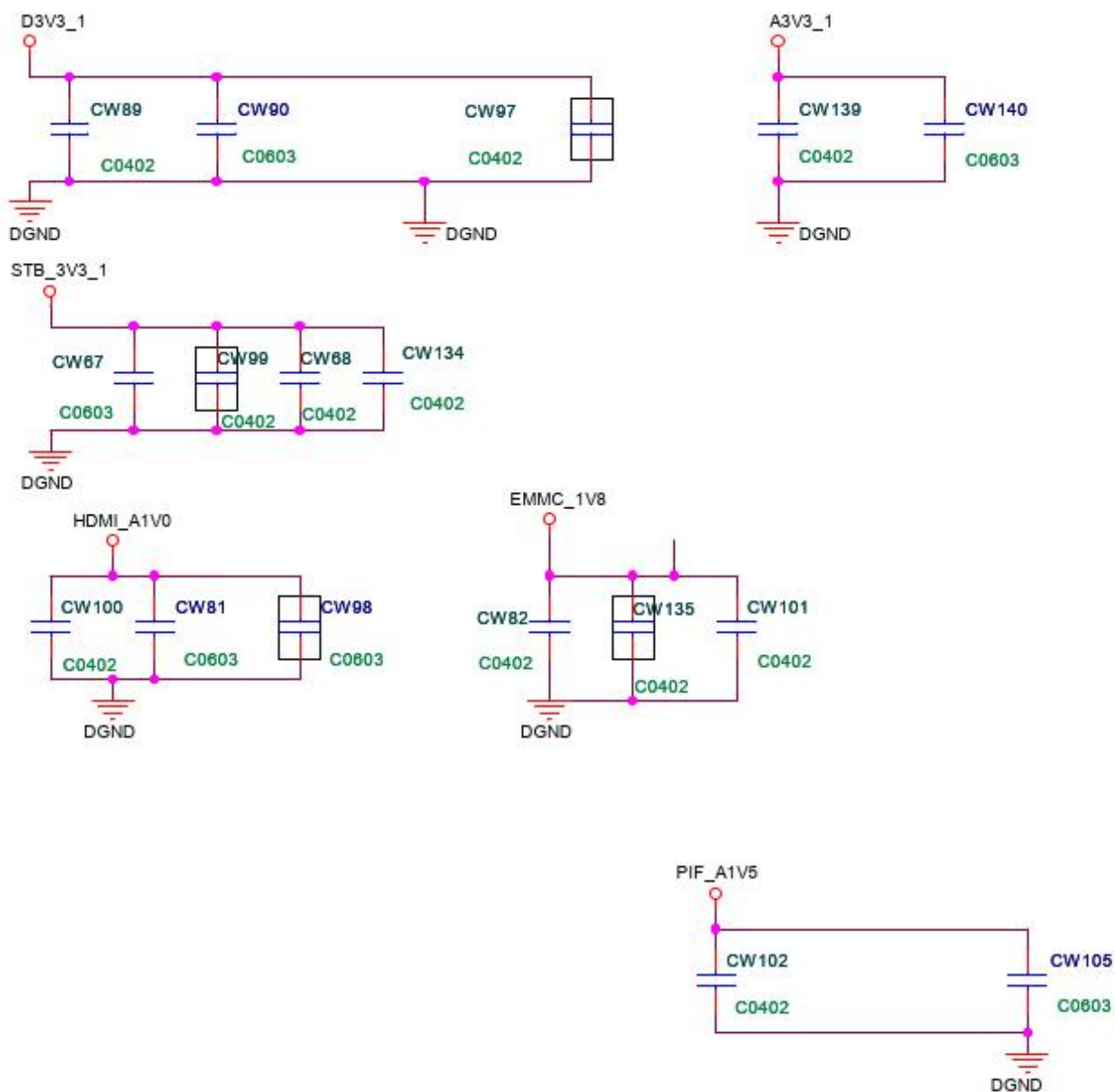


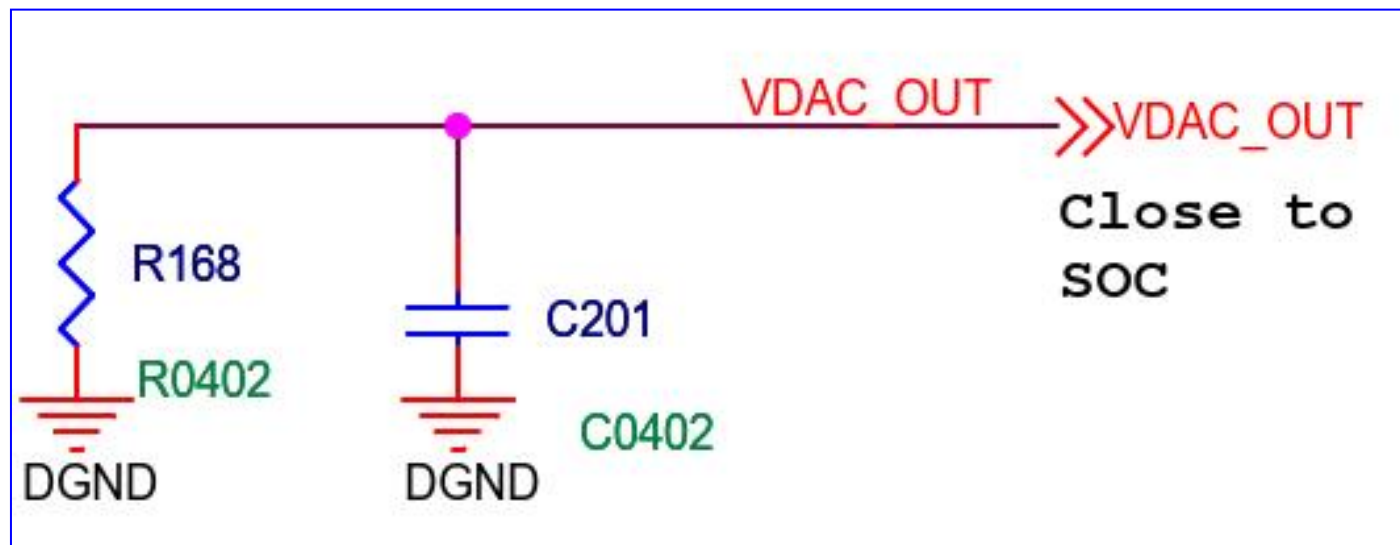


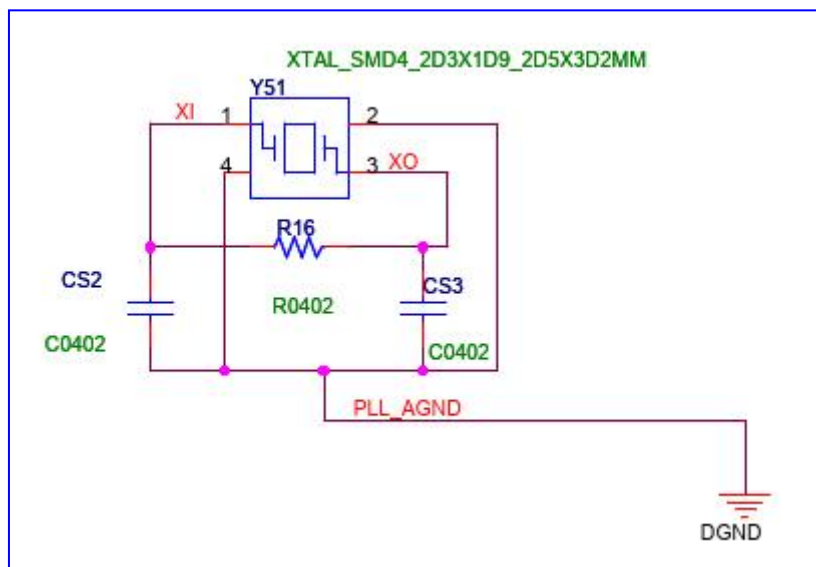
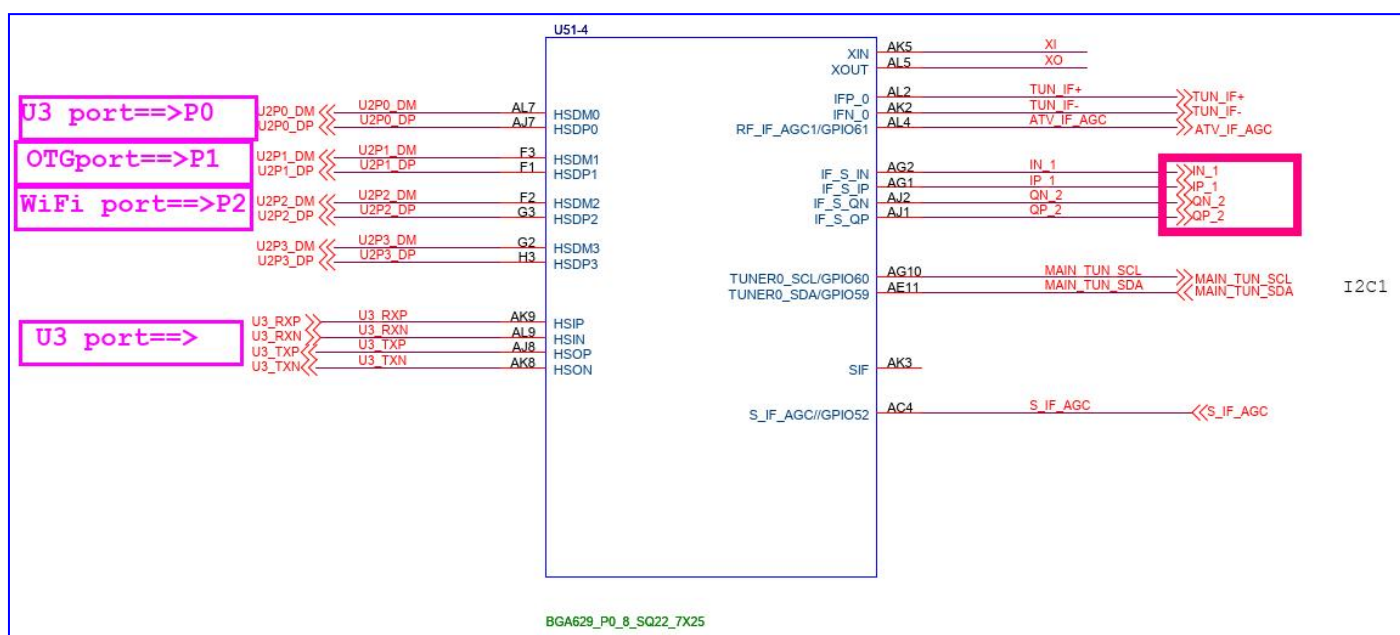
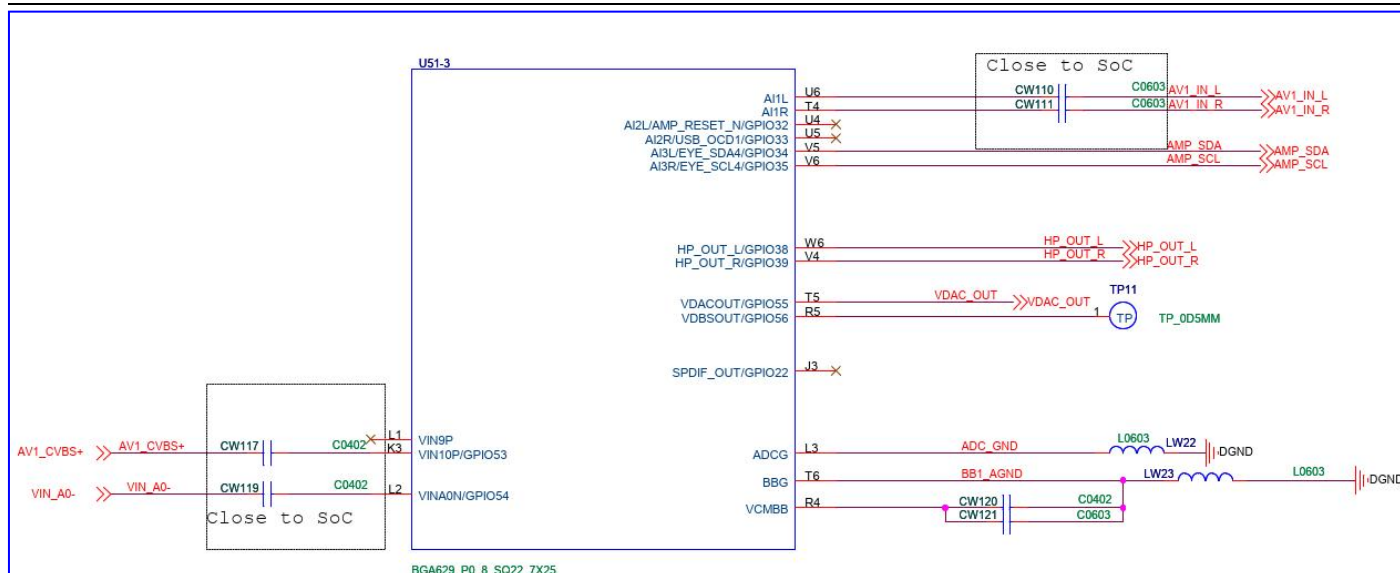
DDR4 Only

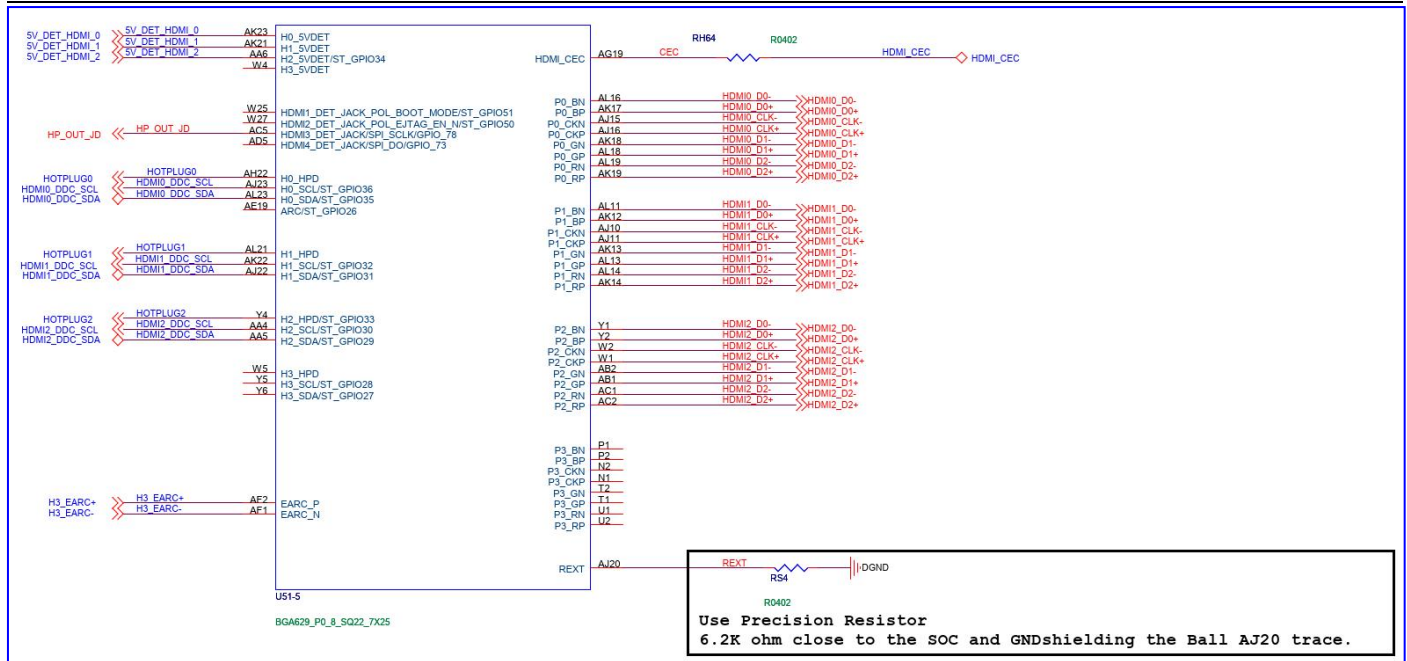


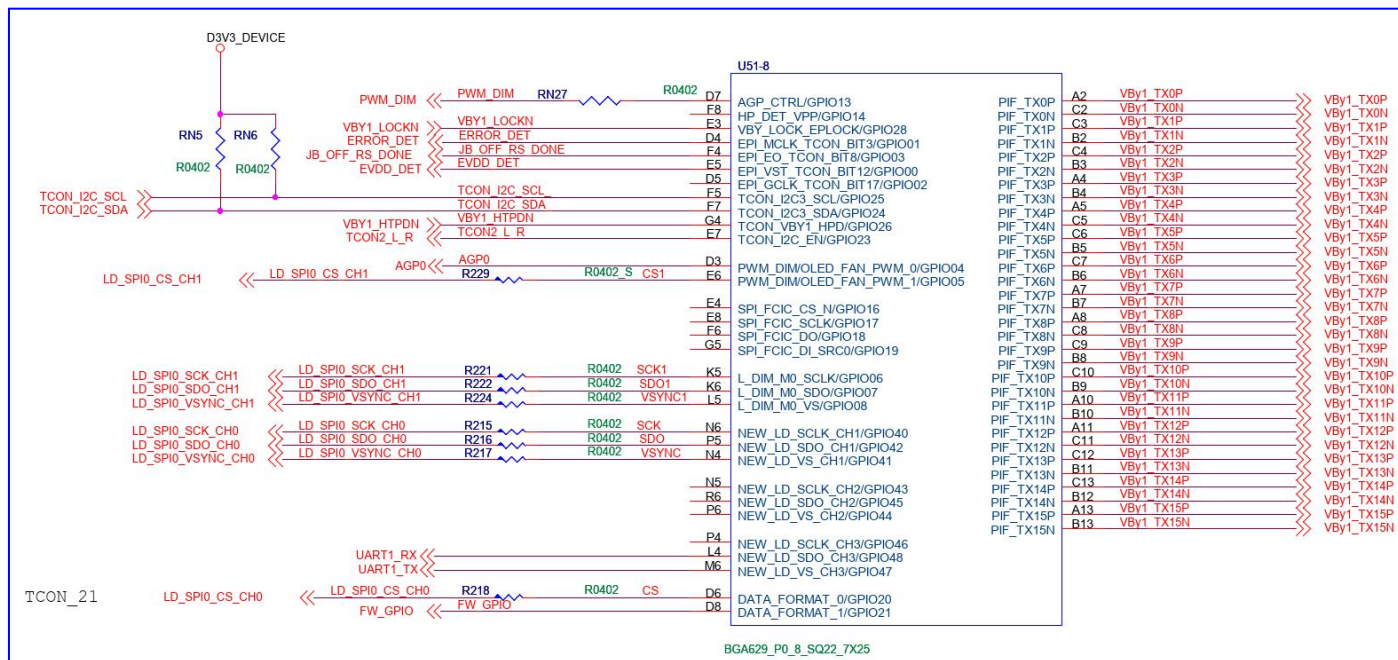
IC Side Bypass MLCC

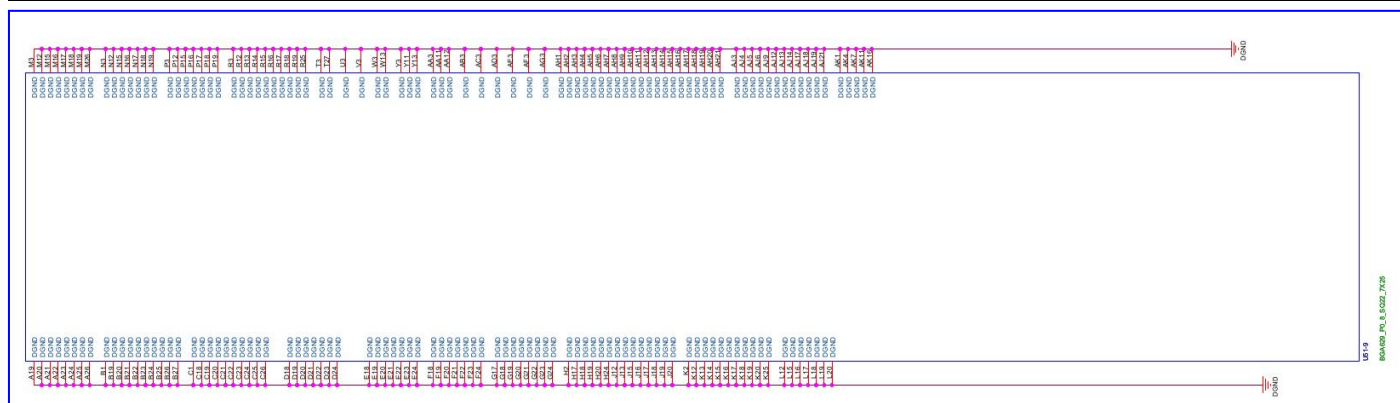




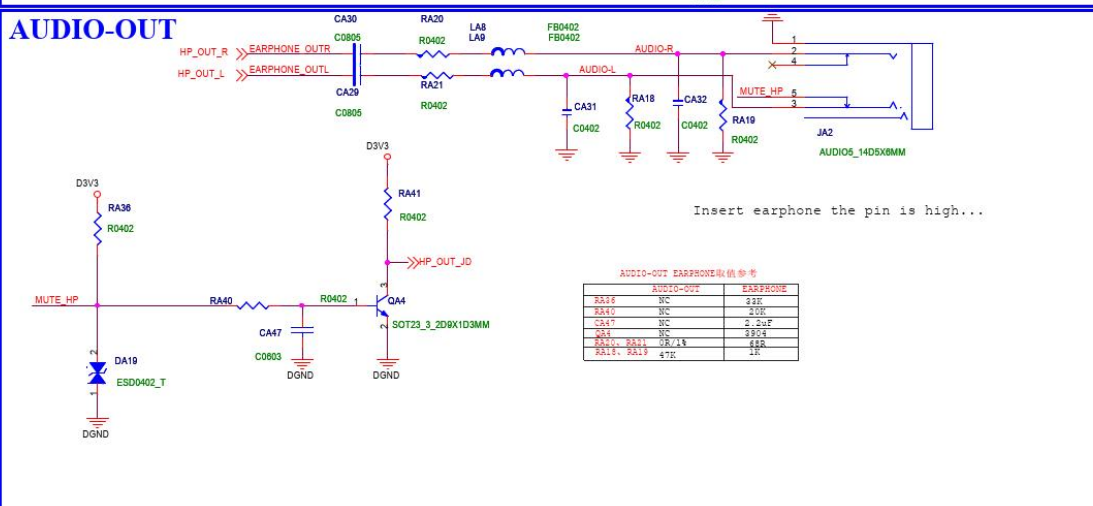
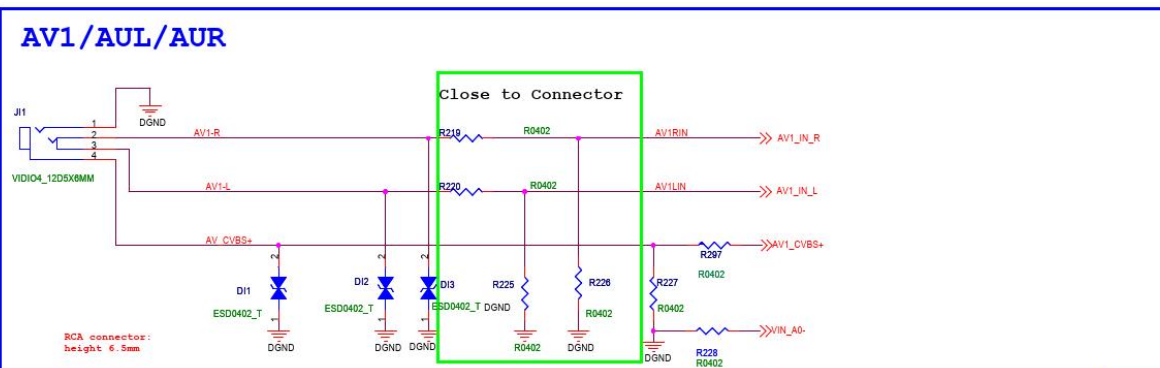




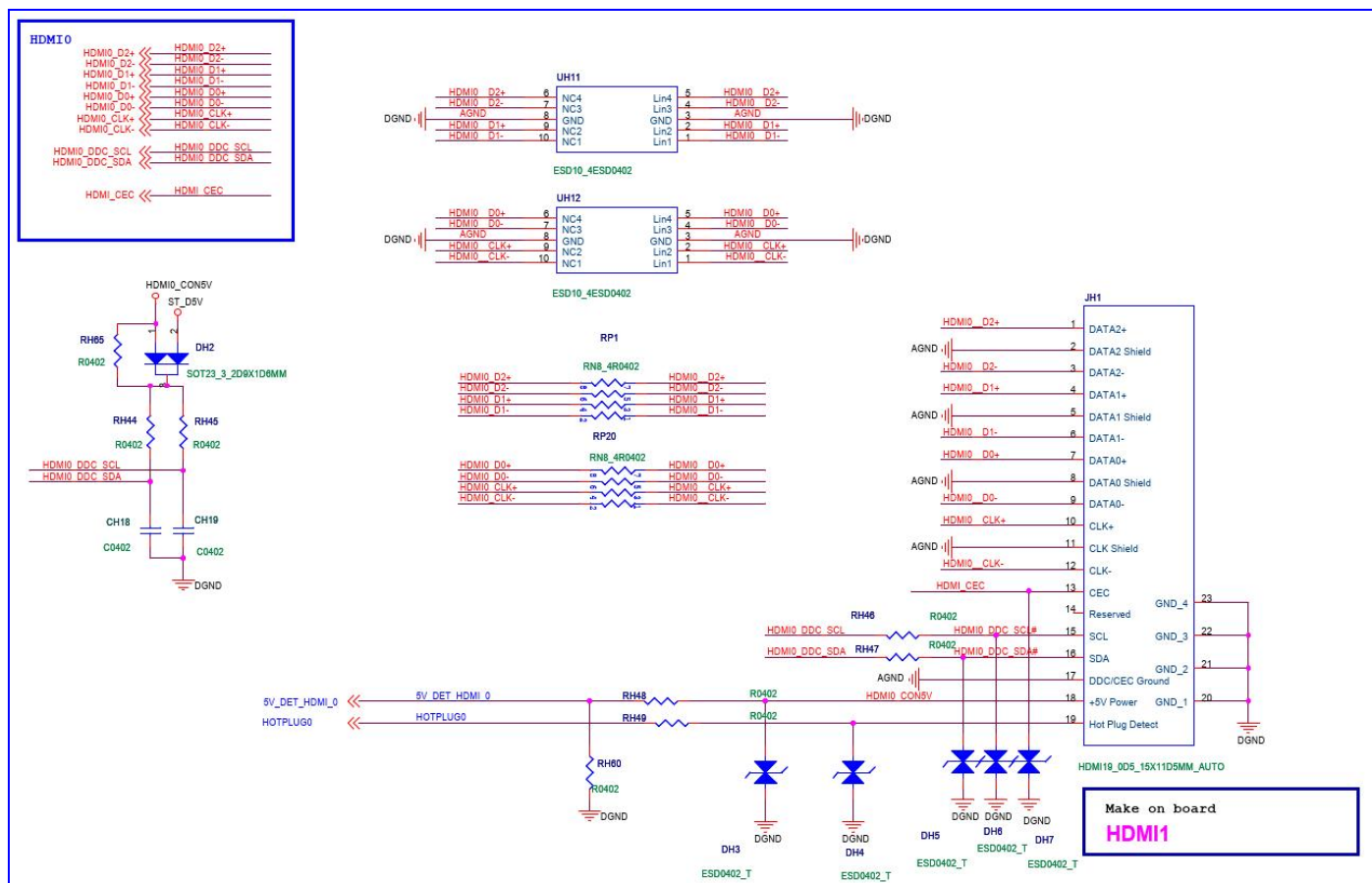


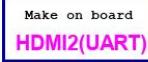


AV1_CVBS+ <-> AV1_CVBS+
 VIN_A0- <-> VIN_A0-
 AV1_IN_L <-> AV1_IN_L
 AV1_IN_R <-> AV1_IN_R
 VDACC_OUT <-> VDACC_OUT

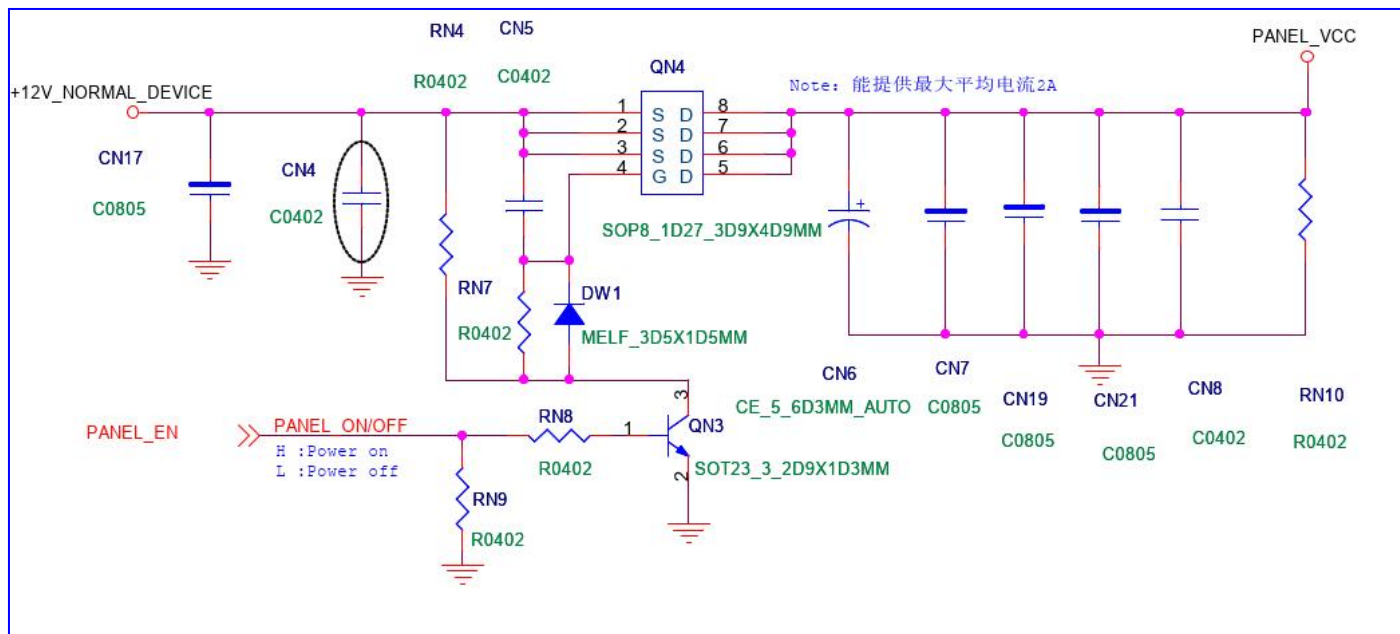


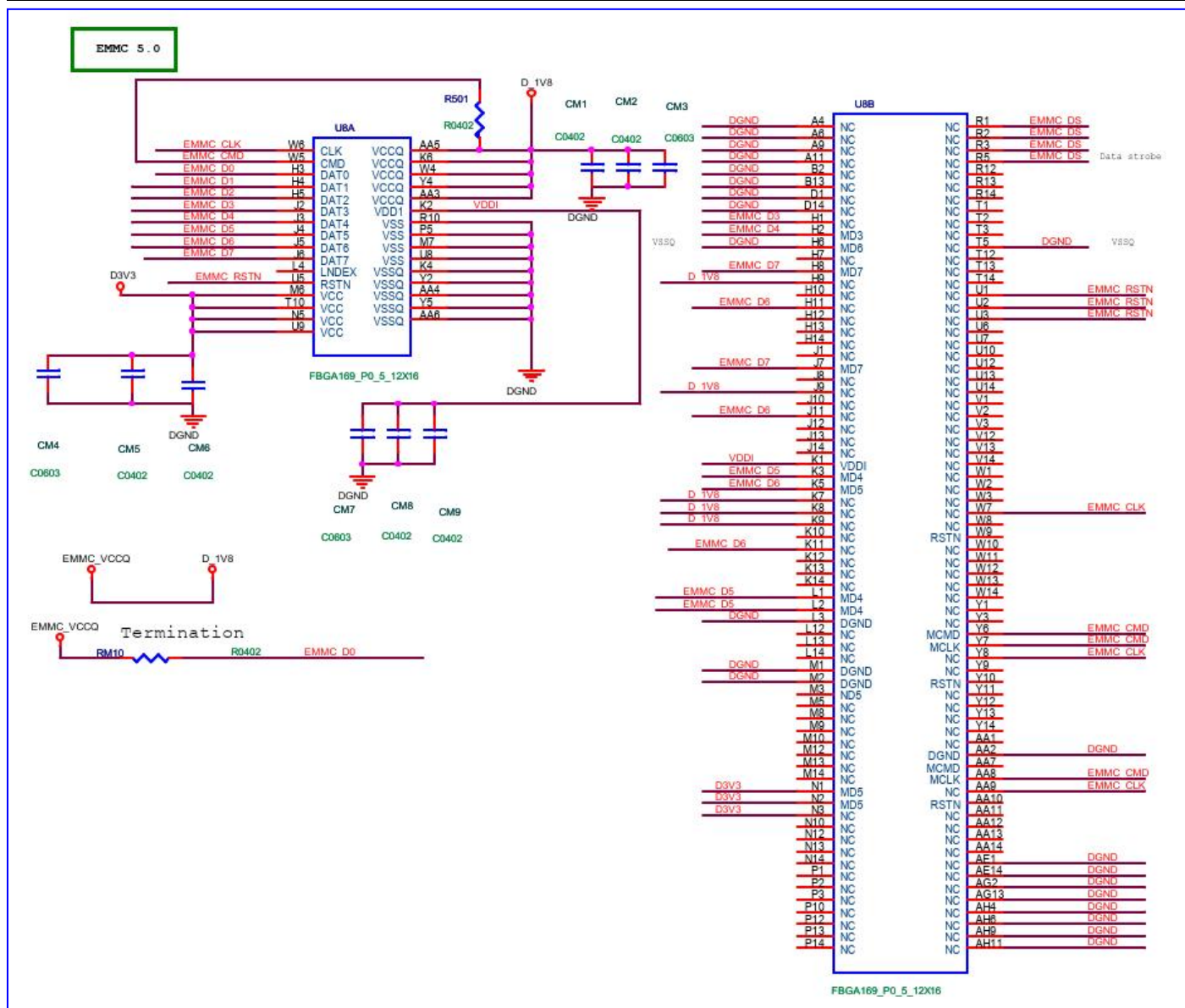
Optical-OUT

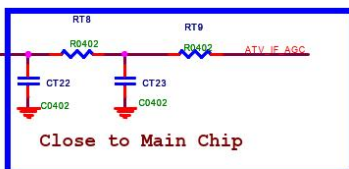
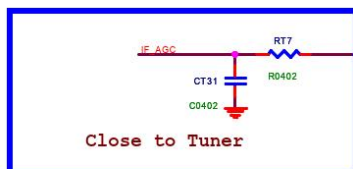
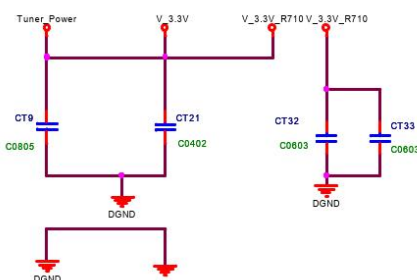
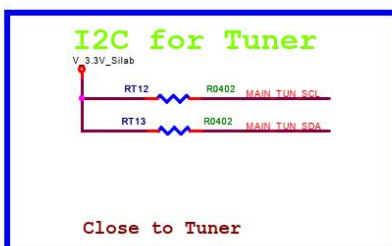
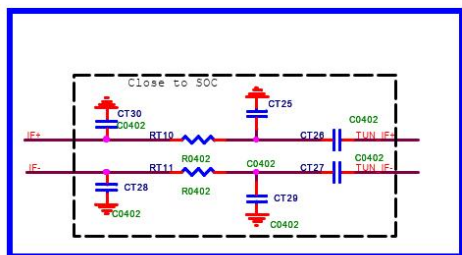


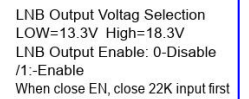


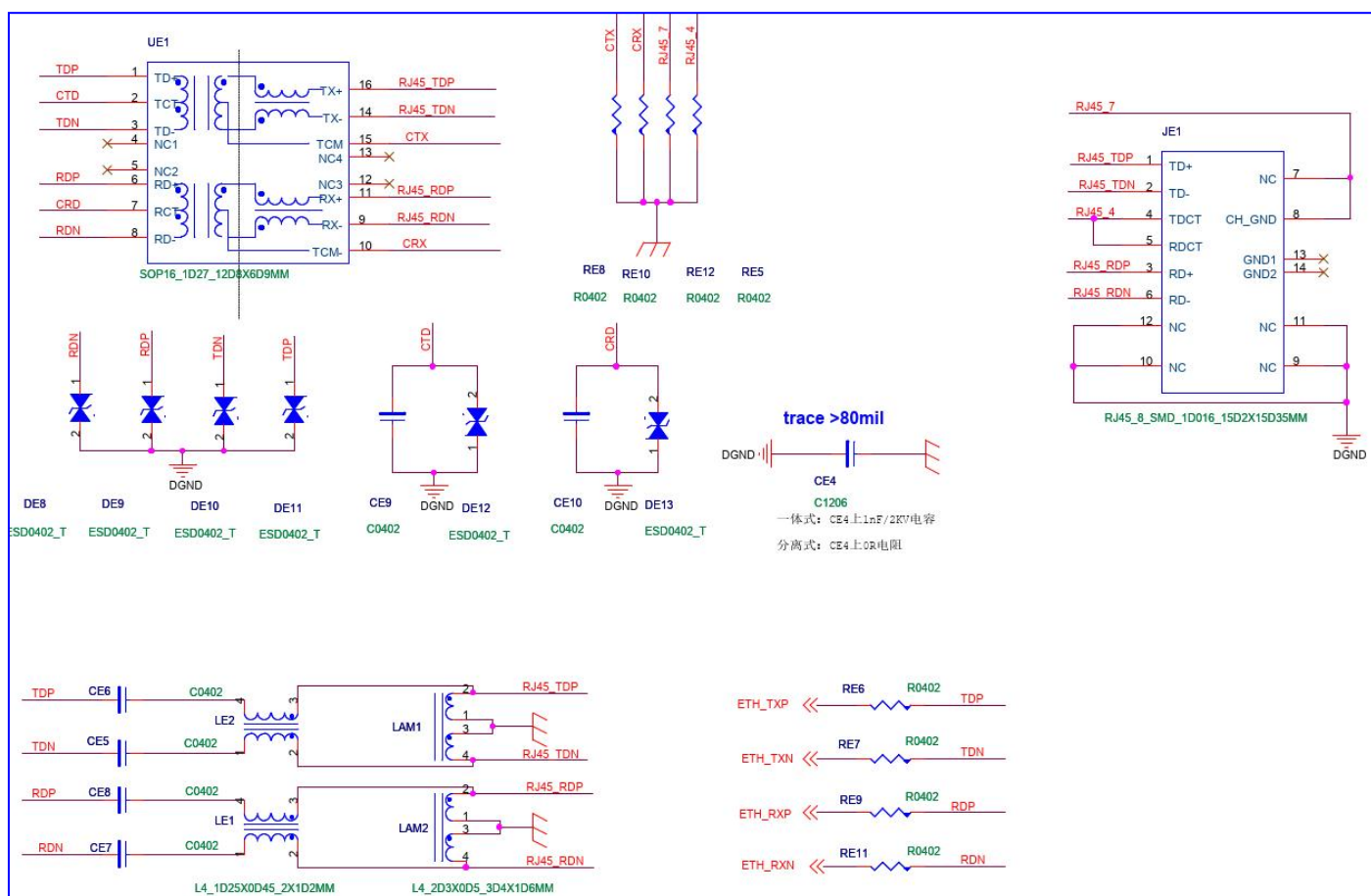
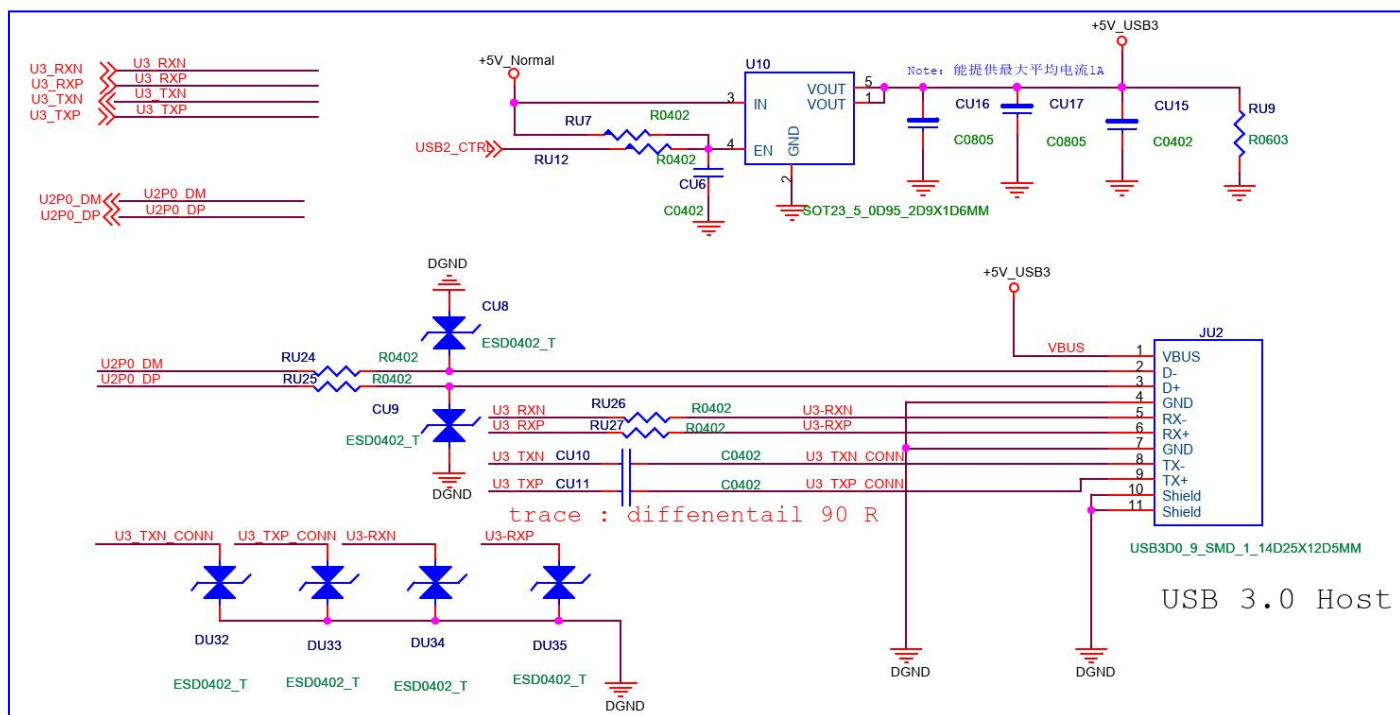


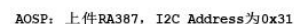




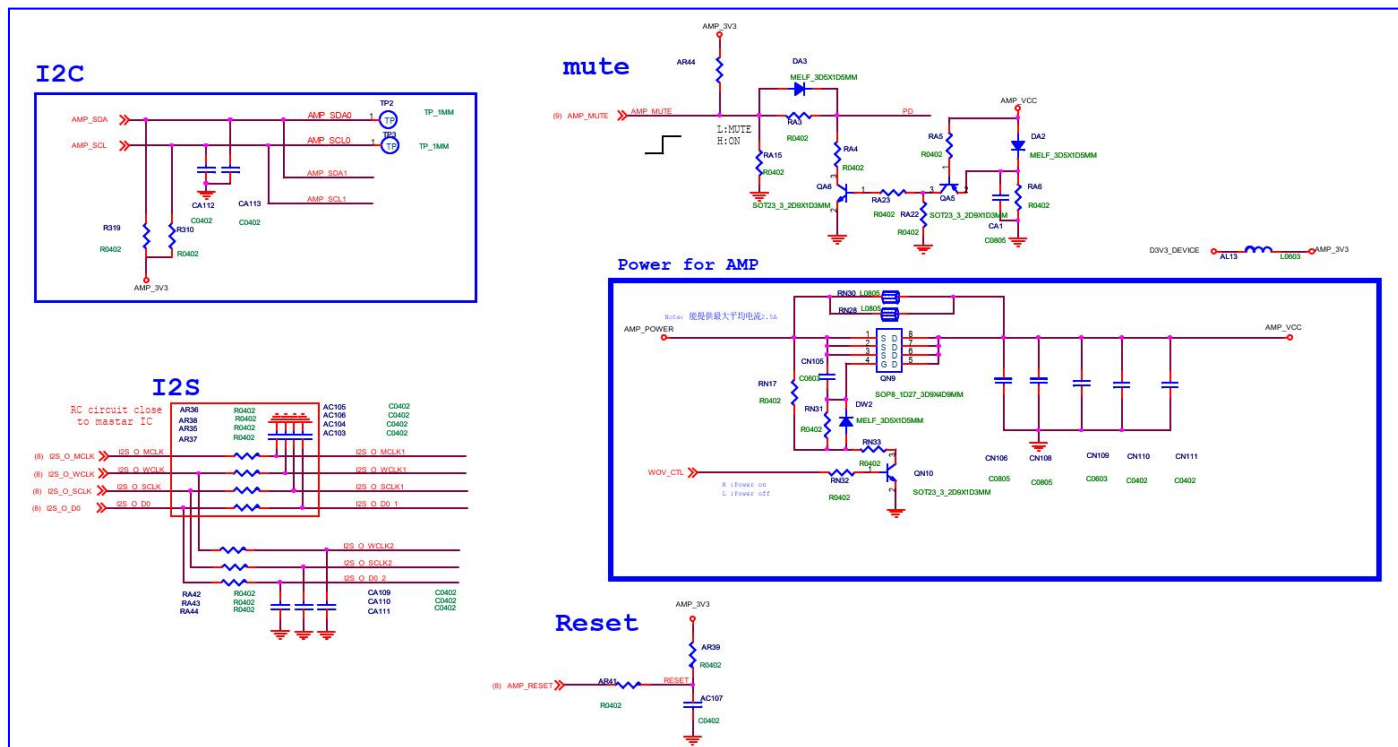


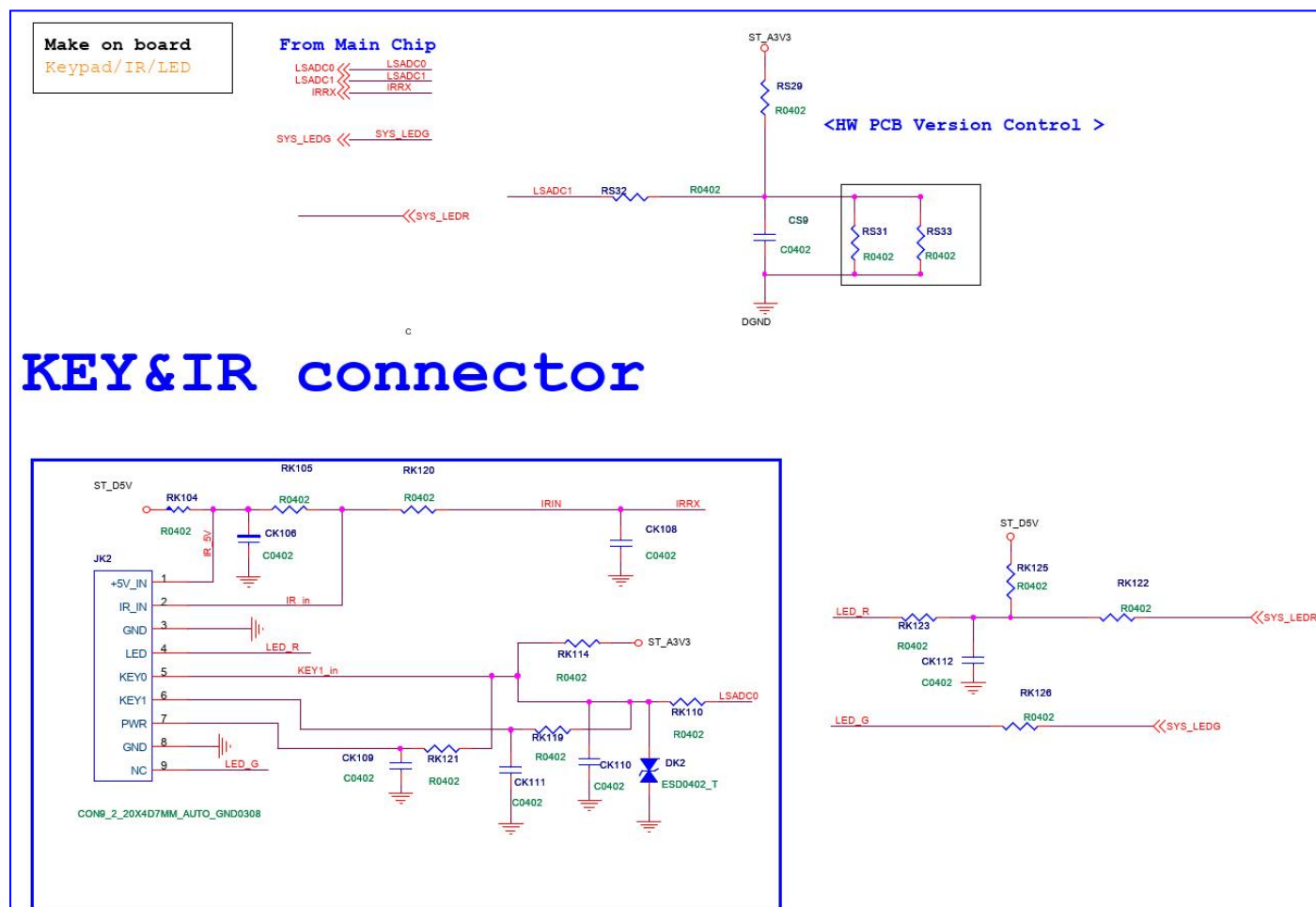


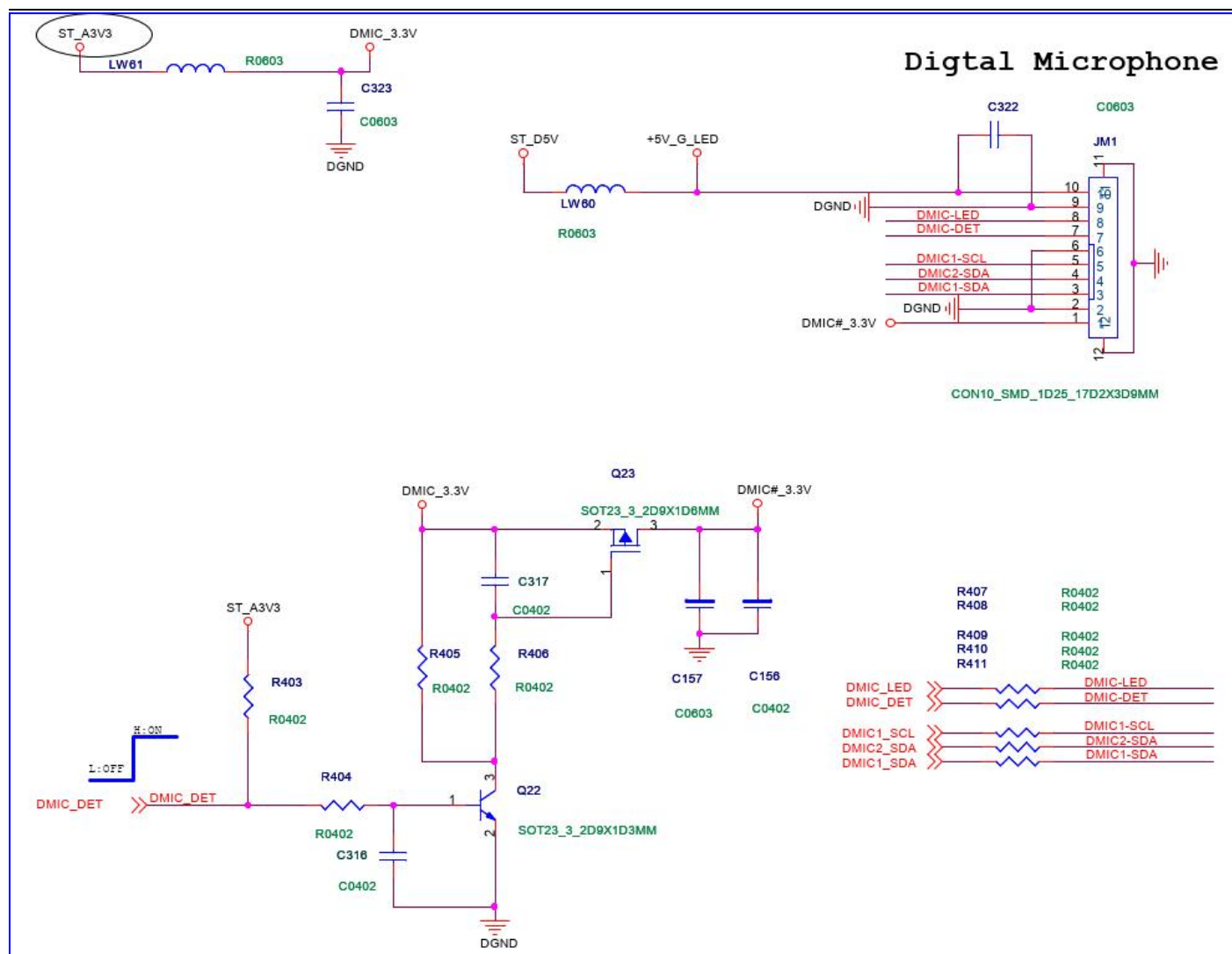




Google R+: 上件RA374, I2C Address为0x30



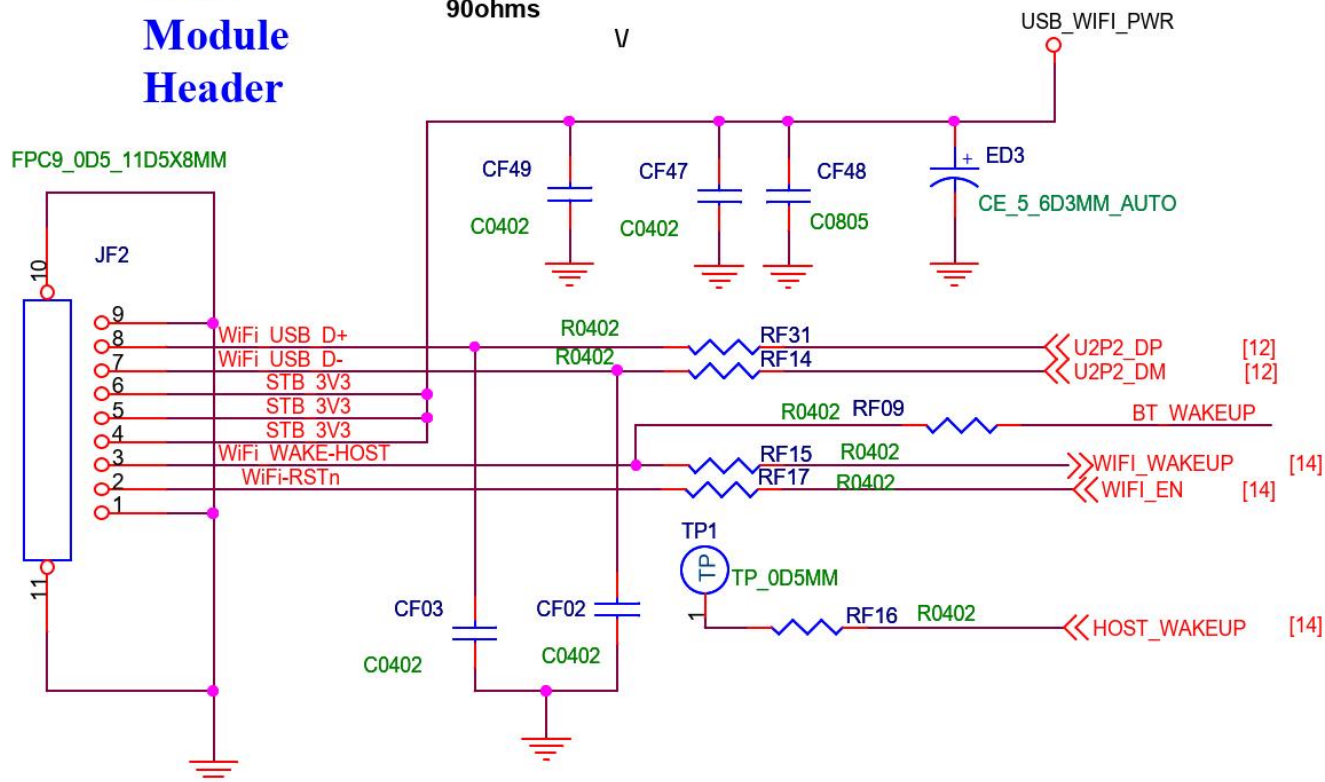




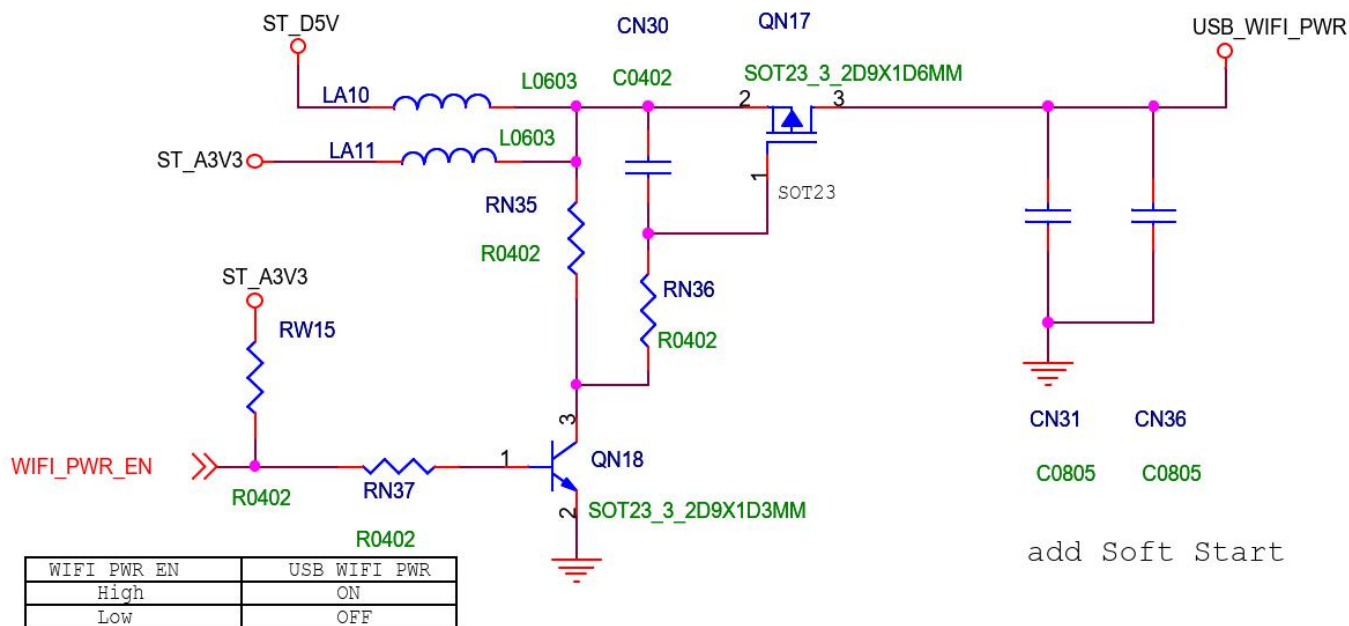
USB Trace : Diffenentail Impendence 90 R

WiFi Module Header

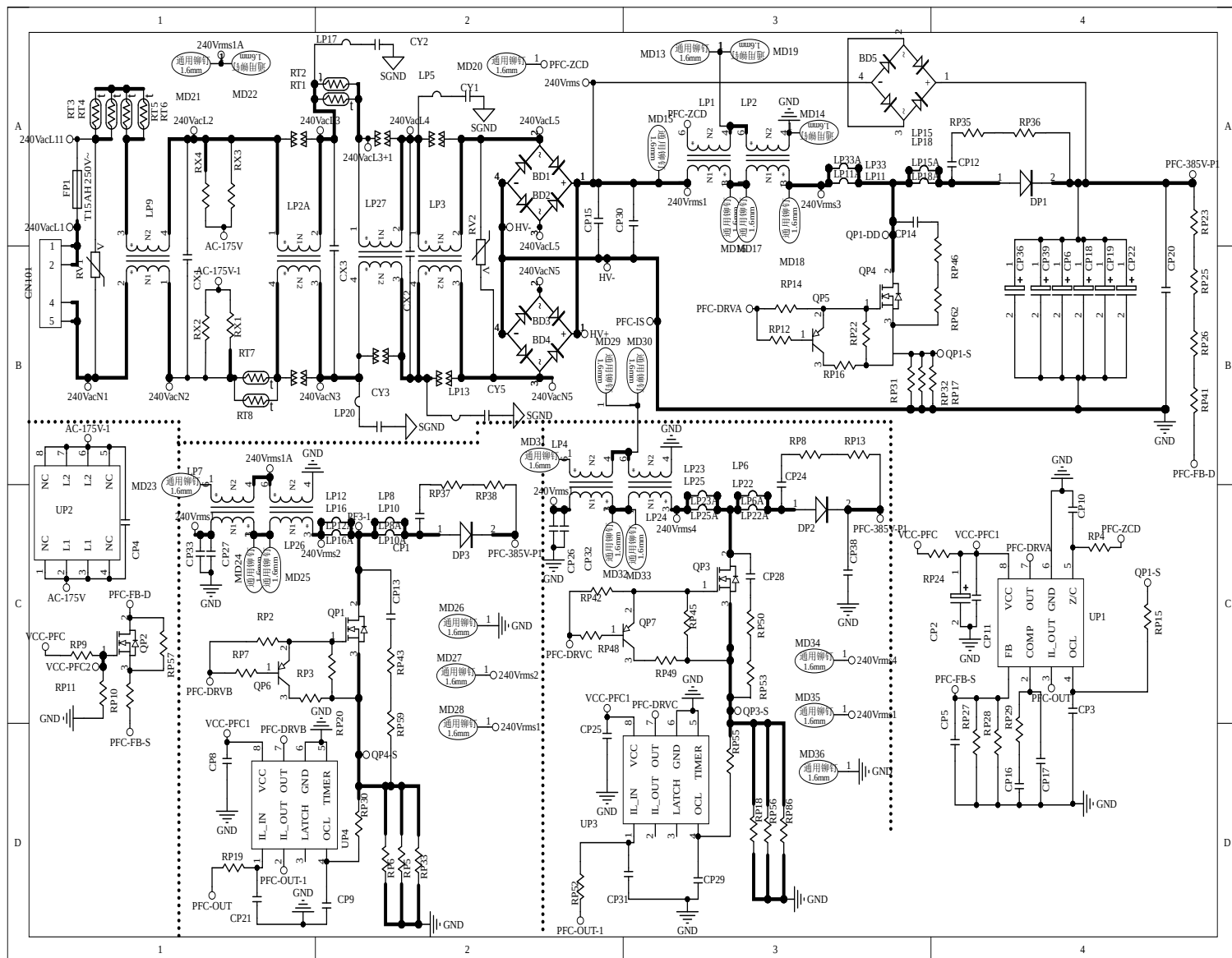
Route as differential pairs @
90ohms

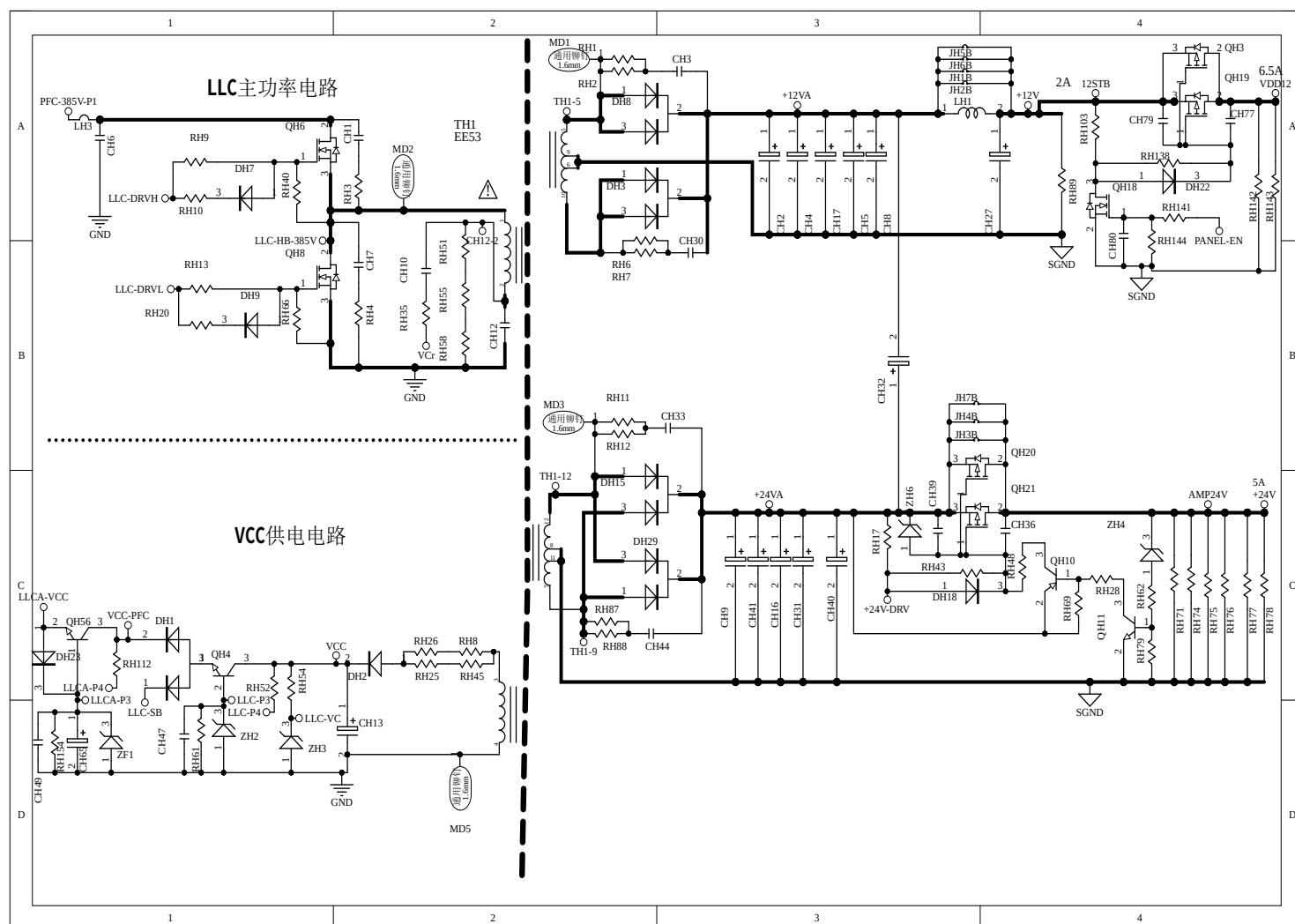


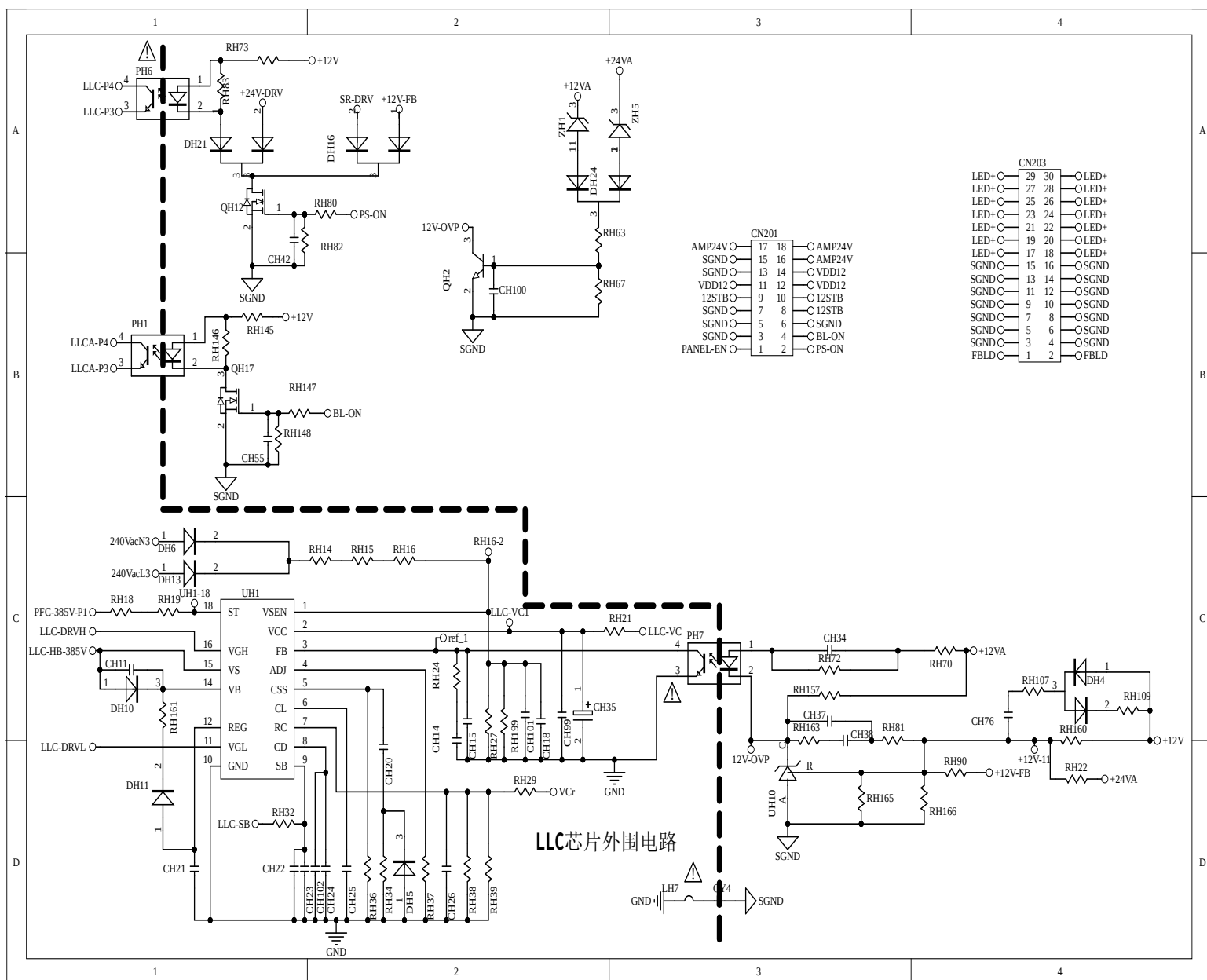
Note: 能提供最大平均电流1A

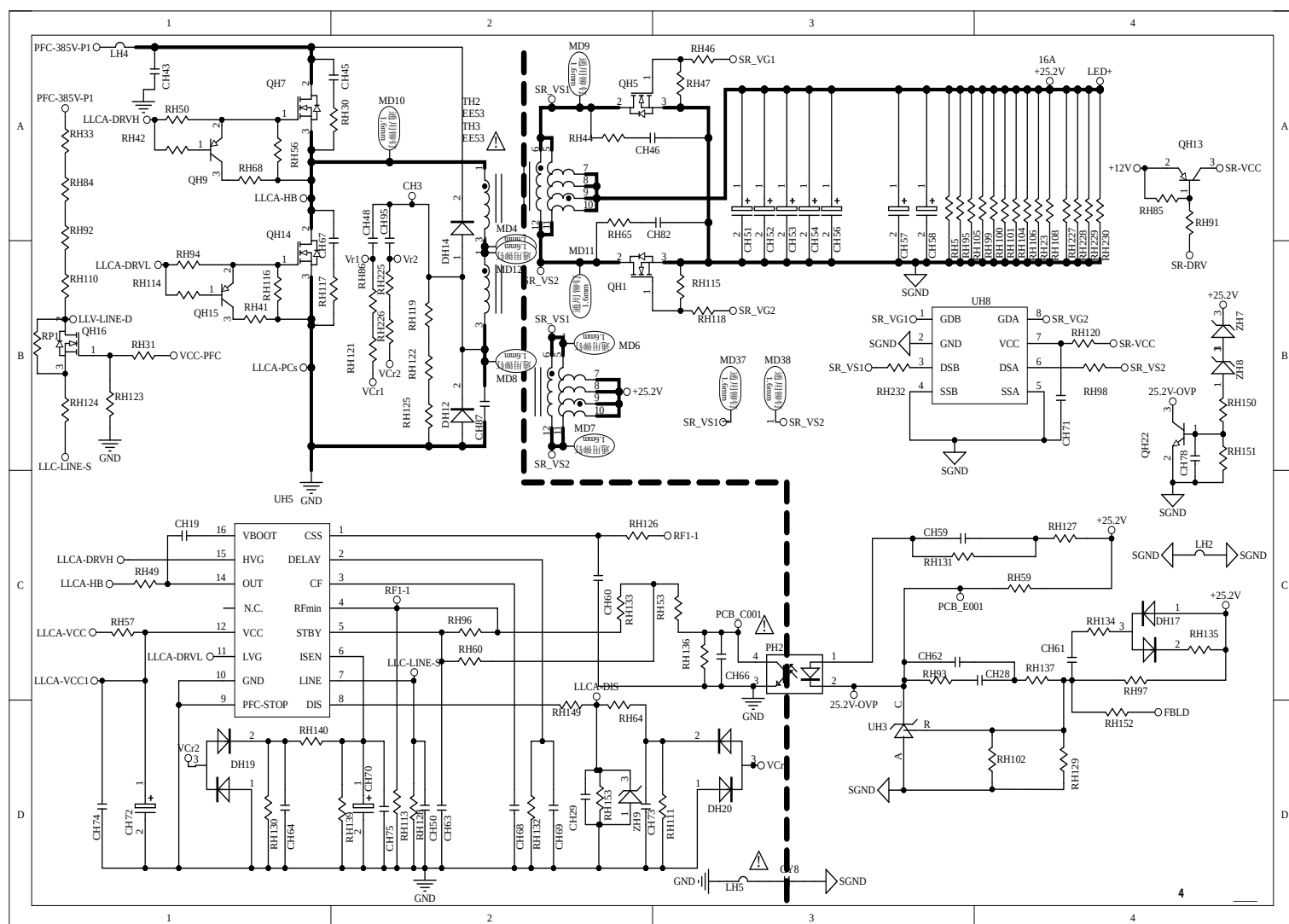


11.2 Power board circuit diagram









12.1 Main Board PCBA Layout

